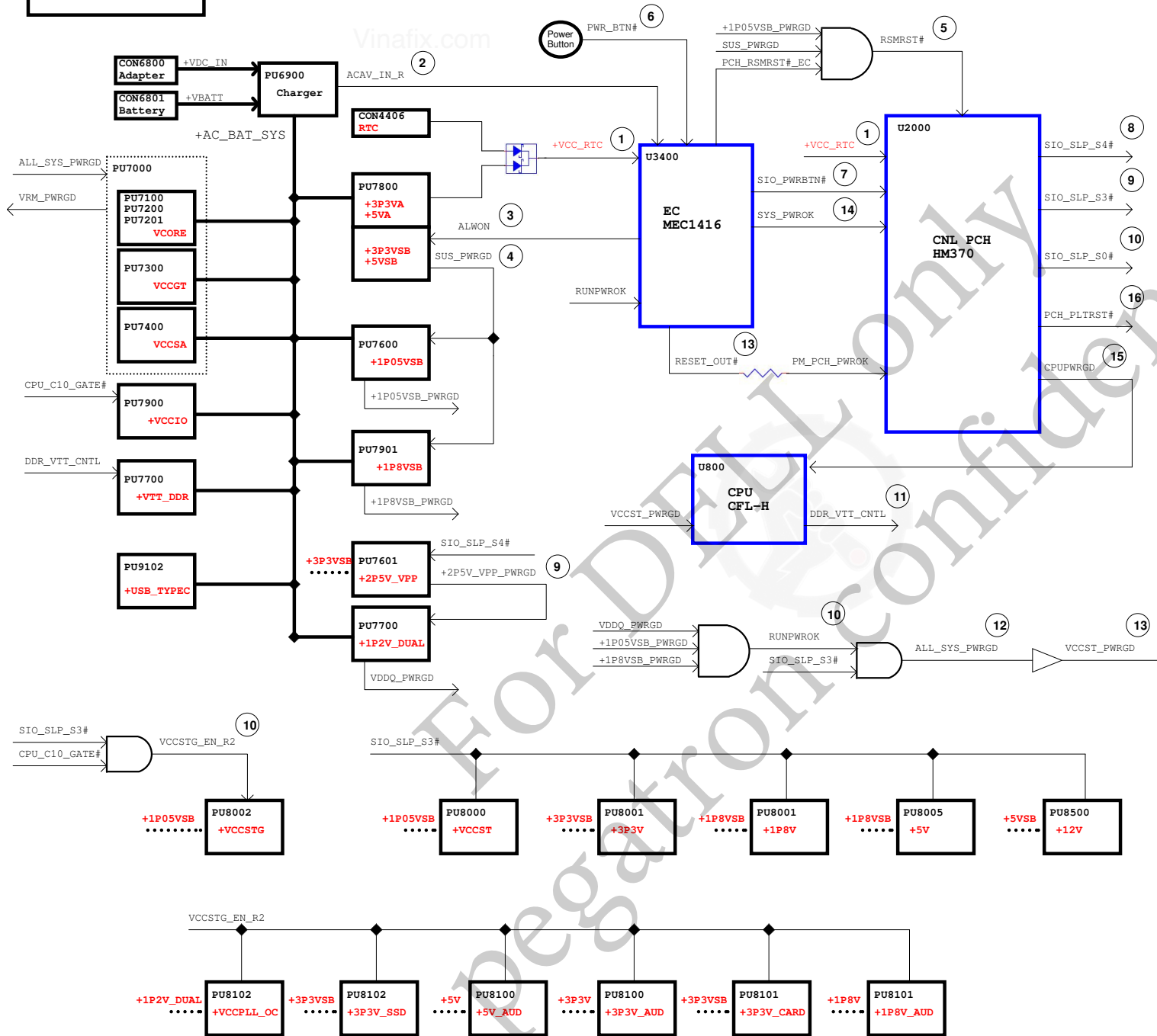


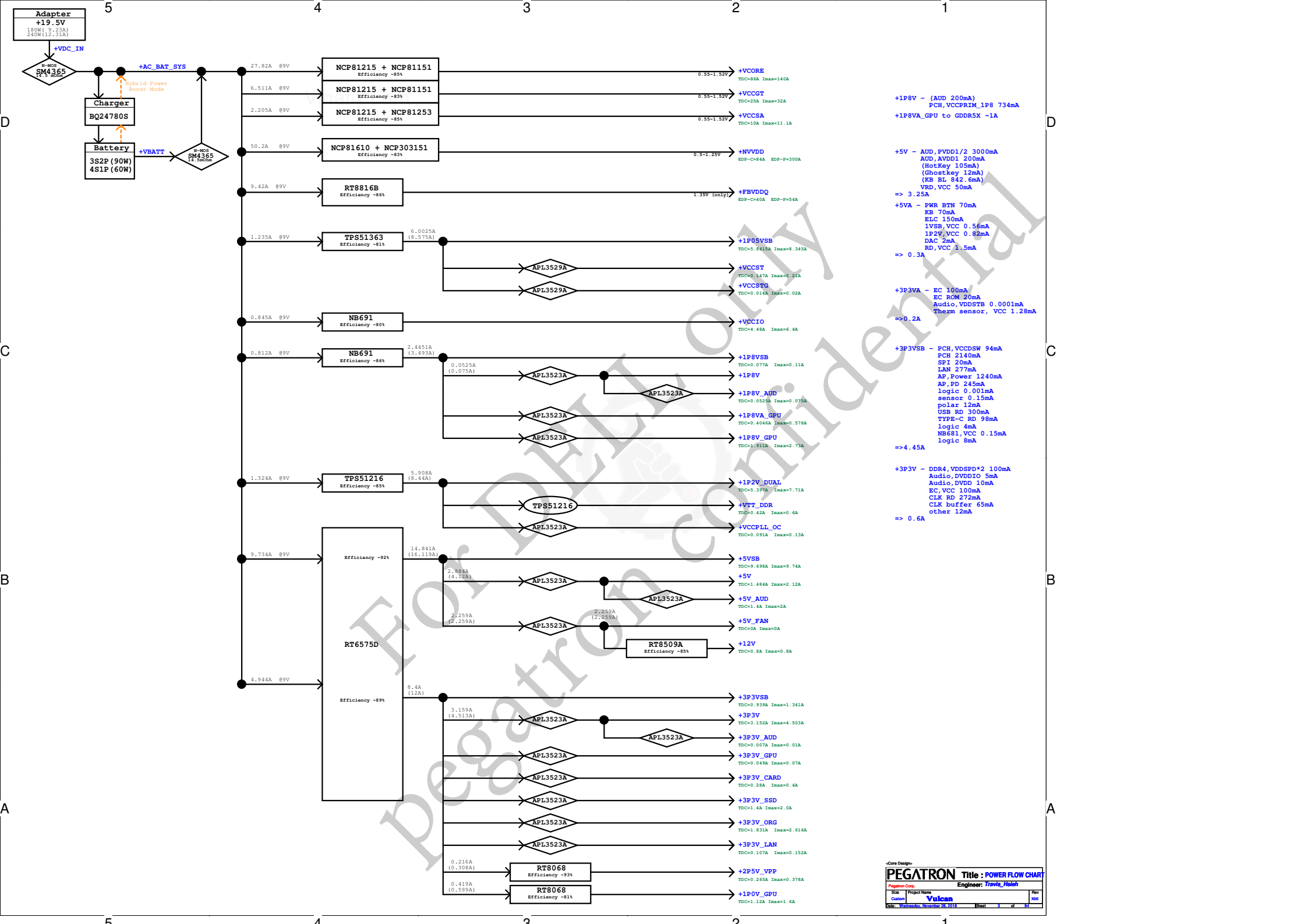


# Power On Sequence

① → ⑩

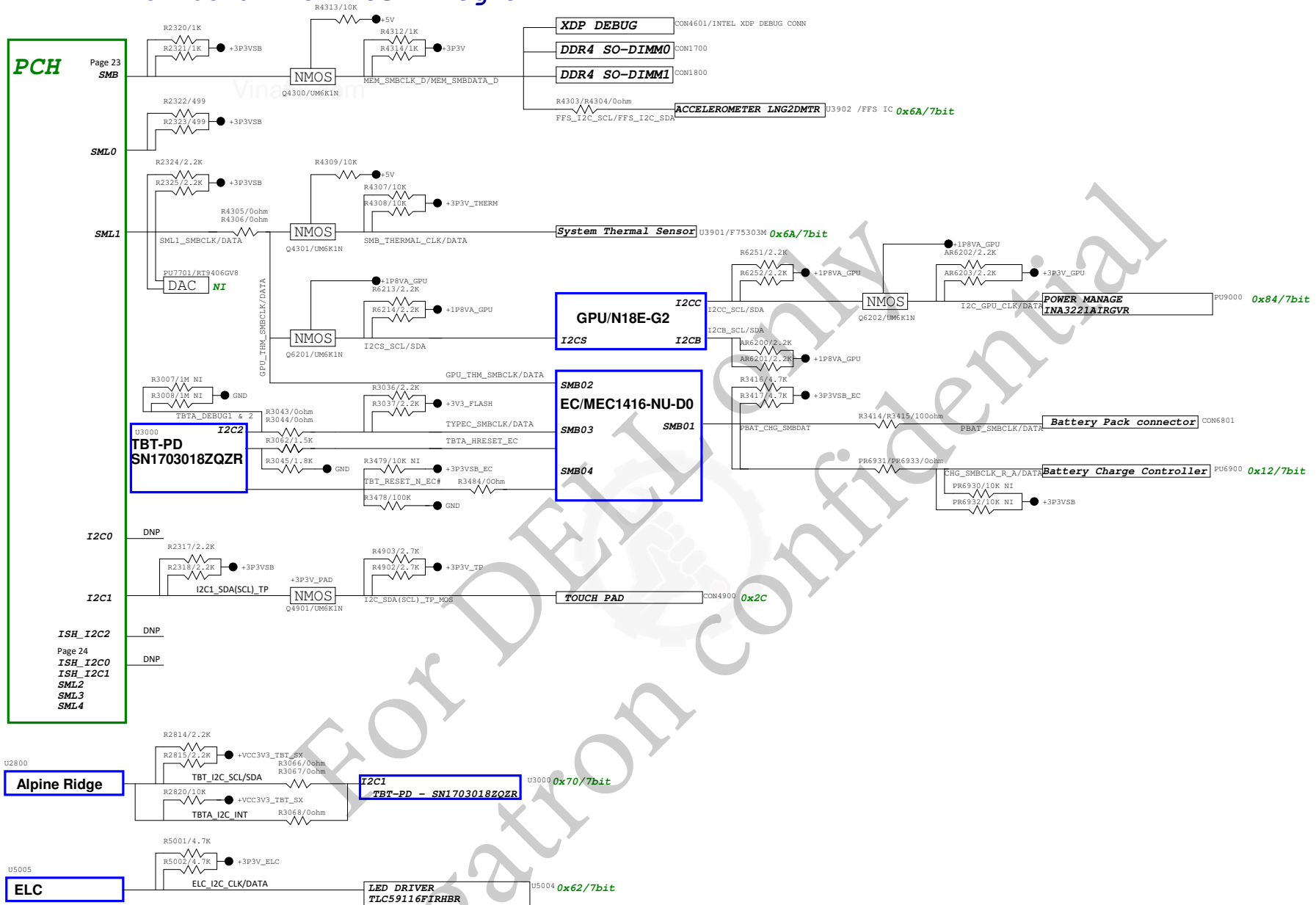
Vinafix.com

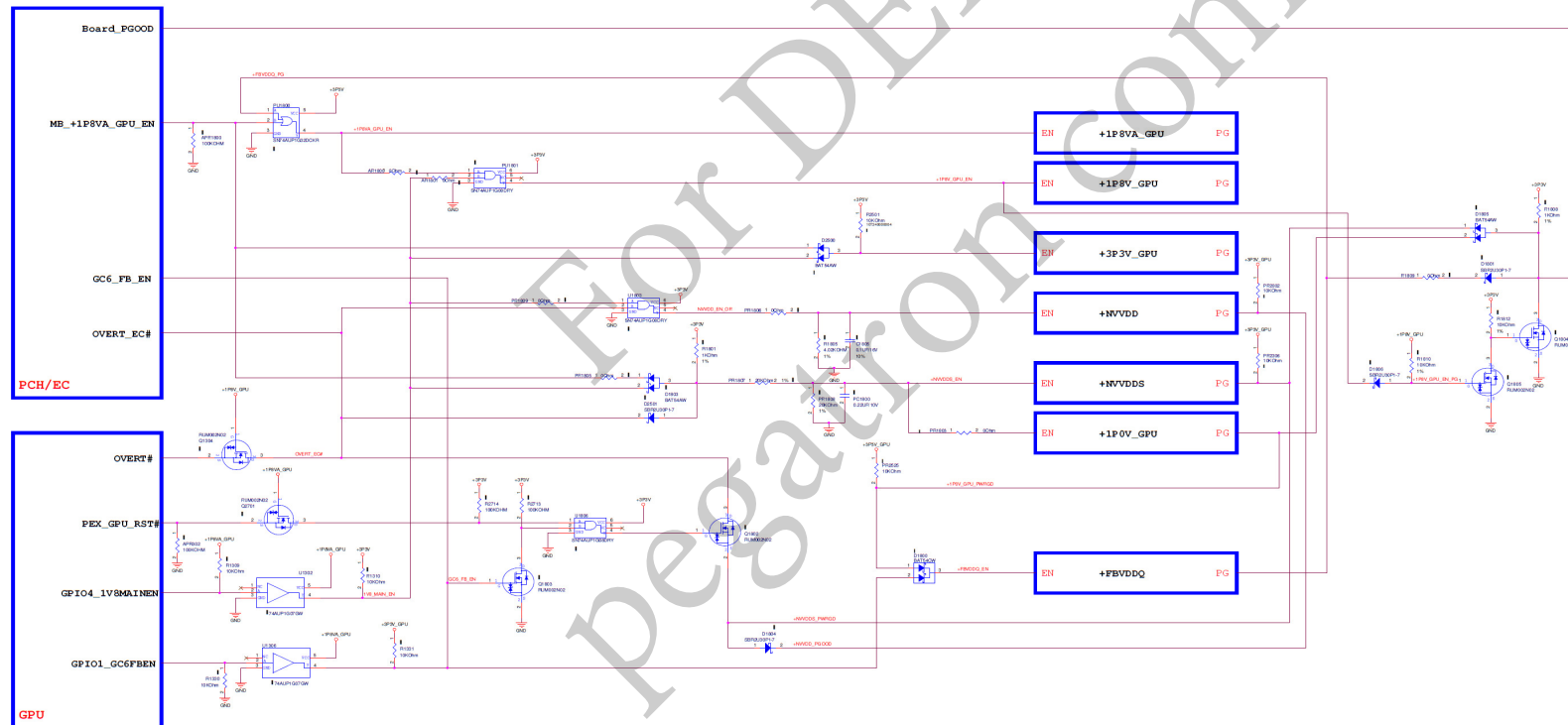
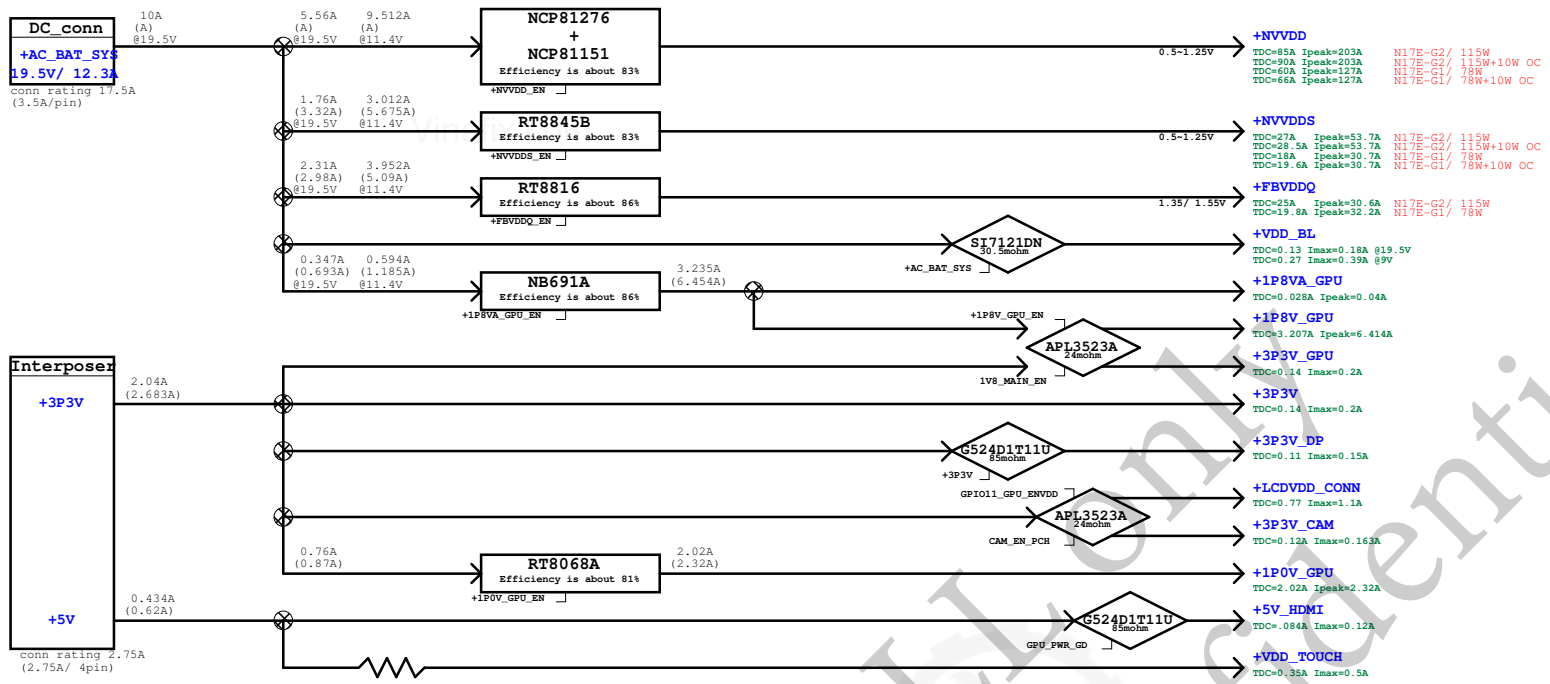




[illegible]

# SMBUS & I2C Block Diagram



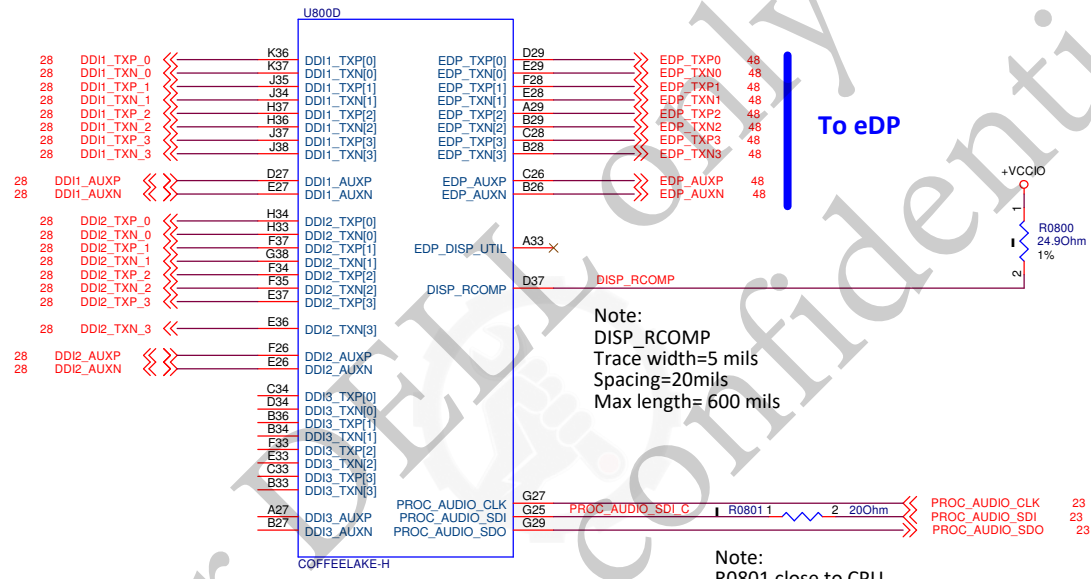


Reserved Page

PEGATRON DT-MB RESTRICTED SECRET

<b>PEGATRON</b>		Title : <b>POWER SEQUENCE</b>	
Pegatron Corp.		Engineer: <b>Travis_Hsieh</b>	
Size <b>A4</b>	Project Name <b>Vulcan</b>		Rev <b>X00</b>
Date: <b>Wednesday, November 28, 2018</b>		Sheet <b>7</b> of <b>94</b>	

To Apline ridge

Note:  
R0801 close to CPU

PEGATRON DT-MB RESTRICTED SECRET

**PEGATRON** Title : CPU DDI/EDP

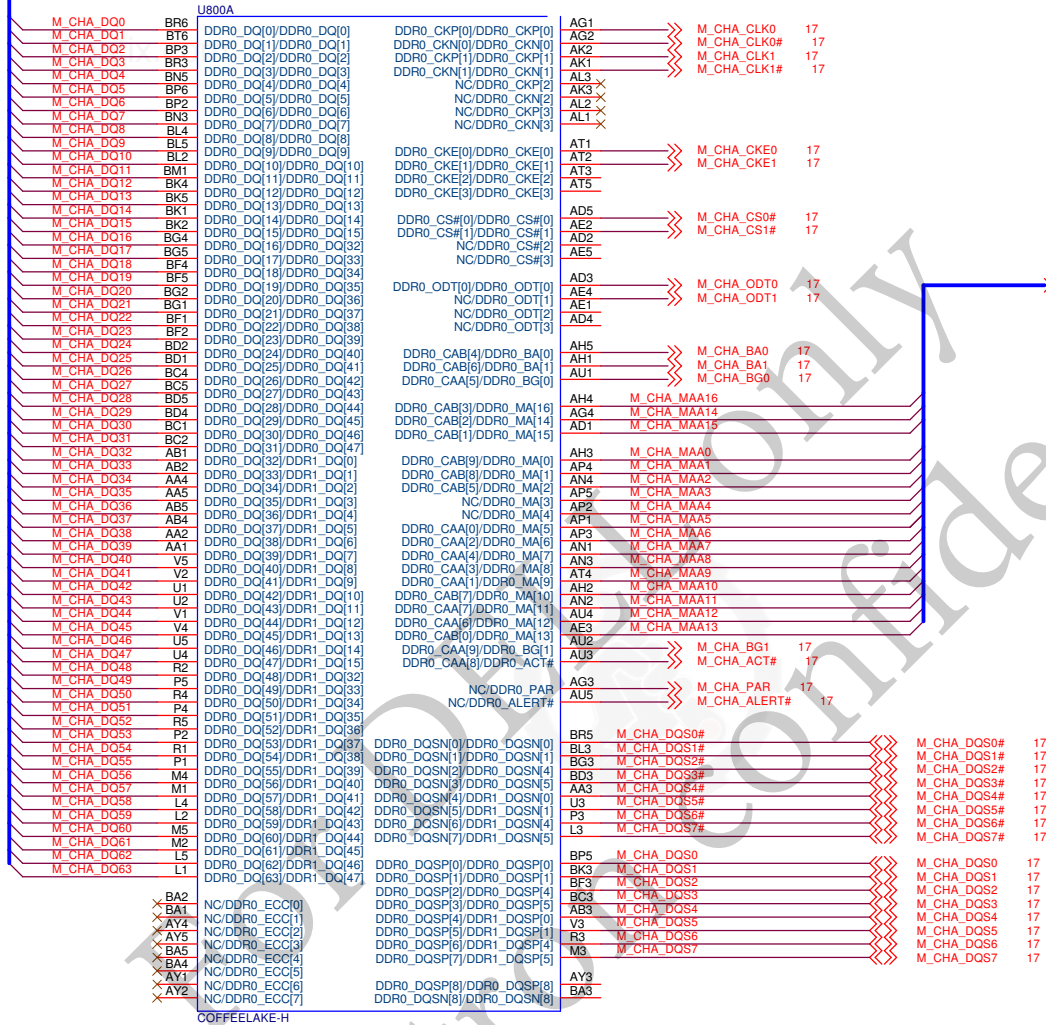
Pegatron Corp. Engineer: Travis\_Hsieh

Size A3 Project Name **Vulcan** Rev X00

Date: Wednesday, November 28, 2018 Sheet 8 of 94



17 M\_CHA\_DQ[0..63] <<>



PEGATRON DT-MB RESTRICTED SECRET

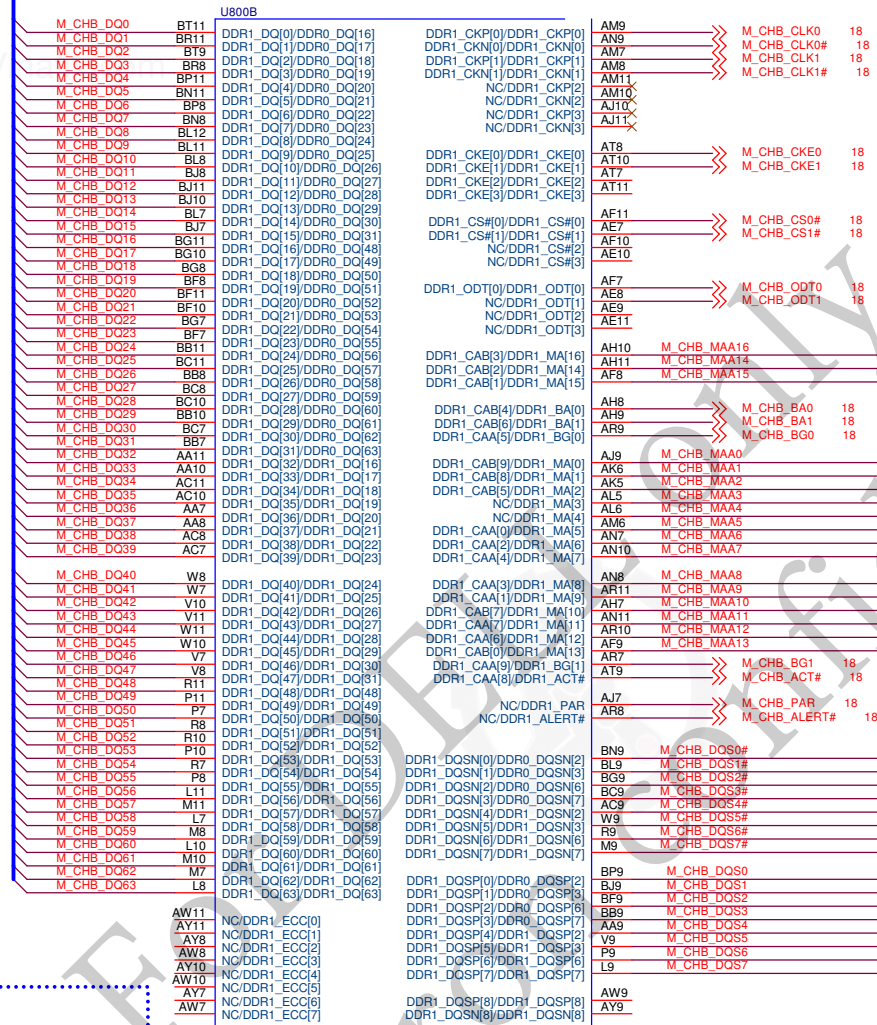
PEGATRON Title : CPU DDR4 CHA

Pegatron Corp. Engineer: Travis\_Hsieh

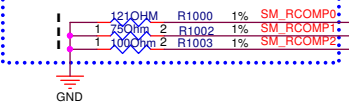
Size A3 Project Name Vulcan Rev X00

Date: Wednesday, November 28, 2018 Sheet 9 of 94

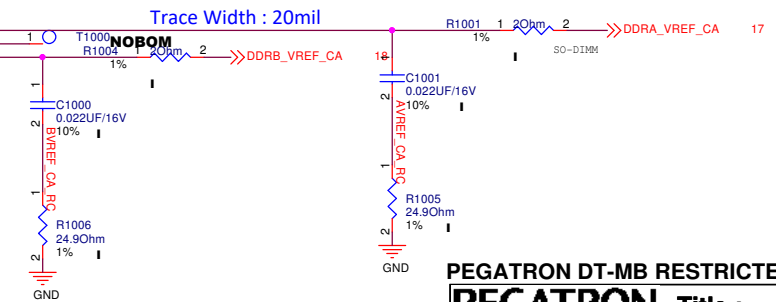
18 M\_CHB\_DQ[0..63] <<>

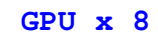


Note:  
Trace Width/Space : 15/25 mil  
Max Trace Length : 500 mil



Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)			Max Length (mils)			R (Ω±%) C(μF)	Notes	
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group [1]/[2]	Byte [1]/[2]	Region	Breakout [1,2]			Total
RCOMP [0]	M	MS	VSS	2	12-15					20	25/25				500	121	
RCOMP [1]	M	MS	VSS	2	12-15					20	25/25				500	75	
RCOMP [2]	M	MS	VSS	2	12-15					20	25/25				500	100	





20	DMI_RXP0	D8	DMI_RXP[0]	DMI_TXP[0]	B8	DMI_TXP0	20
20	DMI_RXN0	E8	DMI_RXN[0]	DMI_TXN[0]	A8	DMI_TXN0	20
20	DMI_RXP1	E6	DMI_RXP[1]	DMI_TXP[1]	C6	DMI_TXP1	20
20	DMI_RXN1	F6	DMI_RXN[1]	DMI_TXN[1]	B6	DMI_TXN1	20
20	DMI_RXP2	D5	DMI_RXP[2]	DMI_TXP[2]	B5	DMI_TXP2	20
20	DMI_RXN2	E5	DMI_RXN[2]	DMI_TXN[2]	A5	DMI_TXN2	20
20	DMI_RXP3	J8	DMI_RXP[3]	DMI_TXP[3]	D4	DMI_TXP3	20
20	DMI_RXN3	J9	DMI_RXN[3]	DMI_TXN[3]	B4	DMI_TXN3	20

COFFEE LAKE-H

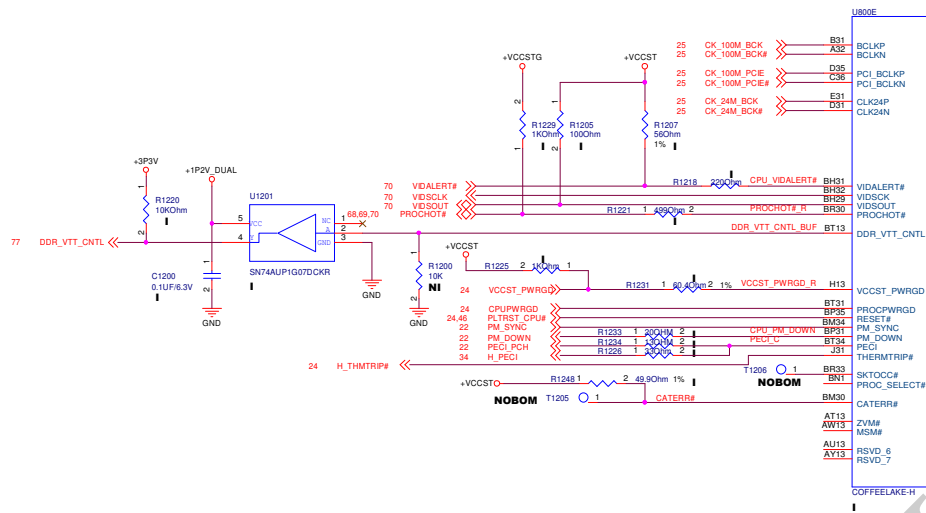


Table 6-7. Reset and Miscellaneous Signals

Table 6-10. Processor Clocking Signals

Signal Name	Description	Dir.	Buffer Type	Link Type	Availability
BCLKP BCLKN	100 MHz Differential bus clock input to the processor	I		Diff	
CLK24P CLK24N	24 MHz Differential bus clock input to the processor	I		Diff	H and S-Processor Line
PCI_BCLKP PCI_BCLKN	100 MHz Clock for PCI Express* logic	I		Diff	

Table 51-39. Processor/PCH Strapping Checklist (Sheet 2 of 2)

Pin Name	Strap Description	Configuration (Default Value for Each Bit is 1 Unless Specified)	Default Value	
CFG[19:8]	Reserved configuration lands.			

Signal Name	Description
CFG[0]	<b>Configuration Signals:</b> The CFG signals have a default value of '1' if not terminated on the board. Refer to the appropriate platform design guide for pull-down recommendations when a logic low is desired.
CFG[1]	Intel recommends placing test points on the board for CFG pins.
CFG[2]	CFG[2]: Stall reset sequence after PCU PLL lock until de-asserted:
CFG[3]	CFG[3]: Reserved configuration lane.
CFG[4]	CFG[4]: eDP enable:
CFG[5]	CFG[5]: PCI Express* Bifurcation
CFG[6]	CFG[6]: PEG Training:
CFG[7]	CFG[7]: Reserved configuration lanes.
CFG[19:0]	CFG[19:0]: Reserved configuration lanes.







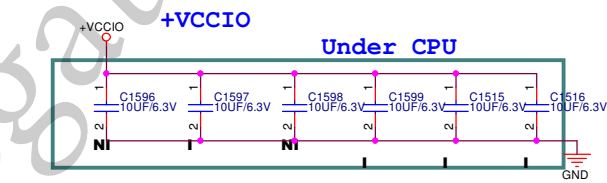
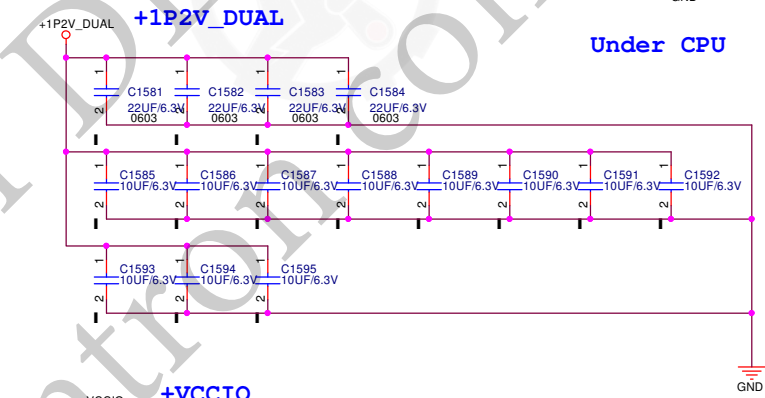
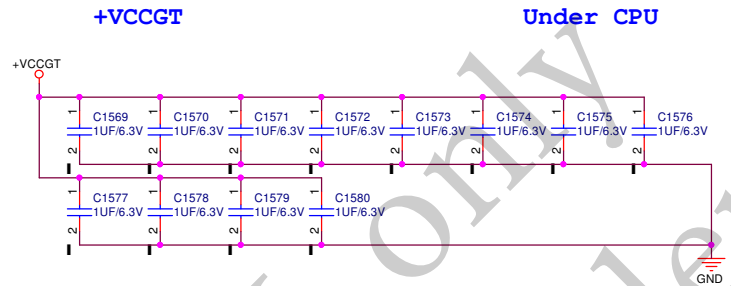
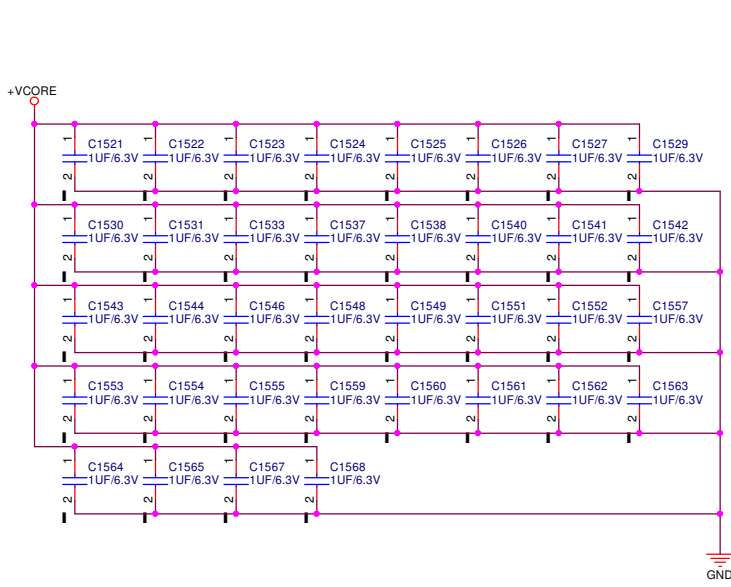
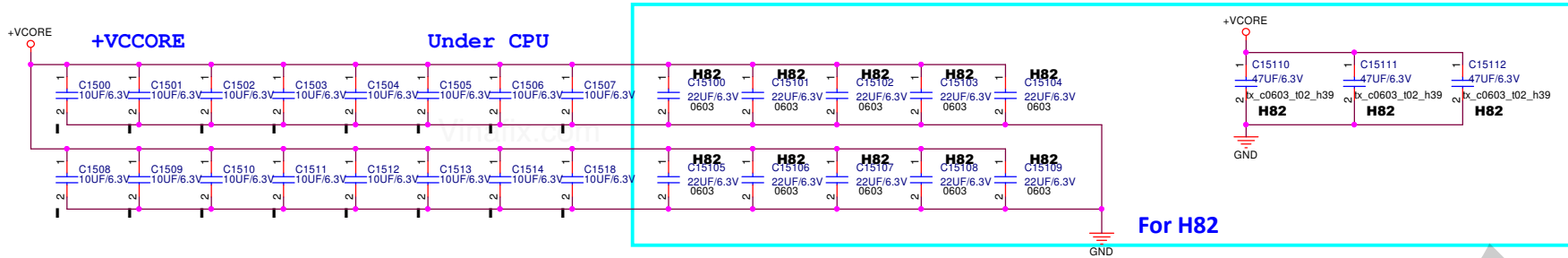


Table 50-3. Decoupling Requirements for CFL H Processor

Domain	Board Edge cap	Backside cap	Notes
Vcc	5x 47uF 0805	12x 22uF 0603	
		21x 10uF 0402	
		24x 1uF 0201	
		24x 0201 (placeholder)	
VCCGT	3x 47uF 0805 7x 22uF 0603		Place as close to the BGA as possible
		10x 10uF 0402	
		12x 1uF 0201	
VCCSA	2x 47uF 0805 2x 22uF 0603		
		7x 10uF 0402	
		1x 1uF 0201	
VDDQ		4x 22uF 0603	
		11x 10uF 0402	
VCCIO		3x 10uF 0402	
		3x 0402 (placeholder)	

Additional capacitors might be needed if the connectivity from BGAs to capacitors is not adequate.

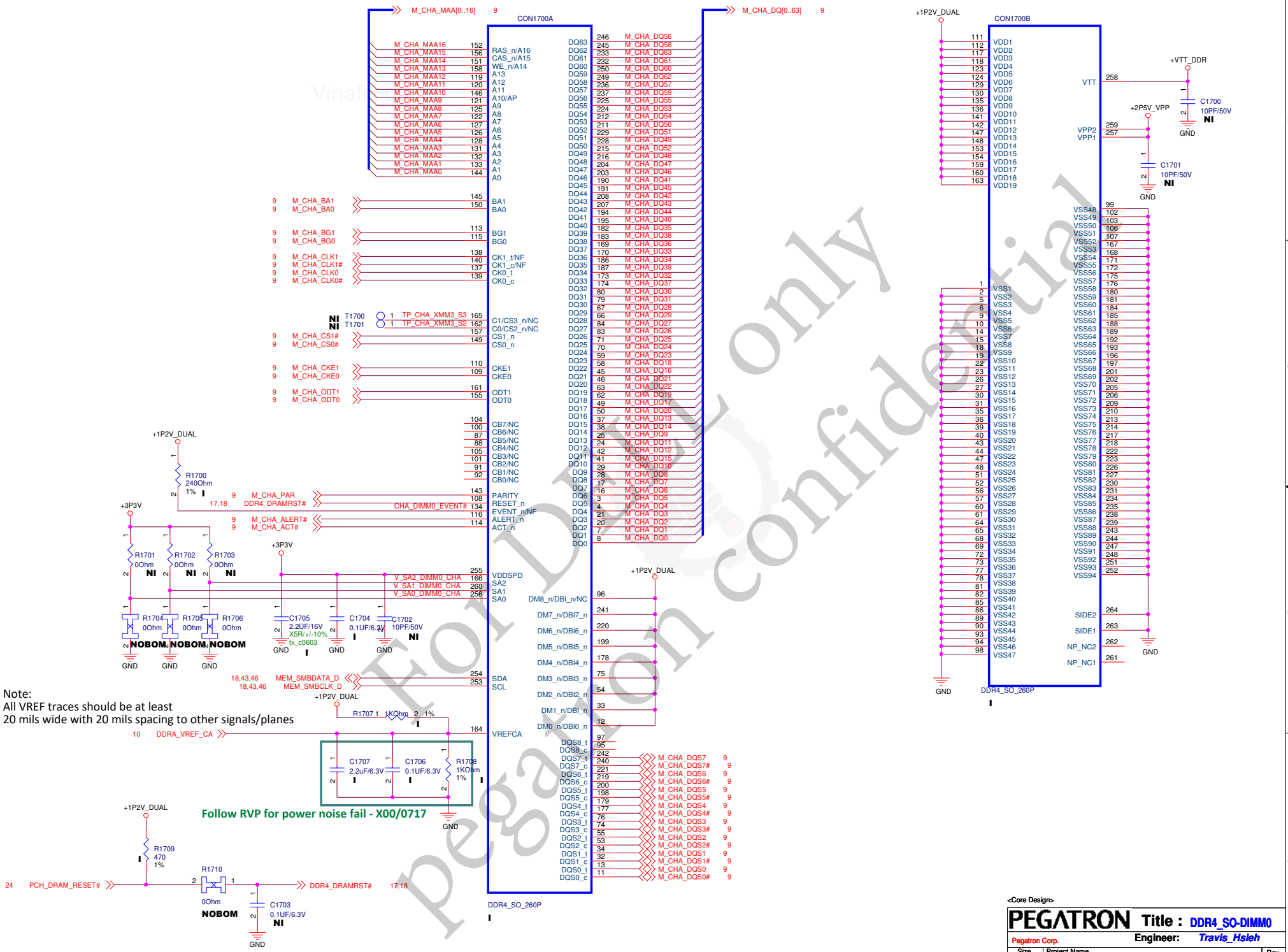
Change for power noise fail - X00/0717

Reserved Page

PEGATRON DT-MB RESTRICTED SECRET

<b>PEGATRON</b>		Title : <b>Reserved</b>	
<b>Pegatron Corp.</b>		Engineer: <b>Travis_Hsieh</b>	
Size <b>A4</b>	Project Name <b>Vulcan</b>		Rev <b>X00</b>
Date: <b>Wednesday, November 28, 2018</b>		Sheet	<b>16</b> of <b>94</b>





Note:  
All VREF traces should be at least  
20 mils wide with 20 mils spacing to other signals/planes

Follow RVP for power noise fail - X00/0717

<Core Design>

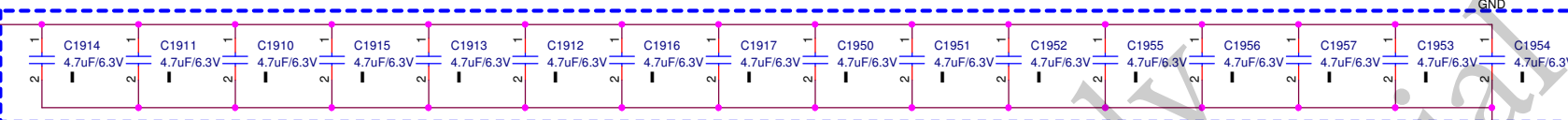
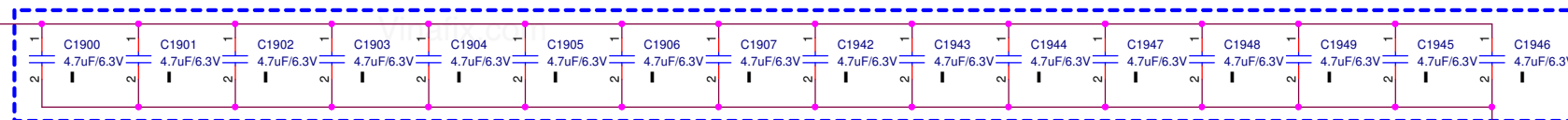
**PEGATRON** Title : **DDR4\_SO-DIMM1**  
Pegatron Corp. Engineer: **Travis\_Hsieh**

Size	Project Name	Rev
Custom	<b>Vulcan</b>	X00
Date: Wednesday, November 28, 2018		Sheet 18 of 94

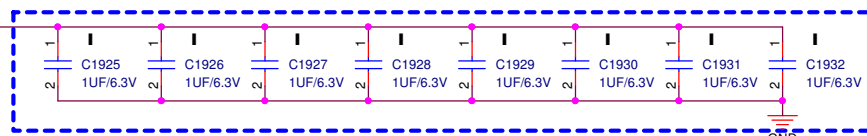
+1P2V\_DUAL

Change all 10u to 4.7u\*2 for placement - 2017-1/4

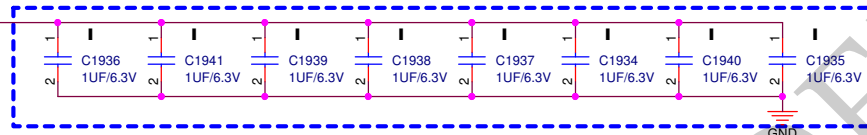
close  
CH A SO-DIMM



close  
CH B SO-DIMM



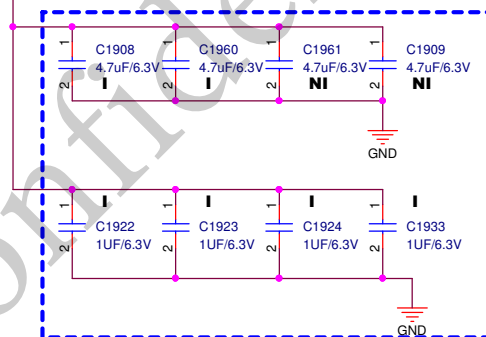
close  
CH A SO-DIMM



close  
CH B SO-DIMM

Change all 1uF from 0402 package to 0201 for placement - 2017-1/4

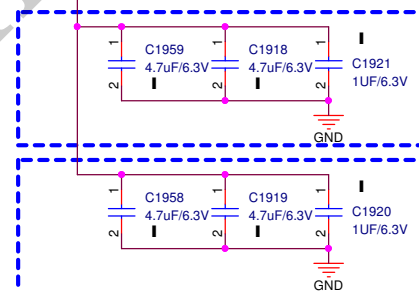
Near SO-DIMM



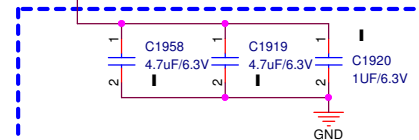
#### DDR4 SODIMM Power Plane Decoupling

Memory Configuration	Power Domain	Decoupling Location	Qty x $\mu$ F (size)	Note
DDR4 2 Channels SODIMM 1DPC	VDDQ	4 near each side of the DIMM connector close to VDD pins	16x 10 $\mu$ F (0603)	
		4 near each side of the DIMM connector close to VDD pins	16x 1 $\mu$ F (0402)	
		1 placeholder	1x 330 $\mu$ F (7343)	
	VTT	Place these caps on the VTT plane close to SODIMM	1x 10 $\mu$ F (0603)	
		Placeholder	1x 10 $\mu$ F (0603)	
		Place these caps on the VTT plane close to SODIMM	4x 1 $\mu$ F (0402)	
	VPP	DRAM Side	2x 10 $\mu$ F (0603)	
		DRAM Side	2x 1 $\mu$ F (0402)	
	VDDSPD	Place close to DIMM	1x 0.1 $\mu$ F (0402)	
		Place close to DIMM	1x 2.2 $\mu$ F (0402)	

+2P5V\_VPP



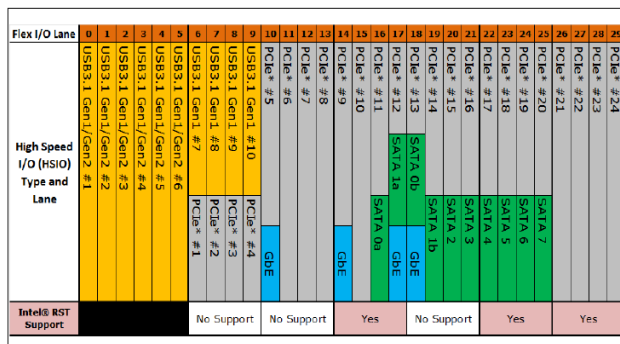
close CH A SO-DIMM



close CH B SO-DIMM

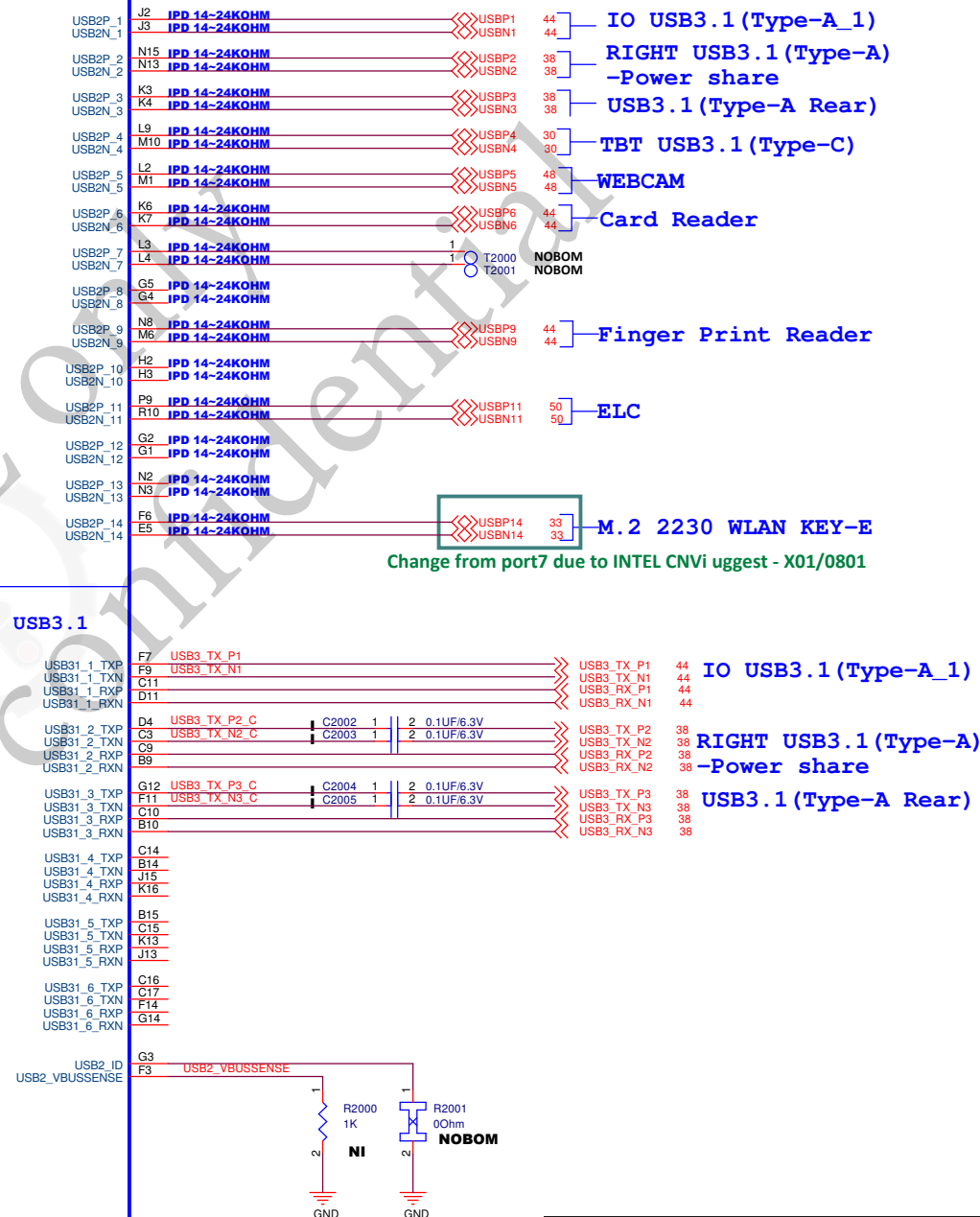
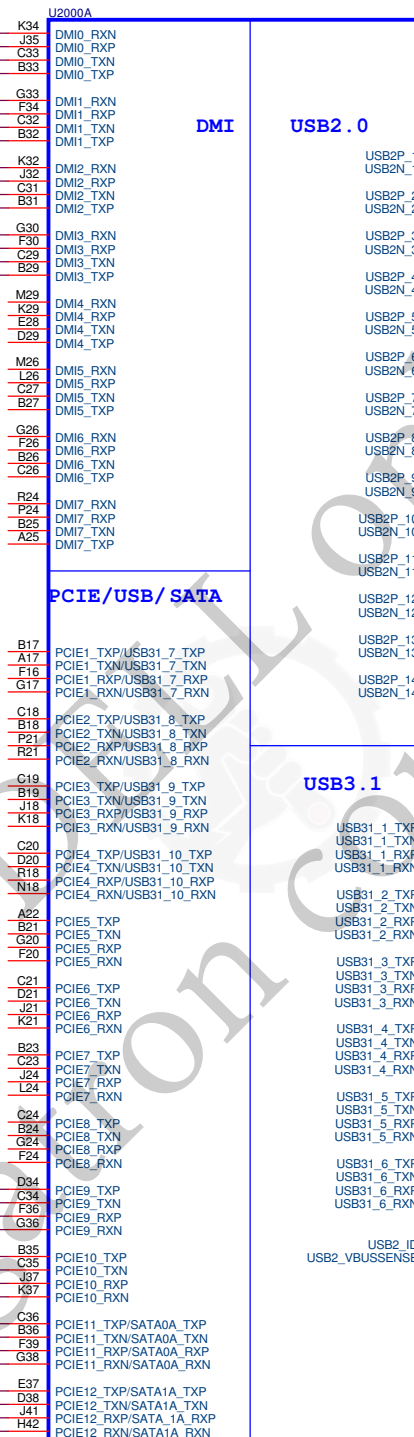
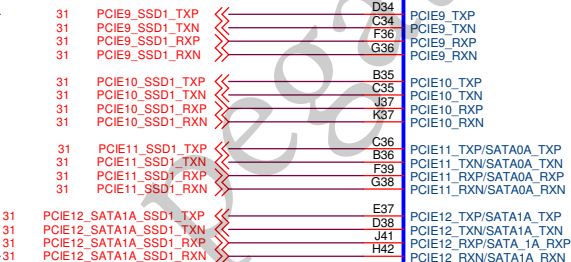
PEGATRON DT-MB RESTRICTED SECRET

<b>PEGATRON</b>		Title : DDR DECOUPLING	
Pegatron Corp.		Engineer: Travis_Hsieh	
Size	Project Name	Vulcan	Rev
Custom			X00
Date: Wednesday, November 28, 2018		Sheet	19 of 94



PCI-H Details		PCIe <sup>®</sup> Controller #1				PCIe <sup>®</sup> Controller #2				PCIe <sup>®</sup> Controller #3				PCIe <sup>®</sup> Controller #4				PCIe <sup>®</sup> Controller #5				PCIe <sup>®</sup> Controller #6								
Flex I/O Lane #		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29
		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29
	1x4																													
	1x8																													
	2x2																													
	1x2+1x2																													
	1x2+1x2																													
	1x2+1x2																													

M.2 PCIE X4 #1







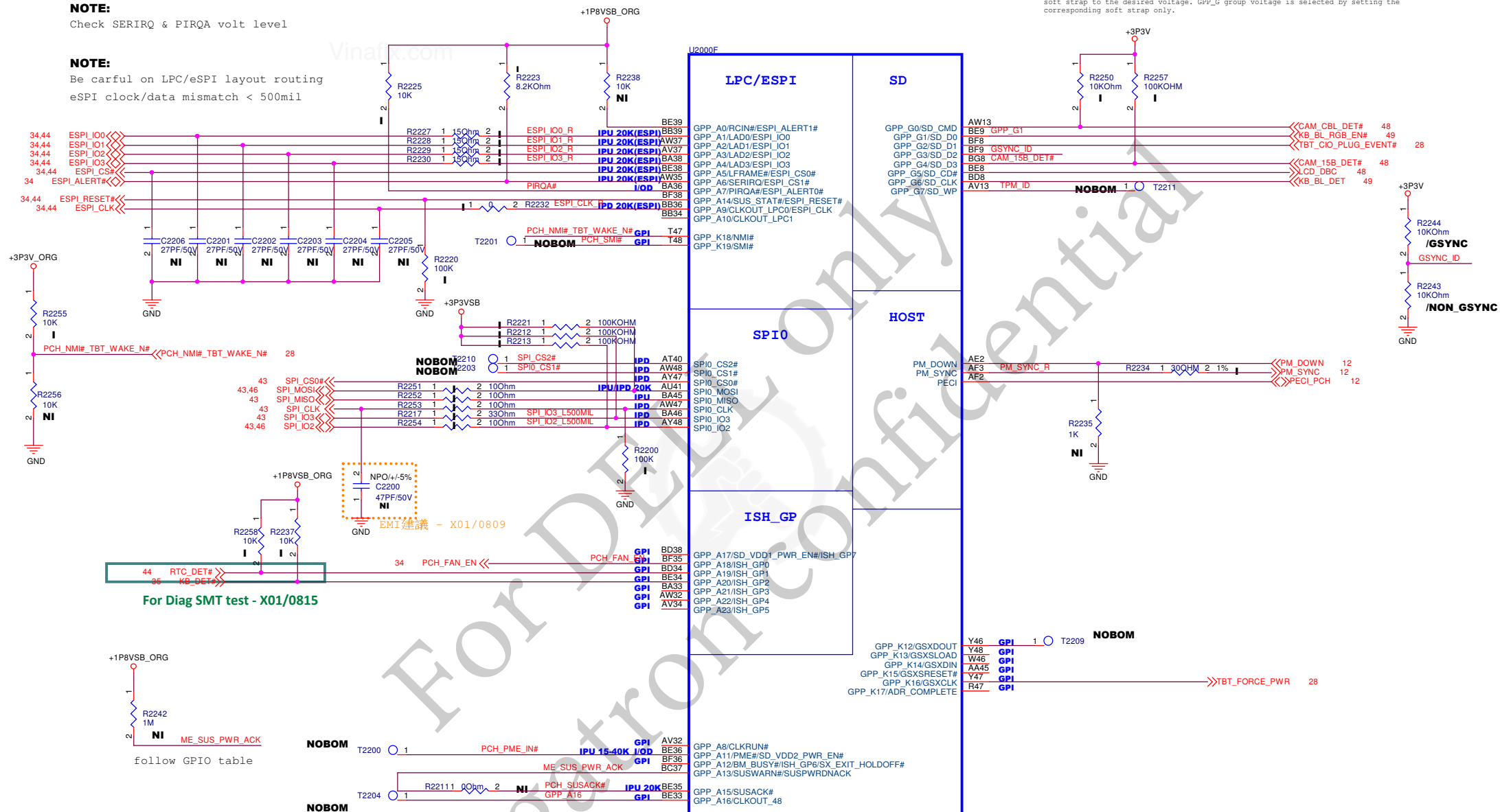
eSPI operates at 1.8V

Check SERIRQ & PIRQA volt level

Be careful on LPC/eSPI layout routing  
eSPI clock/data mismatch < 500mil

Check GPP\_A0 power well

GPP\_G group, the operating voltage of a GPIO group having voltage configurability (3.3V or 1.8V) is selected by both connecting the corresponding power pin and setting the group-voltage-selection soft strap to the desired voltage. GPP\_G group voltage is selected by setting the corresponding soft strap only.



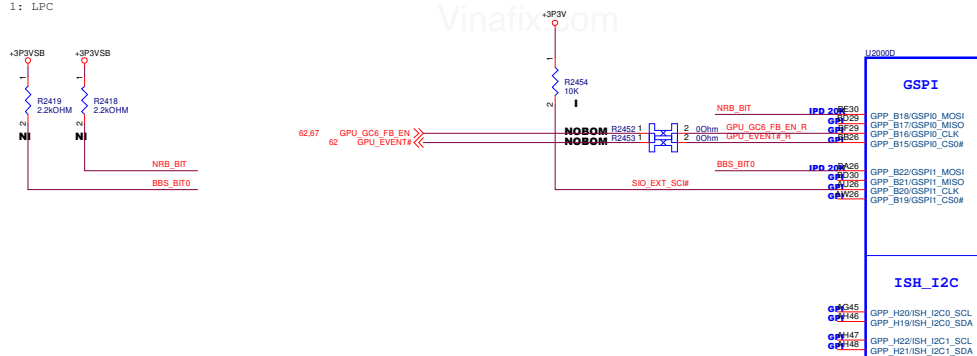
If Deep Sx is supported, the EC/motherboard controlling logic must change SUSACK# to match SUSWARN# once the EC/motherboard controlling logic has completed the preparations discussed in the description for the SUSWARN# pin.

**PEGATRON** Title : PCH ESPI/SPI/FAN/HOST

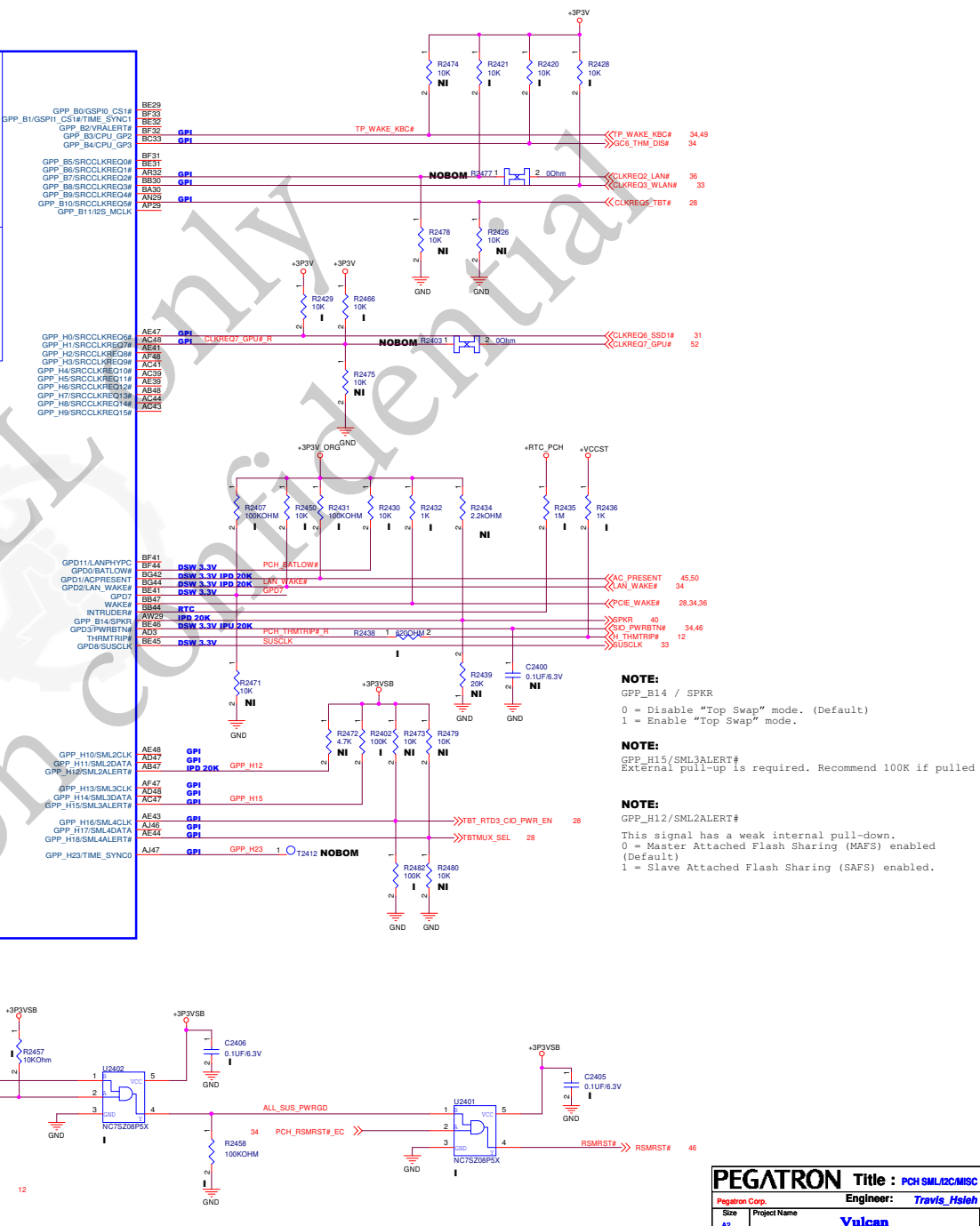
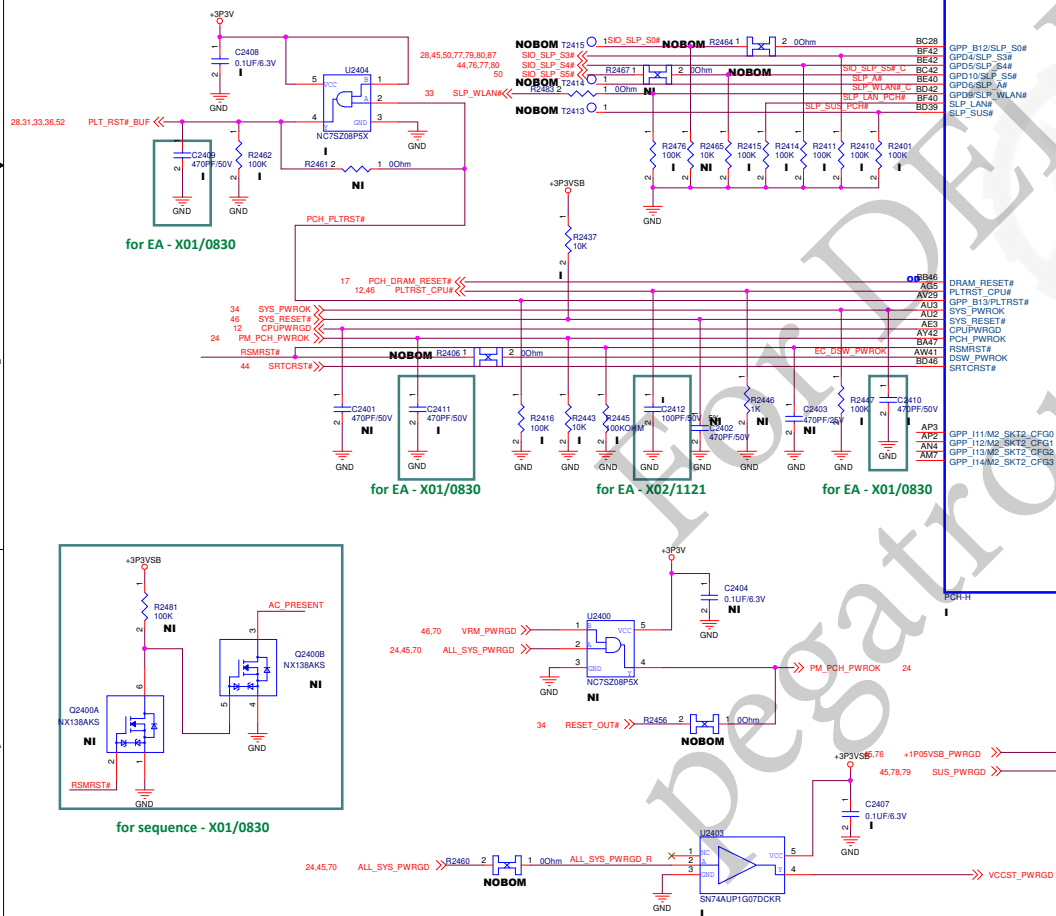
Pegatron Corp.		Engineer: <u>Travis_Hsieh</u>	
Size Custom	Project Name <b>Vulcan</b>	Rev X00	
Date: <u>Wednesday, November 28, 2018</u>		Sheet <u>22</u> of <u>94</u>	



This Signal has a weak internal pull-down.  
Offset 3410h:Bit 10  
0: SPI  
1: LPC



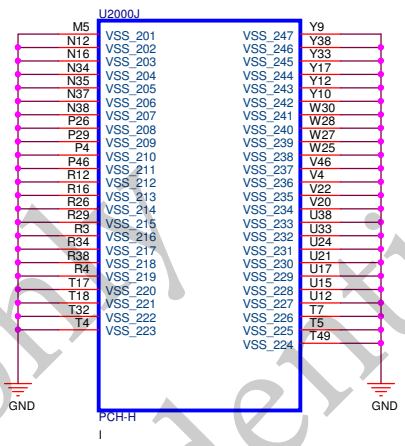
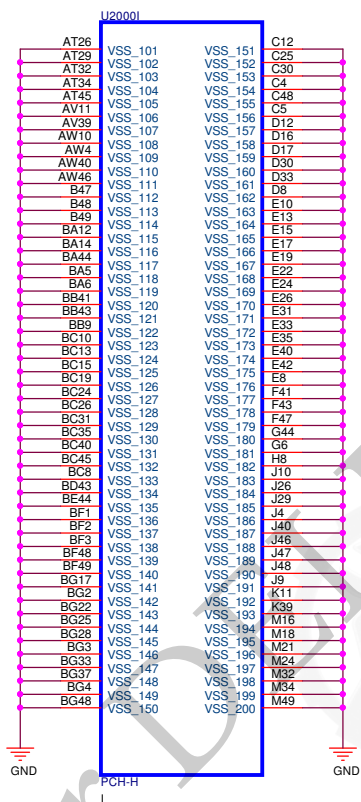
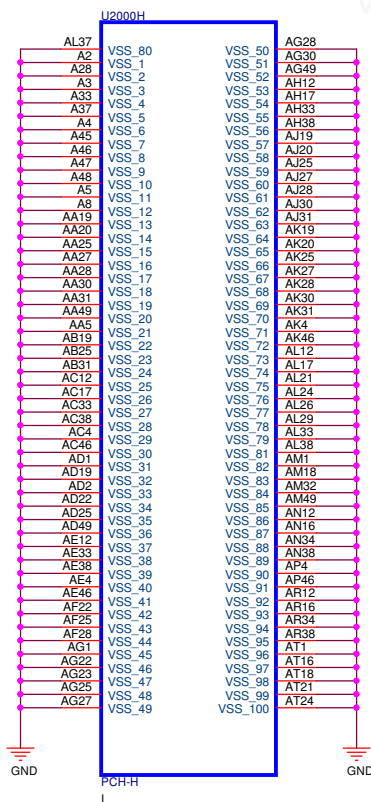
The signal has a weak internal pull-down.  
0 = Disable "No Reboot" mode.  
1 = Enable "No Reboot" mode  
(PCH will disable the TCO Timer system reboot feature).

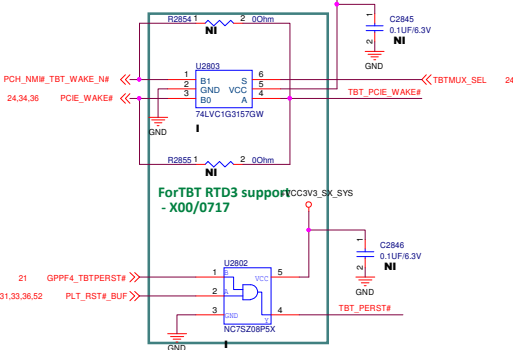








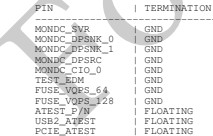




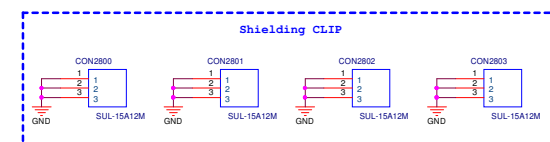
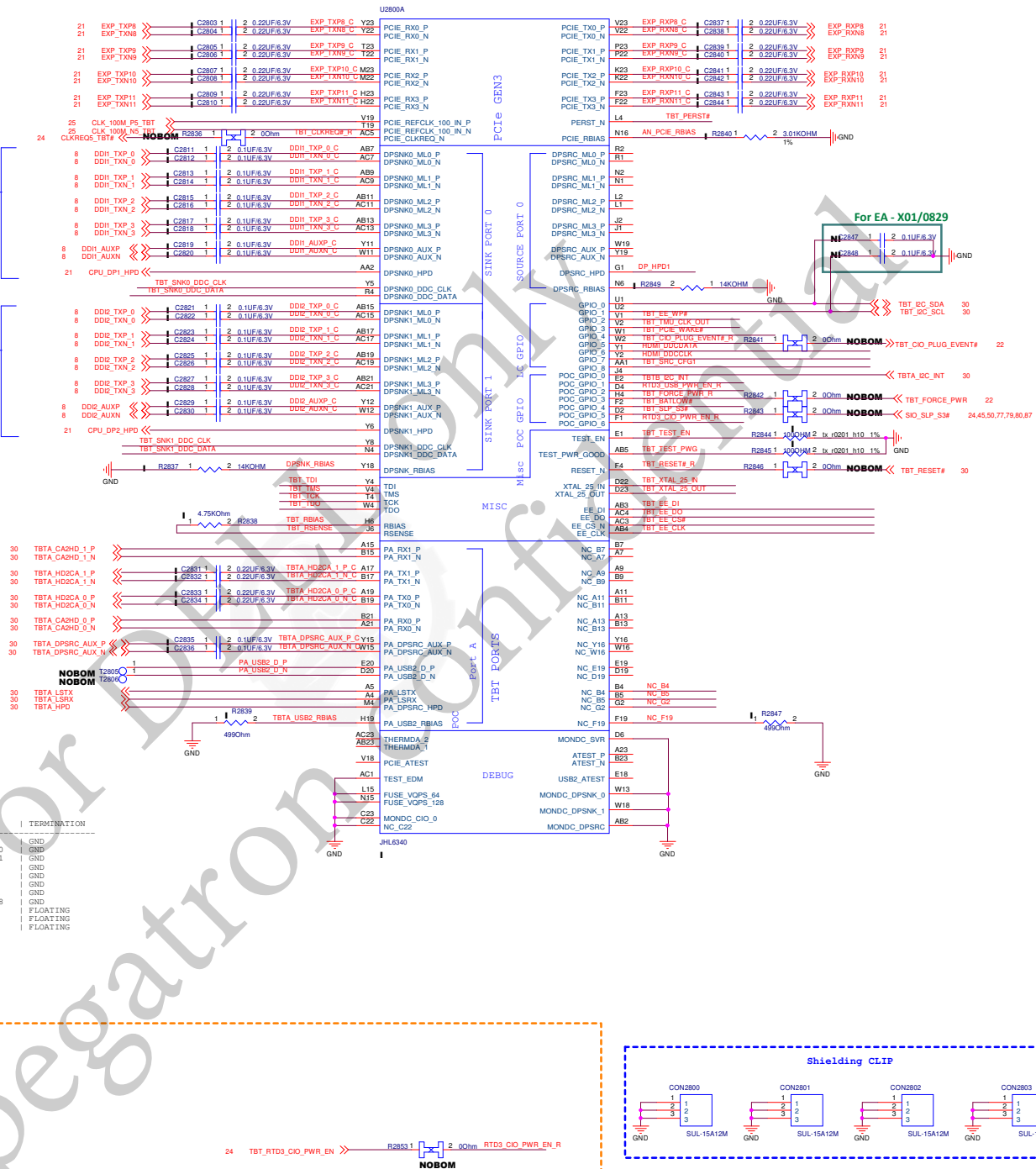
CPU DDI1

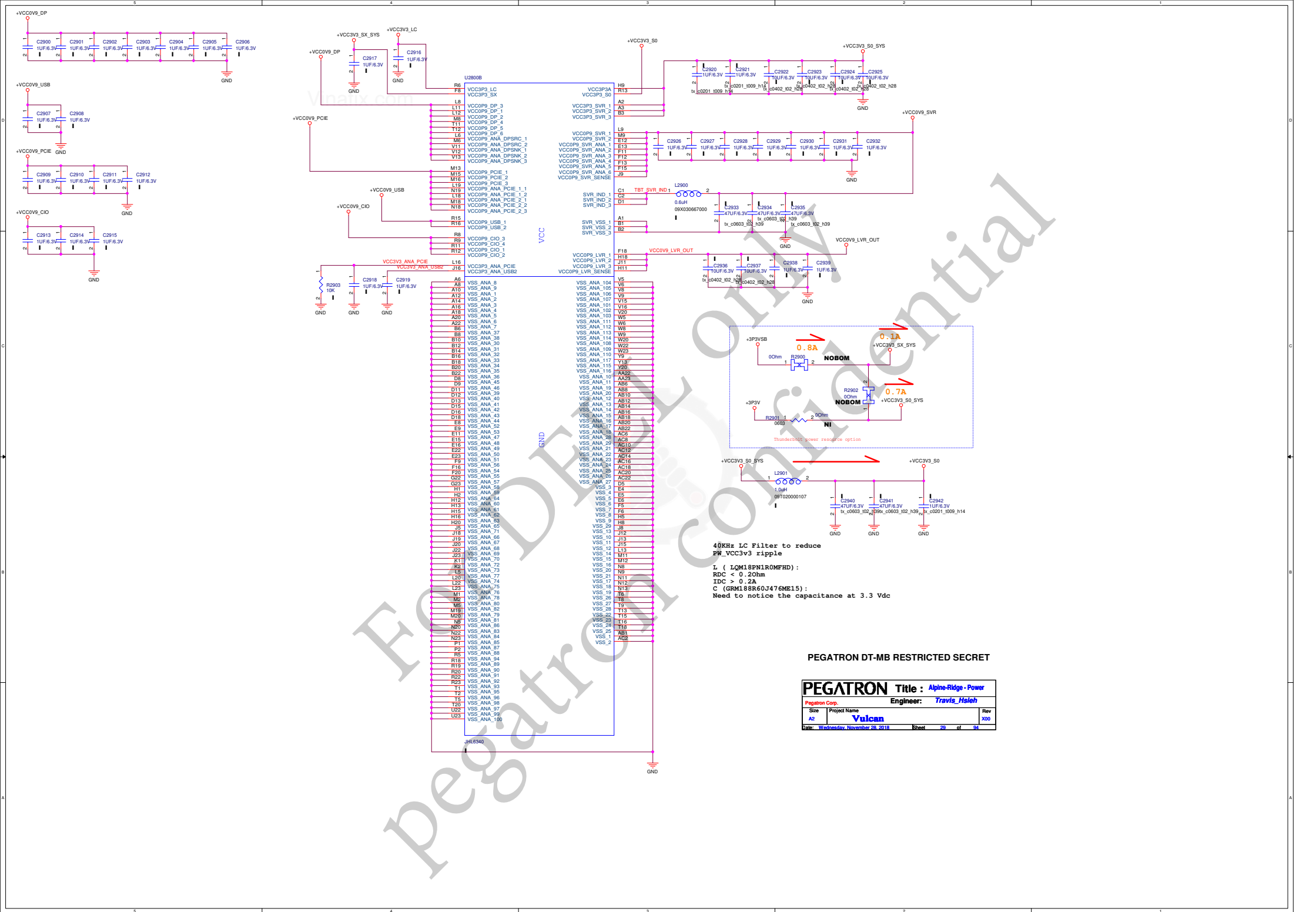
CPU DDI2

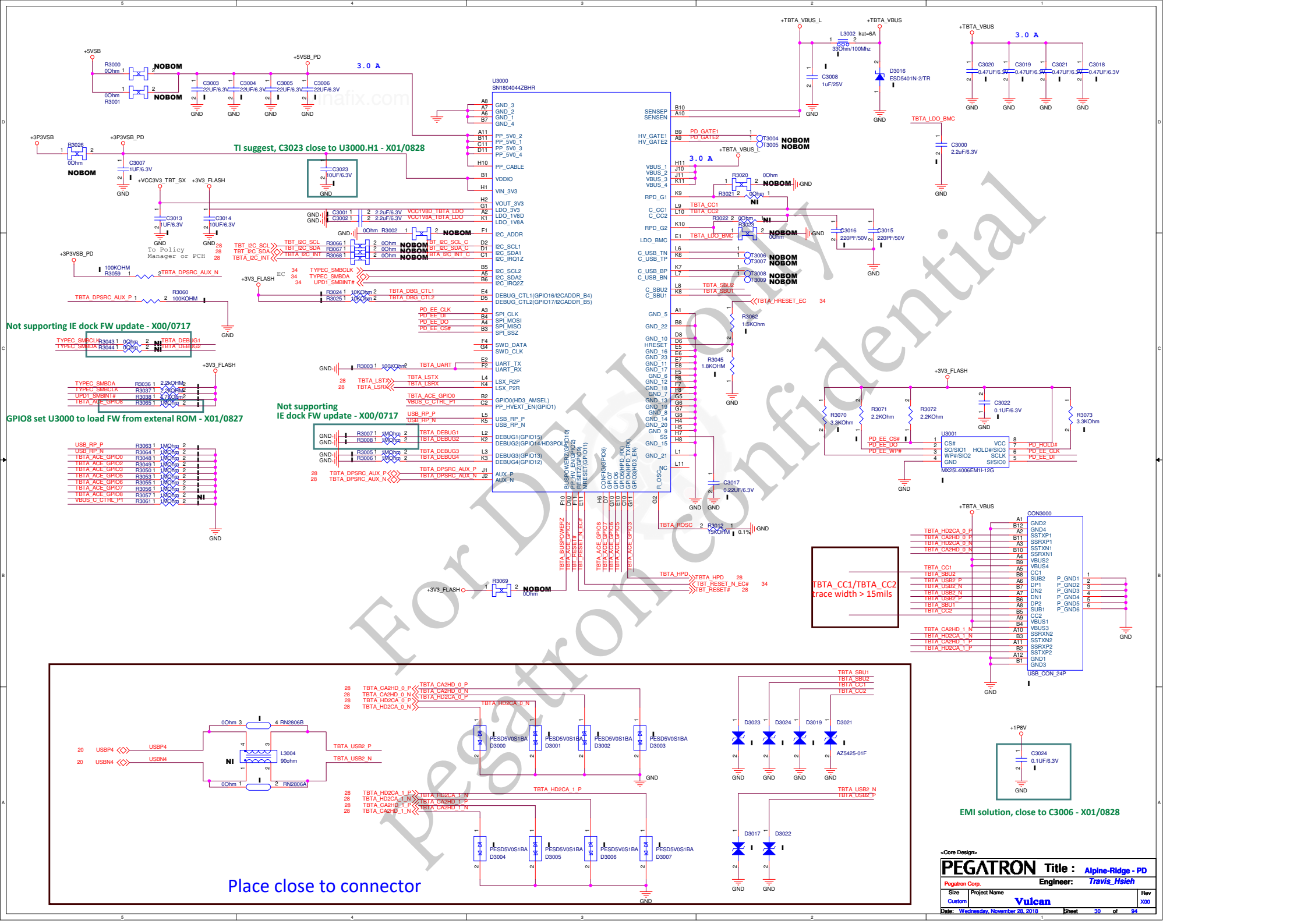
DEBUG PINs:



可置放於shielding外

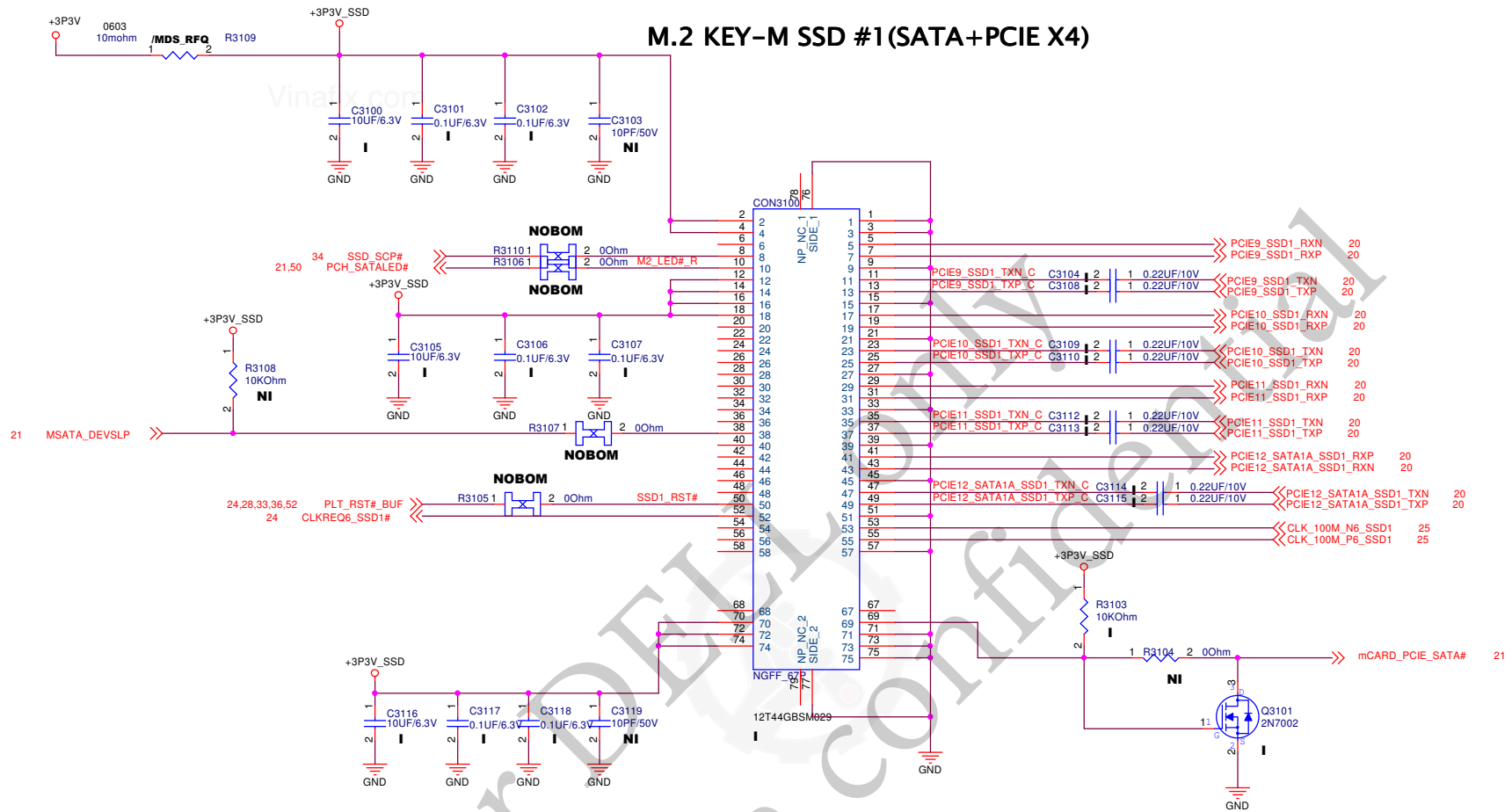




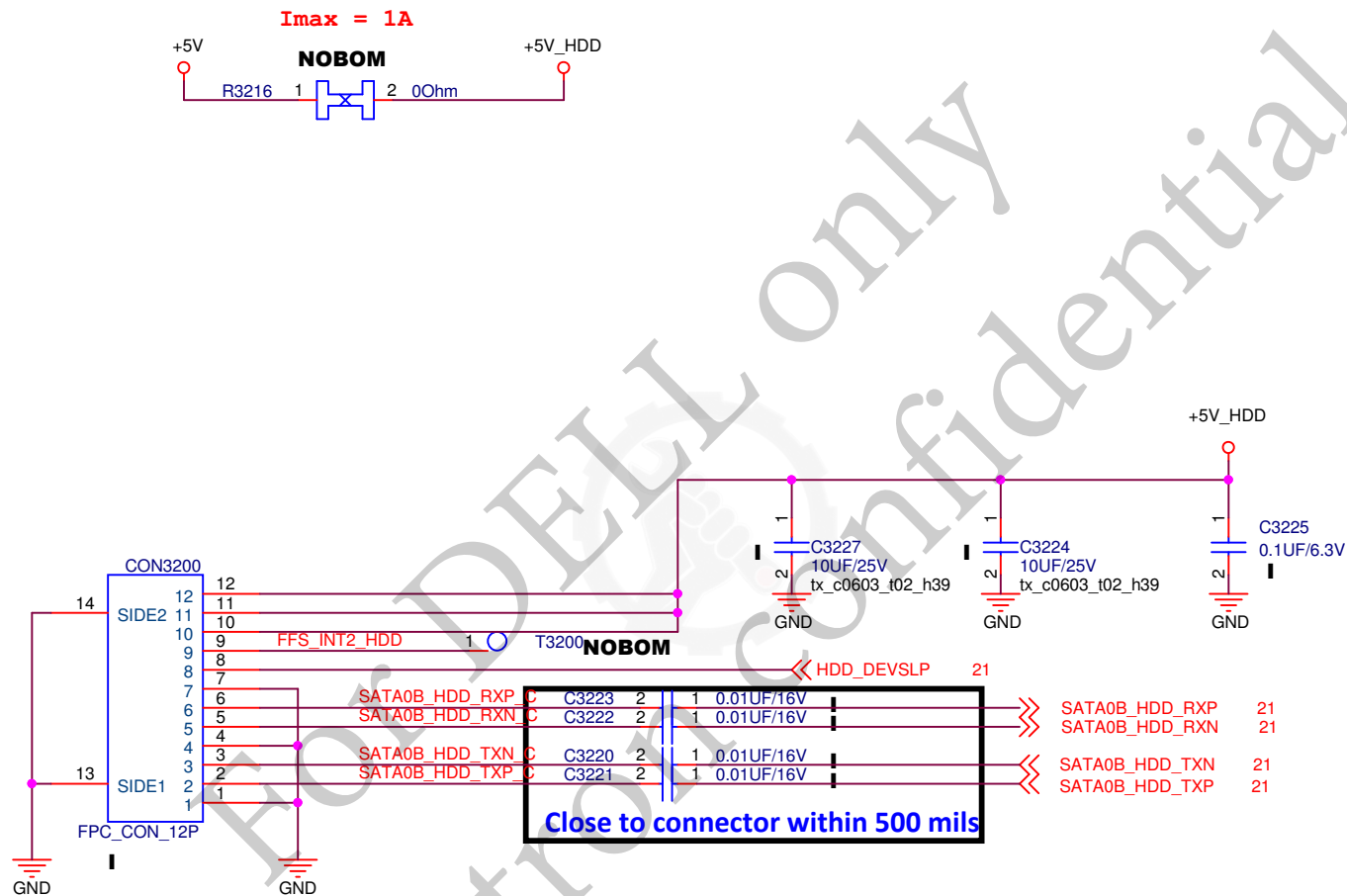




# M.2 KEY-M SSD #1 (SATA+PCIE X4)



# HDD

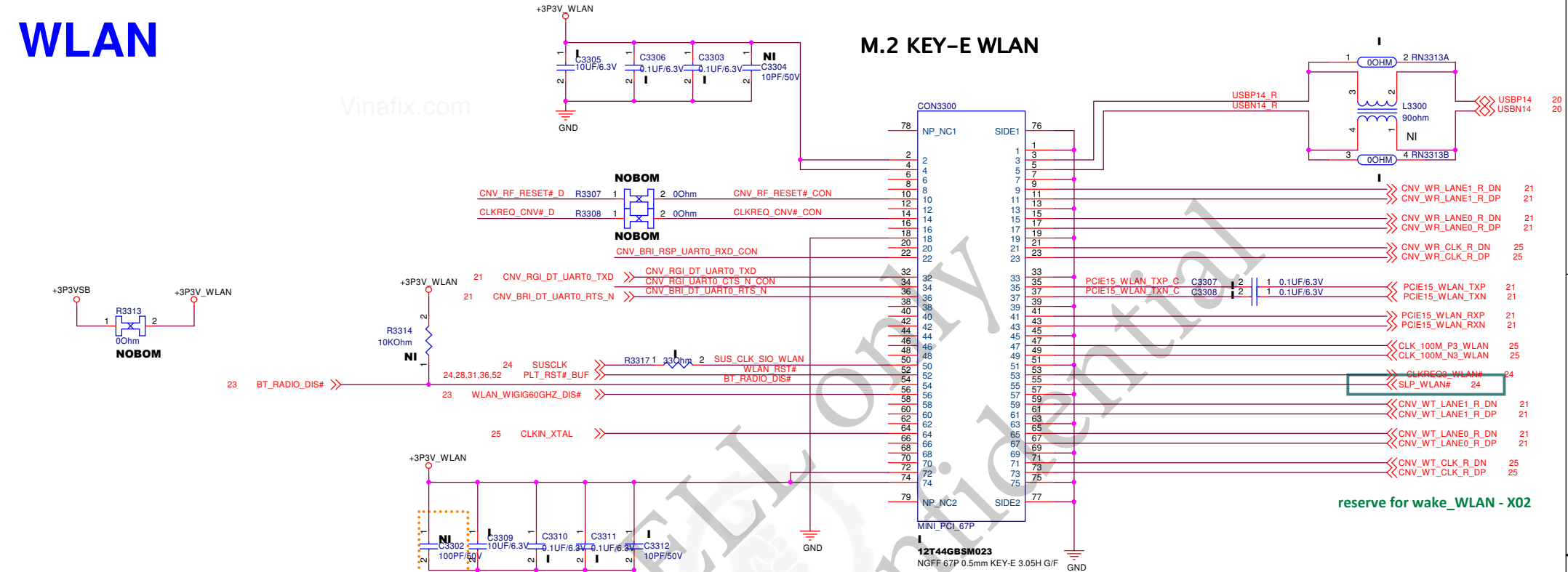




# WLAN

Vinafix.com

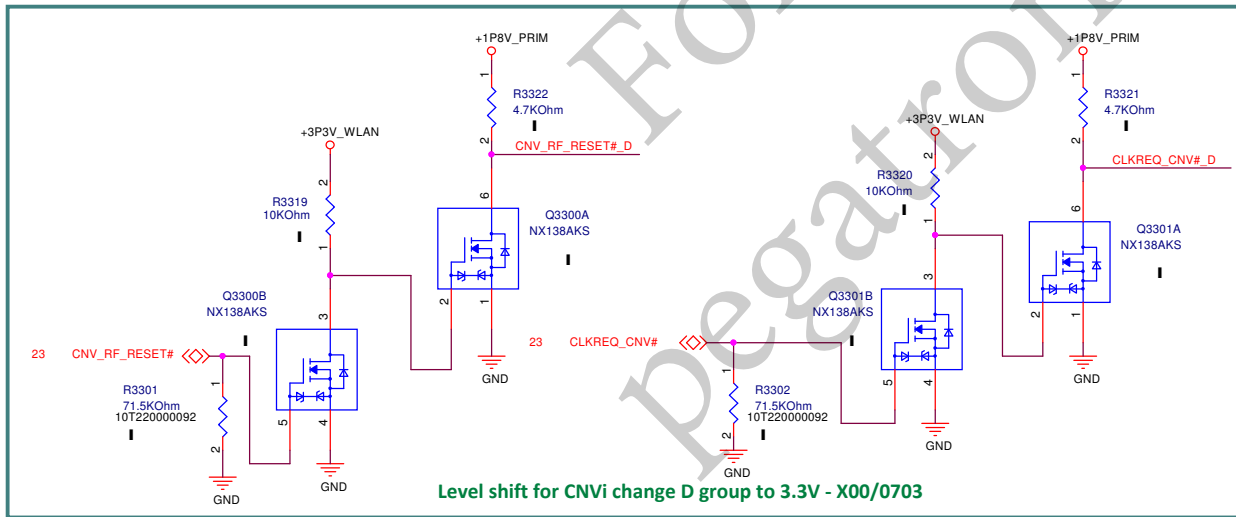
## M.2 KEY-E WLAN



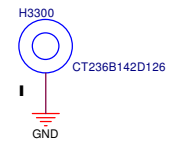
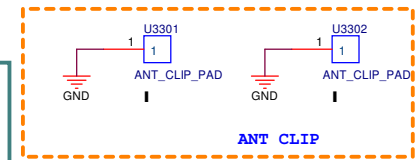
21 CNV\_BRI\_RSP\_UART0\_RXD << R3309 1 2 22Ohm CNV\_BRI\_RSP\_UART0\_RXD\_CON  
21 CNV\_RGI\_UART0\_CTS\_N << R3311 1 2 22Ohm CNV\_RGI\_UART0\_CTS\_N\_CON

Remark: 1. NC is not connected; YES is connected.  
2. Pin54 is BT\_DISABLE\_L; Pin56 is WLAN\_DISABLE\_L.  
3. Pin 20,22,32,34 and 36 are GPIO and have internal pull up(QCA6174A75), Suggest platform NC those pins.  
4. Pin44, 46, 48, QCA suggest platform to NC.  
5. Pin17 and 19 suggest reserve test point at platform side.

reserve for wake\_WLAN - X02



Level shift for CNVi change D group to 3.3V - X00/0703



# Pull Up

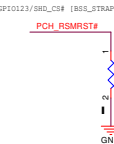
# EC Power

# eSPI Strap

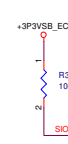
CR_STRAP	BSS_STRAP	Source
0	X	Use 3.3V Private SPI
1	0	Use eSPI Flash Channel
1	1	Use 3.3V Shared SPI

Note:  
If the eSPI Flash Channel is used for booting, the GPIO123/SHD\_CS# pin must be used as RSMRST#. This pin will be driven high by the boot ROM code in order to activate the eSPI flash channel.  
If the SHD\_SPI port is used for booting, then any unused GPIO may be used for RSMRST#.

GPIO123/SHD\_CS# [R83\_STRAP]



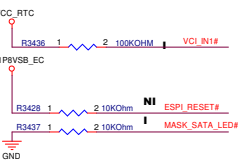
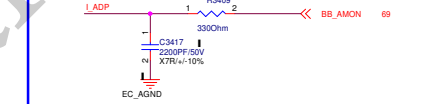
+3P3VSB\_EC



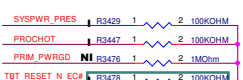
debug test point  
placement together  
bottom side

HOST_DEBUG_TX	1	T3404	TPC26T_50	NOBOM
ICSP_CLK	1	T3406	TPC26T_50	NOBOM
ICSP_DAT	1	T3405	TPC26T_50	NOBOM
ICSP_CLK	1	T3407	TPC26T_50	NOBOM
+3P3VSB_EC	1	T3409	TPC26T_50	NOBOM

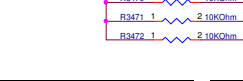
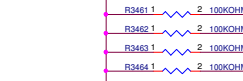
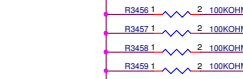
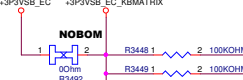
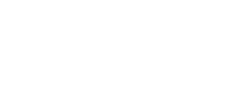
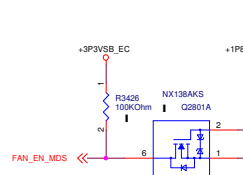
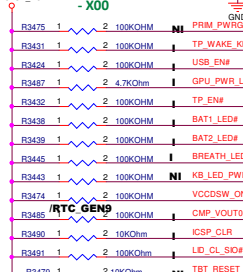
Adapter power monitor to EC ADC pin  
Need very close to EC



Imax: 12.5mA

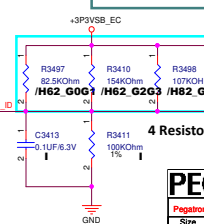
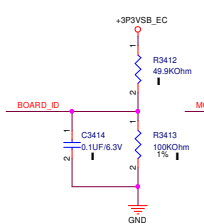


PD reset  
follow reference design  
-X00

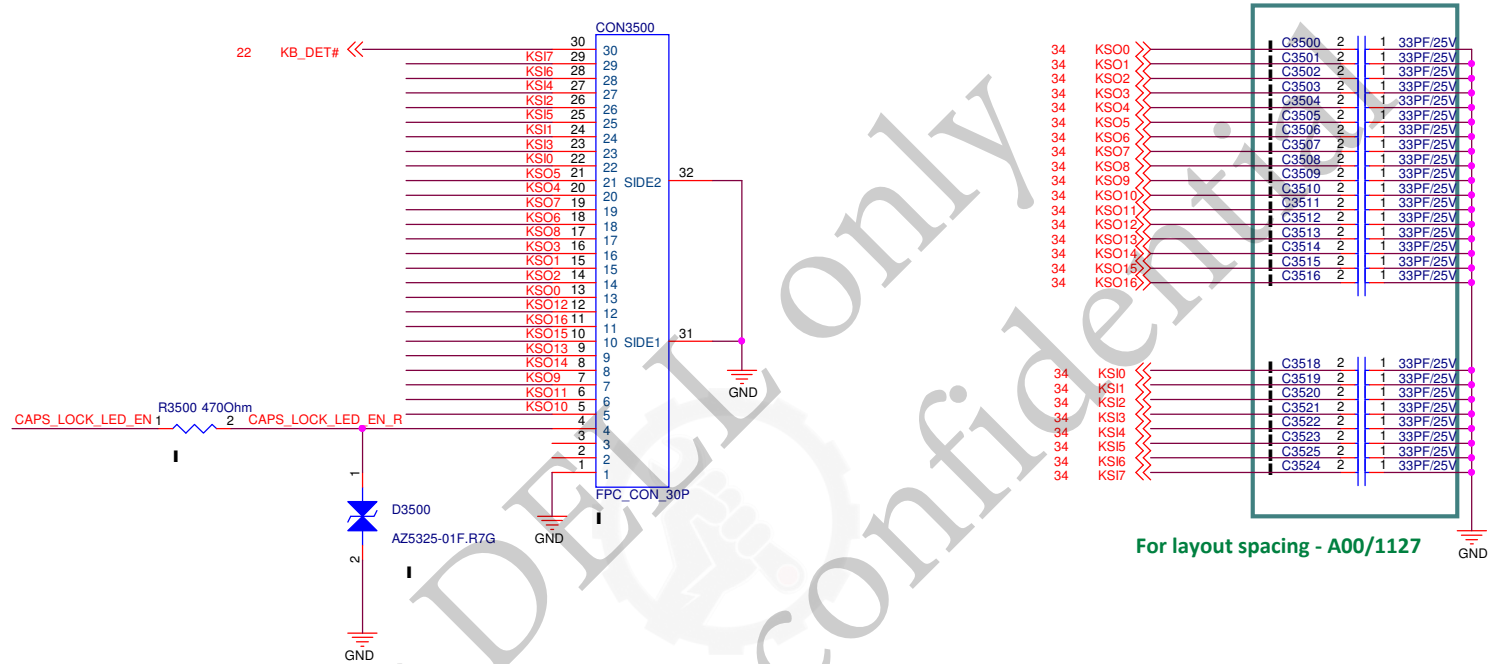


Board_ID	config	Pull-High res ; R3412	Voltage
X00(EVT)	10K		3
X01(DVT)	17.8K		2.801
X02(DVT2)	27K		2.598
X03(reserve1)	37.4K		2.402
A00(PVT)	49.9K		2.201
A01	64.9K		2.001
A02	82.5K		1.808
A03	107K		1.594
Reserve2	154K		1.299
Reserve3	200K		1.1

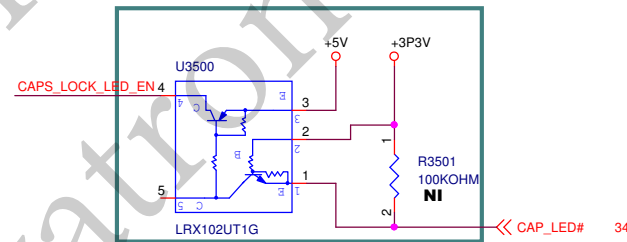
MODEL ID	config	CPU	GPU	Pull-High res ; R3410	Voltage
0	H62	N17P_G1/N18P_G0		10K	3
1	H82	N17P_G1/N18P_G0		17.8K	2.801
2	H62	N18P_G1		27K	2.598
3	H82	N18P_G1		37.4K	2.402
4		Reserve		49.9K	2.201
5		Reserve		64.9K	2.001
6	H62	N17E_G1/N18E_G1/N18E_G0		82.5K	1.808
7	H82	N17E_G1/N18E_G1/N18E_G0		107K	1.594
8	H62	N18E_G2_G3		154K	1.299
9	H82	N18E_G2_G3		200K	1.1



## KeyBoard connector



For layout spacing - A00/1127



TX pool change to MX per CE request - X01/0801

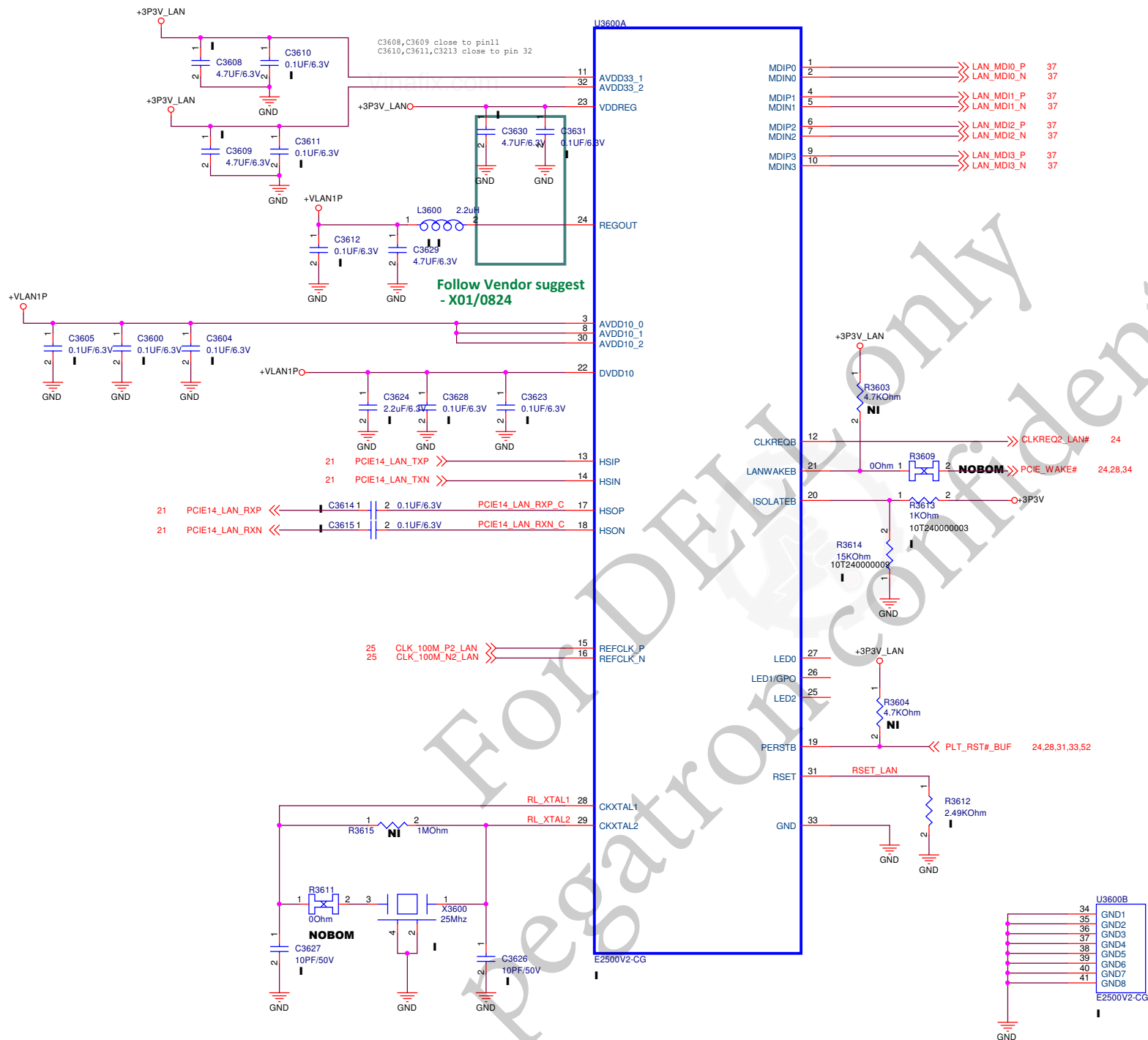
PEGATRON DT-MB RESTRICTED SECRET

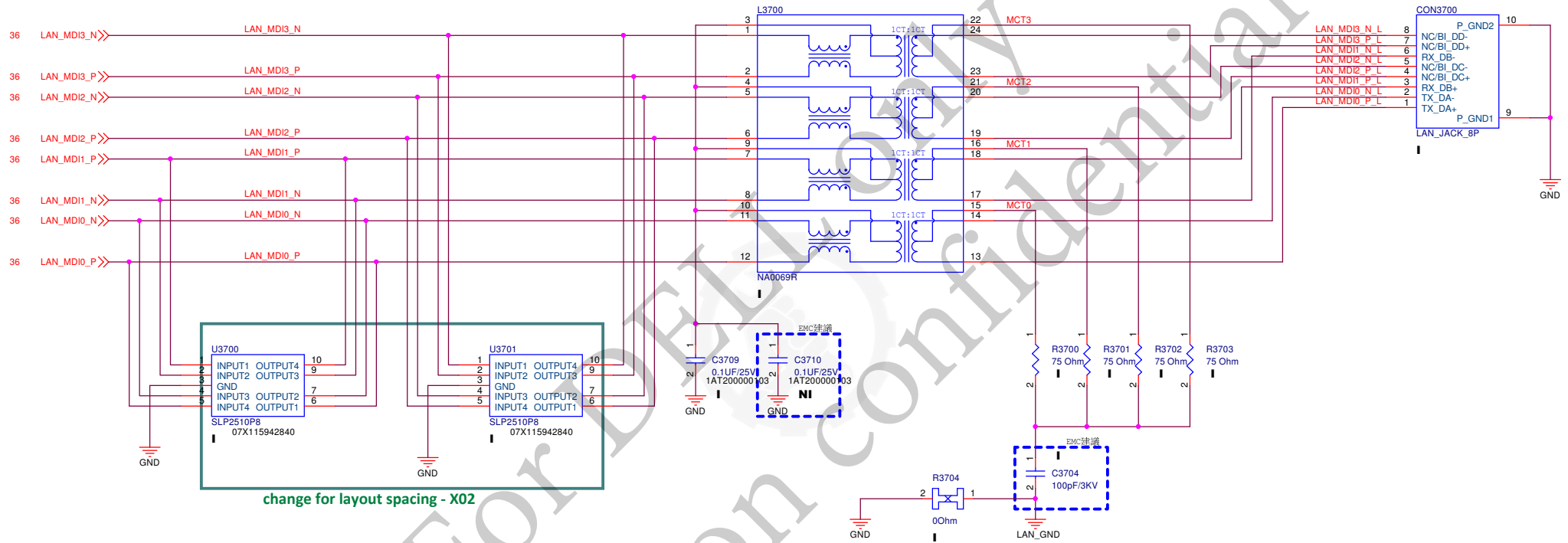
**PEGATRON** Title : KB & NKRO

Pegatron Corp. Engineer: Travis\_Hsieh

Size B Project Name **Vulcan** Rev X00

Date: Wednesday, November 28, 2018 Sheet 35 of 94





<Core Design>

<b>PEGATRON</b>			Title : <b>LAN JACK</b>	
Pegatron Corp.			Engineer: <b>Travis_Hsieh</b>	
Size A3	Project Name <b>Vulcan</b>			Rev X00
Date: Wednesday, November 28, 2018		Sheet 37 of 94		

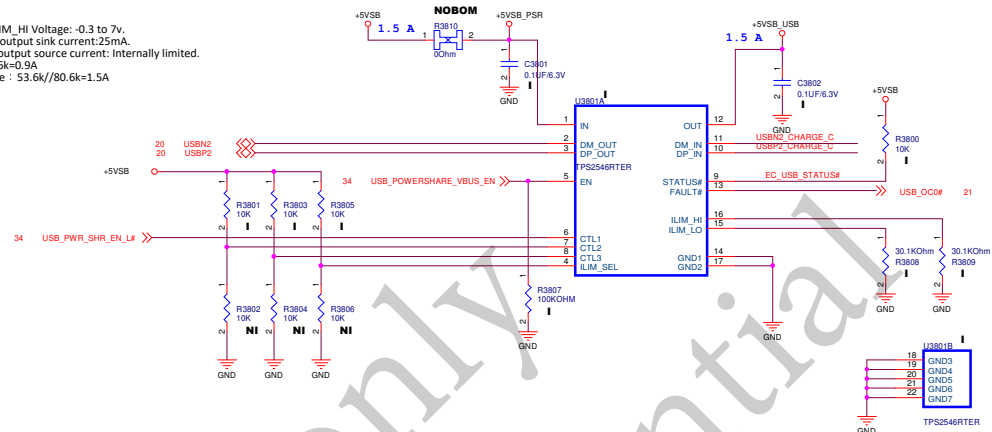
Table 2. Truth Table

CTL1	CTL2	CTL3	ILIM_SEL	MODE	CURRENT LIMIT SETTING	STATUS OUTPUT (Active low)	COMMENT
0	0	0	0	Discharge	NA	OFF	OUT held low
0	0	0	1	Discharge	NA	OFF	OUT held low
0	0	1	0	DCP_Auto	ILIM_HI	OFF	Data Lines Disconnected
0	0	1	1	DCP_Auto	$I_{CDP\_PWR}$ & ILIM_HI <sup>(1)</sup>	DCP load present <sup>(2)</sup>	Data Lines Disconnected and Load Detect Function Active
0	1	0	0	SDP1	ILIM_LO	OFF	Data Lines connected
0	1	0	1	SDP1	ILIM_HI	OFF	Data Lines Disconnected
0	1	1	0	DCP_Auto	ILIM_HI	OFF	Data Lines Disconnected
0	1	1	1	DCP_Auto	ILIM_HI	DCP load present <sup>(1)</sup>	Data Lines Disconnected and Load Detect Function Active
1	0	0	0	DCP_Shorted	ILIM_LO	OFF	Device Forced to stay in DCP BC1.2 charging mode
1	0	0	1	DCP_Shorted	ILIM_HI	OFF	Device Forced to stay in DCP BC1.2 charging mode
1	0	1	0	DCP / Divider1	ILIM_LO	OFF	Device Forced to stay in DCP Divider1 Charging Mode
1	0	1	1	DCP / Divider1	ILIM_HI	OFF	Device Forced to stay in DCP Divider1 Charging Mode
1	1	0	0	SDP1	ILIM_LO	OFF	Data Lines Connected
1	1	0	1	SDP1	ILIM_HI	OFF	Data Lines Connected
1	1	1	0	SDP2 <sup>(4)</sup>	ILIM_LO	OFF	Data Lines Connected
1	1	1	1	CDP <sup>(4)</sup>	ILIM_HI	CDP load present <sup>(5)</sup>	Data Lines Connected and Load Detect Active

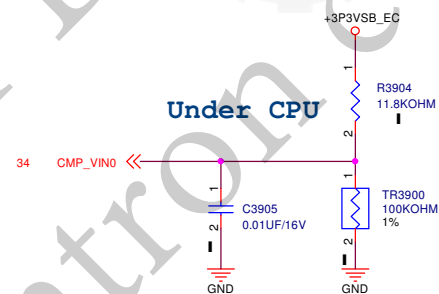
- (1) TPS2546: Current limit ( $I_{CDP}$ ) is automatically switched between  $I_{CDP\_PWR}$  and the value set by ILIM\_HI according to the Load Detect – Power Wake functionality.  
(2) DCP Load present governed by the "Load Detection – Power Wake" limits.  
(3) DCP Load present governed by the "Load Detection – Non Power Wake" limits.  
(4) No OUT discharge when changing between 1111 and 1110.  
(5) CDP Load present governed by the "Load Detection – Non Power Wake" limits and BC1.2 primary detection.

## Power Share

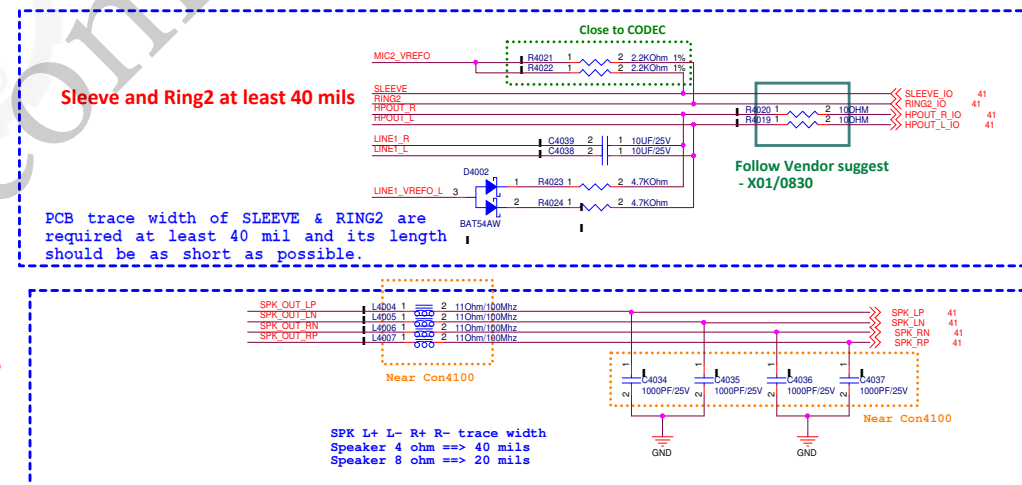
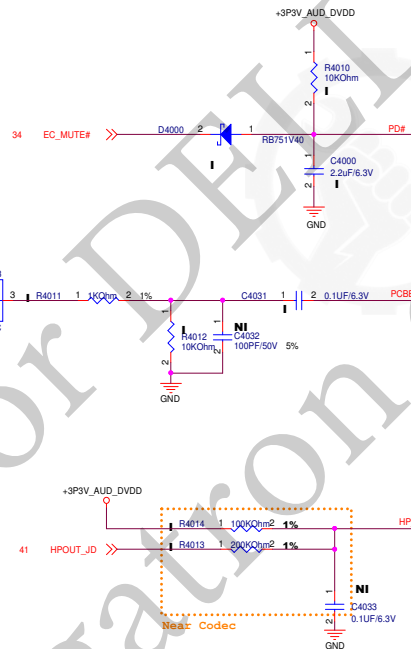
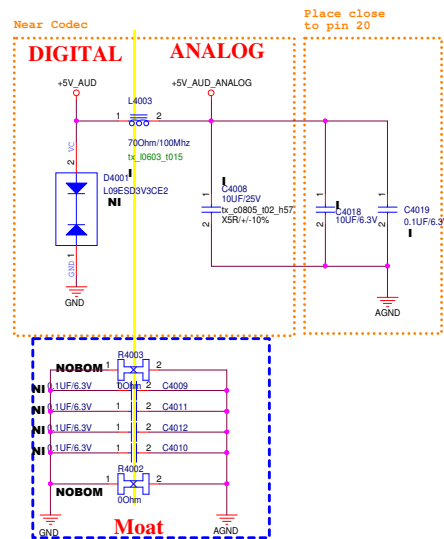
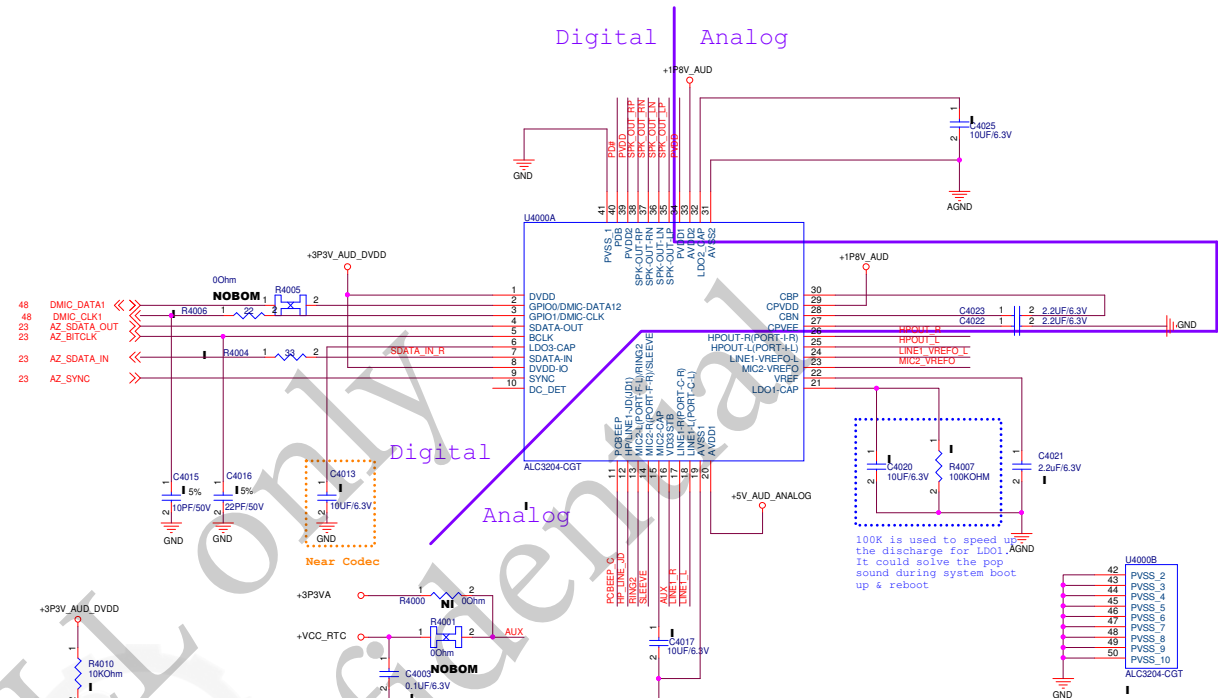
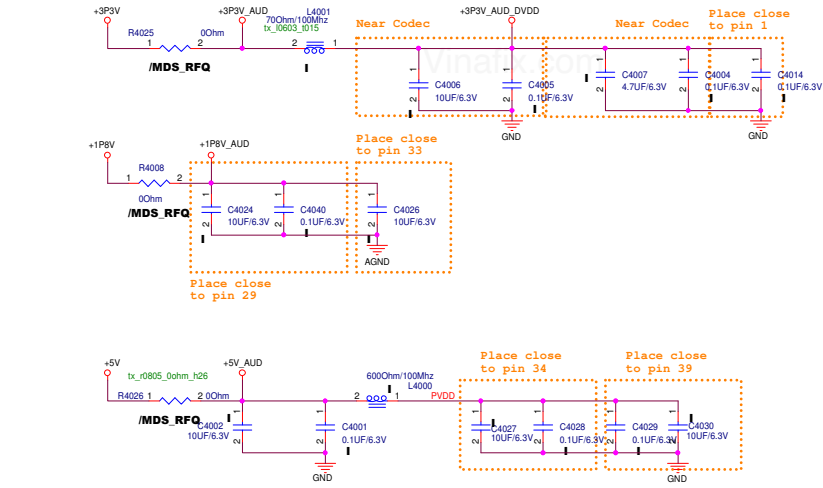
STATUS#, FAULT#, ILIM\_LO, ILIM\_HI Voltage: -0.3 to 7v.  
STATUS#, FAULT# Continuous output sink current: 25mA.  
ILIM\_LO, ILIM\_HI Continuous output source current: Internally limited.  
SDP Mode(S0/S3/S4/S5) : 53.6k±0.9A  
CDP(S0)& DCP(S3/S4/S5) Mode : 53.6k/80.6k±1.5A



```
U3901: Under GPU thermal pipe
Q3900: Under CPU thermal pipe
Q3901: Close to SSD connector
```



## AUDIO CODEC- ALC3204



**R4003** Place at Codec bottom side.  
**R4002** Place near audio connector. Don't short this pad to USB digital ground, and should be far away from any power traces.



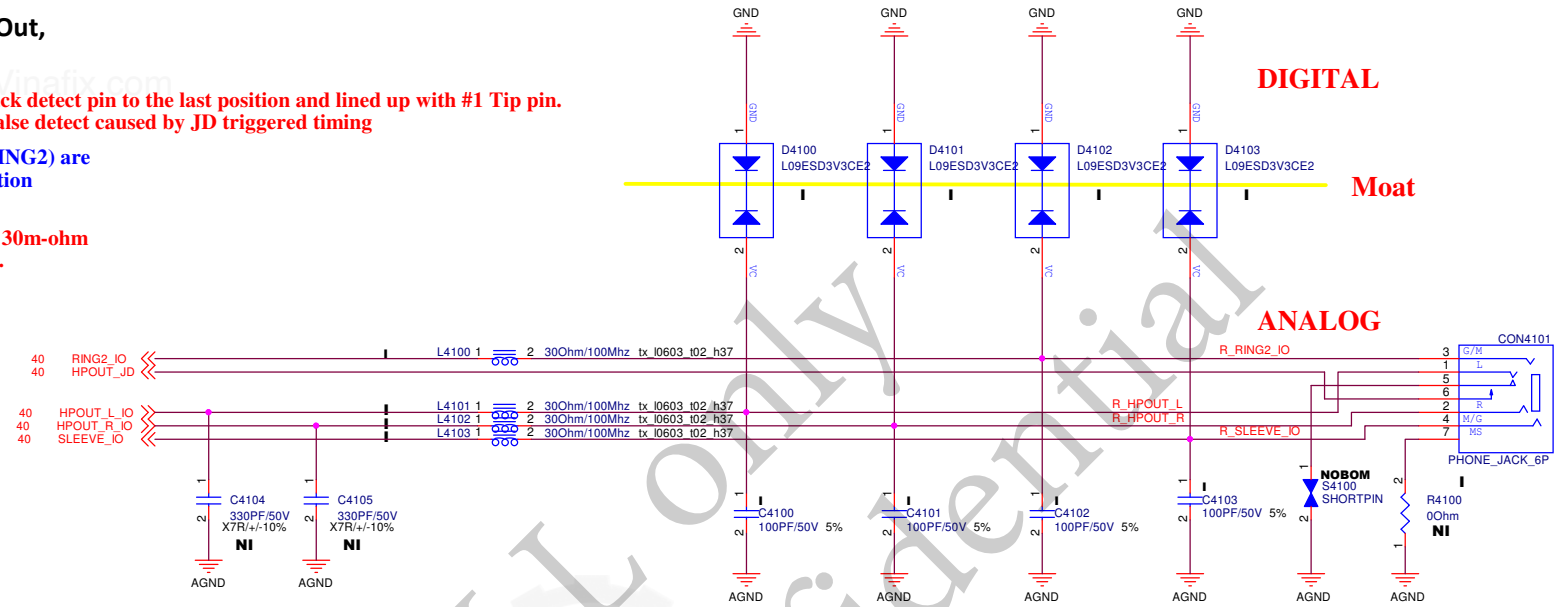
# GLOBAL HEADSET CONNECTOR

OMTP/CTIA headset, Headphone, Line-Out,  
Microphone input, Line input.

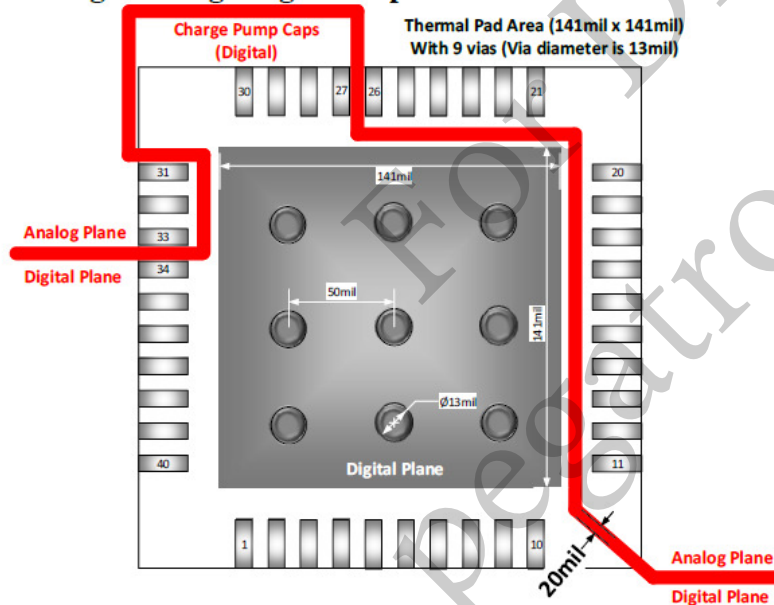
This recommended phone-jack has moved #5/#6 Jack detect pin to the last position and lined up with #1 Tip pin.  
This kind of design will significantly improve the false detect caused by JD triggered timing

PCB trace width of MIC2-R(SLEEVE)/MIC2-L(RING2) are required at least 40 mil for HP crosstalk consideration and, its length should be as short as possible.

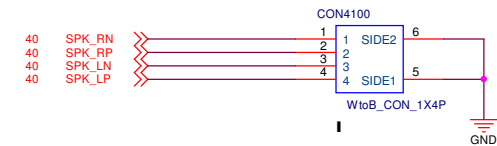
L4100/L4103 should choose DC resistance (Rdc) < 30m-ohm to get the best audio performance for HP crosstalk.



## Separate Analog and Digital ground plane



## SPEAKER CONN



<Core Design>

PEGATRON		Title : AUDIO JACK	
Pegatron Corp.		Engineer: Travis_Hsieh	
Size A3	Project Name Vulcan	Rev X00	
Date: Wednesday, November 28, 2018		Sheet 41 of 94	

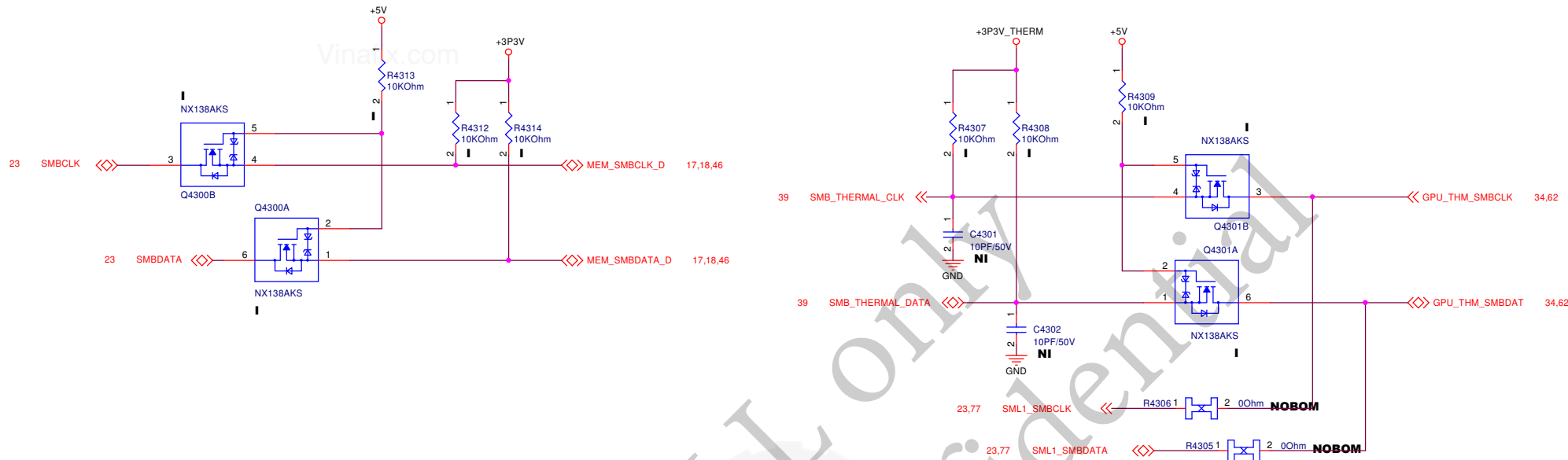
Reserved Page

For Design Only  
pegatron confidential

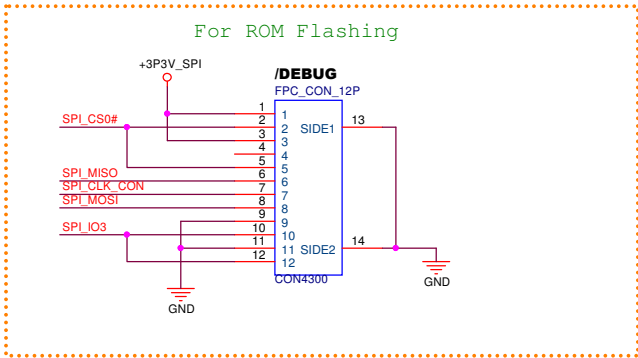
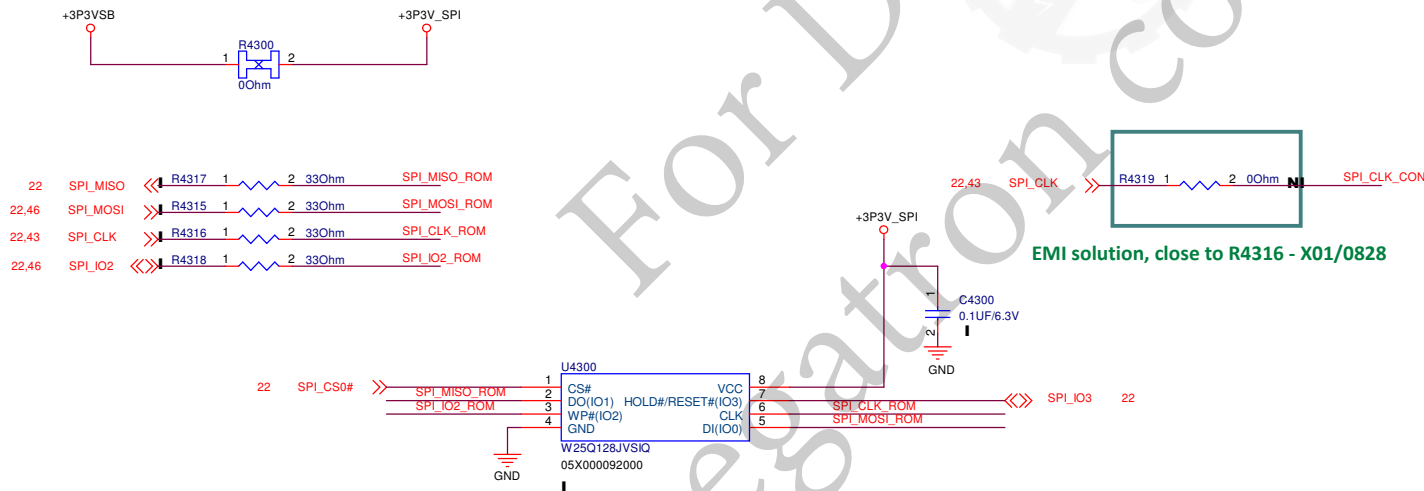
<Core Design>

PEGATRON		Title : Reserved	
Pegatron Corp.		Engineer: Travis_Hsieh	
Size A4	Project Name Vulcan		Rev X00
Date: Wednesday, November 28, 2018		Sheet	42 of 94

SMBUS



SPI ROM (Quad I/O Supported)



PEGATRON DT-MB RESTRICTED SECRET

PEGATRON Title : SM BUS & SPI ROM

Pegatron Corp. Engineer: Travis\_Hsieh

Size A3 Project Name Vulcan Rev X00

Date: Wednesday, November 28, 2018 Sheet 43 of 94



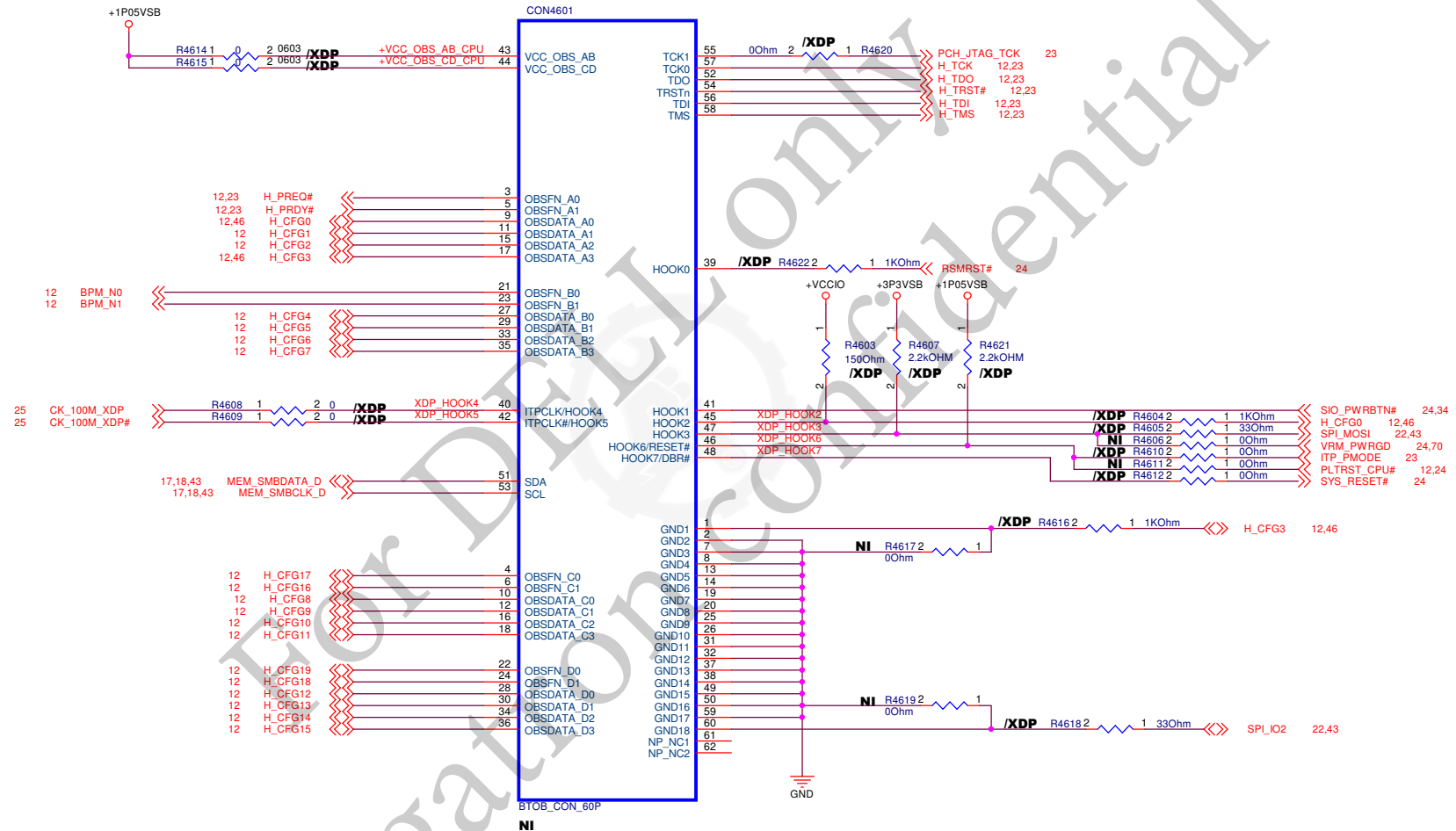
The schematic diagram illustrates the AC/DC converter circuit for the 4.22 ErP Lot 6 Adapter Support. The circuit is designed to convert AC input (ACAV\_IN\_R) into a regulated DC output. Key components include a bridge rectifier (CH751H-40AGP) and a filter capacitor (R4519, 0.001uF). The rectifier output is connected to a MOSFET (Q4500A, NX138AKS) driven by a gate driver (Q4500B, NX138AKS). The MOSFET output is connected to a filter capacitor (R4510, 1M00mF) and a load (R4511, 3.3K00mF). The circuit is powered by a +VDC\_IN supply and includes a GND connection.

4.22 ErP Lot 6 Adapter Support  
Platform in S5 state is required to consume 4mA minimum from adapter DC input without battery attached at the moment of plugging in system.

The schematic diagram illustrates a Thermal CMP Circuit. It is powered by a +3P3VSB\_EC supply, which passes through a 20KOhm resistor (R4518) and a 0.01uF/16V capacitor (C4501) to ground. The circuit also includes a +3P3VSB supply connected to a 100KOhm resistor (R4502) and a 4.7uF/6.3V capacitor (C4500) to ground. Two NOBOM comparators (R4507 and R4515) are used, with their inputs connected to various system signals: 34 VCREFG, 34 CMP\_VOUT0, 62,67 GPU\_OVERT\_R, and 39 PM\_THRMTRIP#. A BAW56W diode (D4501) is connected to the output of the comparators. A MOSFET (Q4501A NX138AKS) is used for switching, controlled by a 5V regulator (R4514) and a 20KOhm resistor (R4515). A note indicates that Vref = 1.1V is used to measure temperature.

[illegible]

# INTEL XDP DEBUG CONN



**REGATRON DT-MB RESTRICTED SECRET**

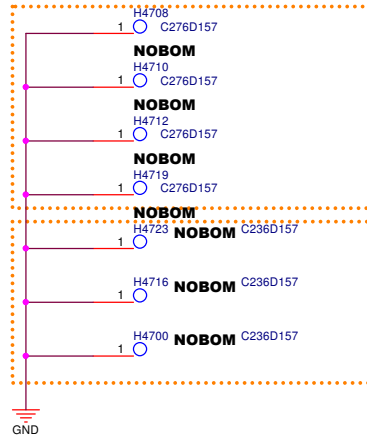
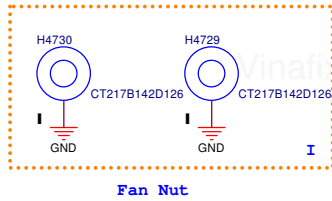
**PEGATRON** Title : **NDP**

**Engineer:** *Travis\_Hsieh*

Size <b>A3</b>	Project Name <b>Vulcan</b>	Rev <b>X00</b>
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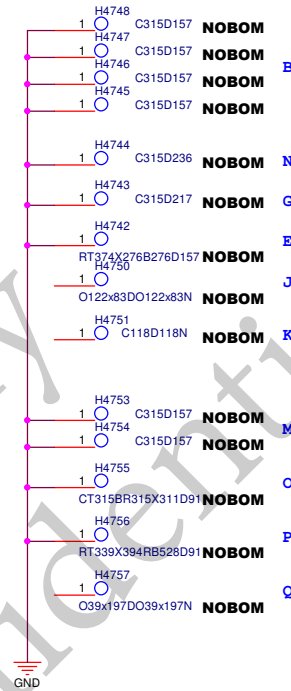
Date: Wednesday, November 28, 2018 Sheet 46 of 94

**NOBOM**  
PCB4700  
PCB\_BOARD  
CCL = Y

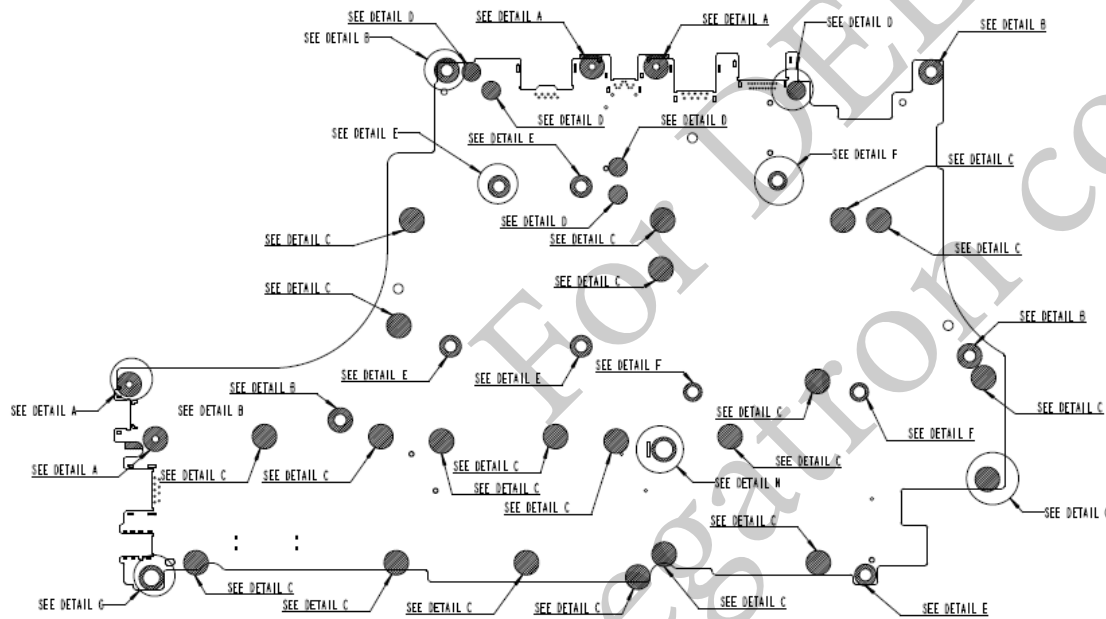


For CPU

For GPU



TOP VIEW



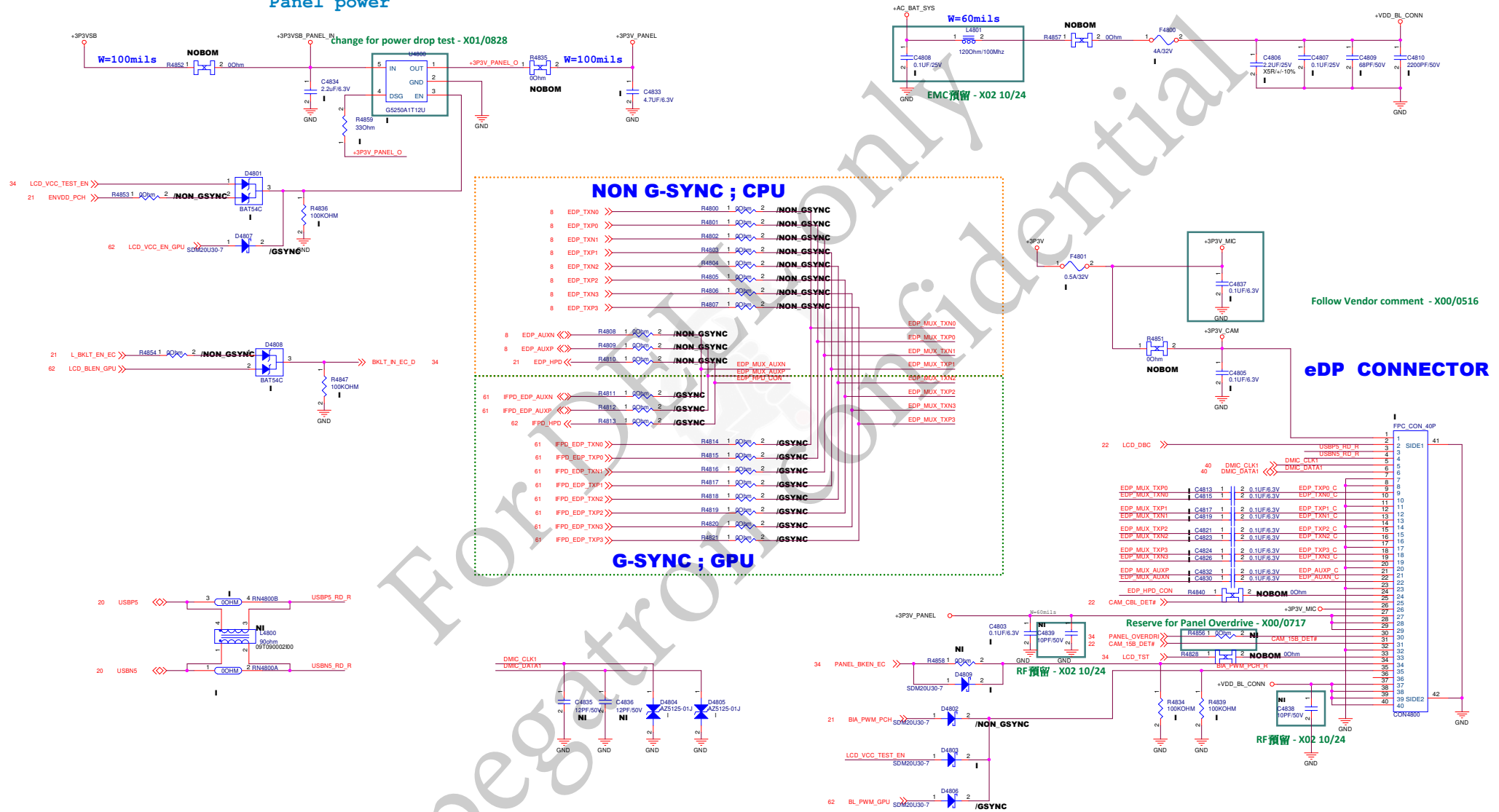
PEGATRON DT-MB RESTRICTED SECRET

<b>PEGATRON</b>		Title : PCB & Label & Screw	
Pegatron Corp.		Engineer: <b>Travis_Hsieh</b>	
Size A3	Project Name <b>Vulcan</b>	Date: Wednesday, November 28, 2018	Rev X00
Sheet 47 of 94			



Supply max 2.5A

## Panel power



&amp;ltCore Design&gt;

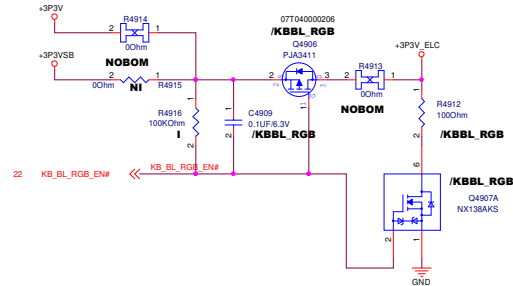
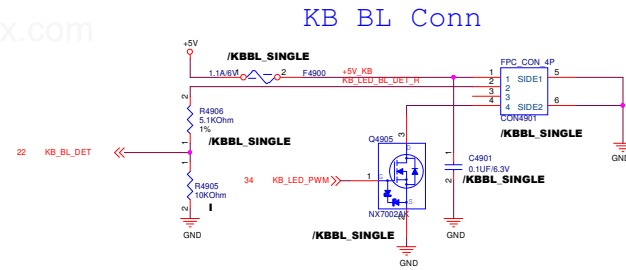
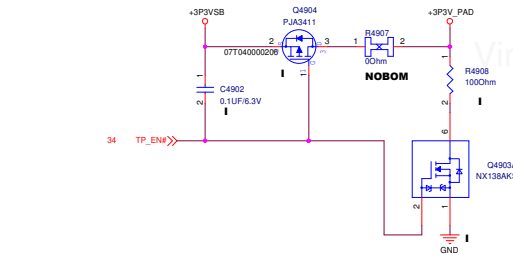
**PEGATRON** Title : **eDP CON.**

Pegatron Corp. Engineer: Travis\_Hsieh

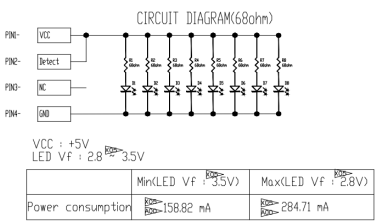
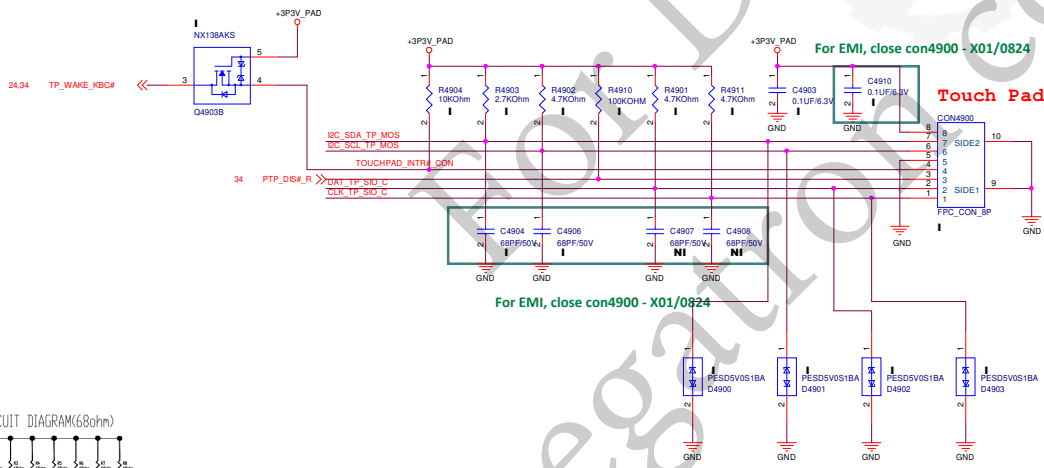
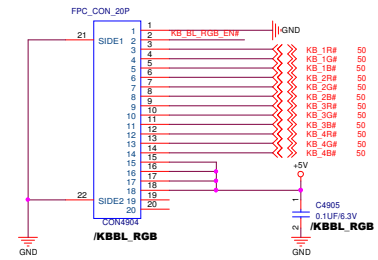
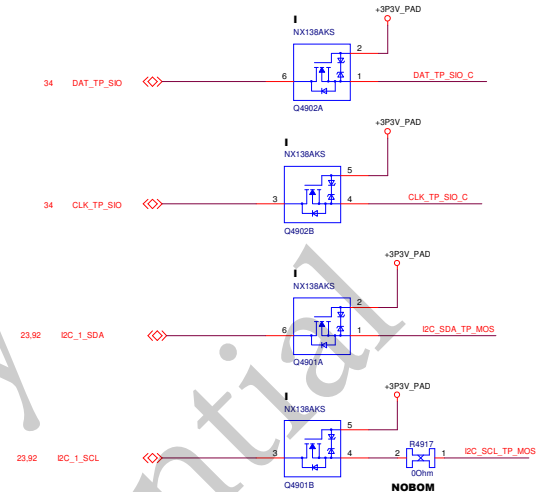
Size	Project Name	Rev
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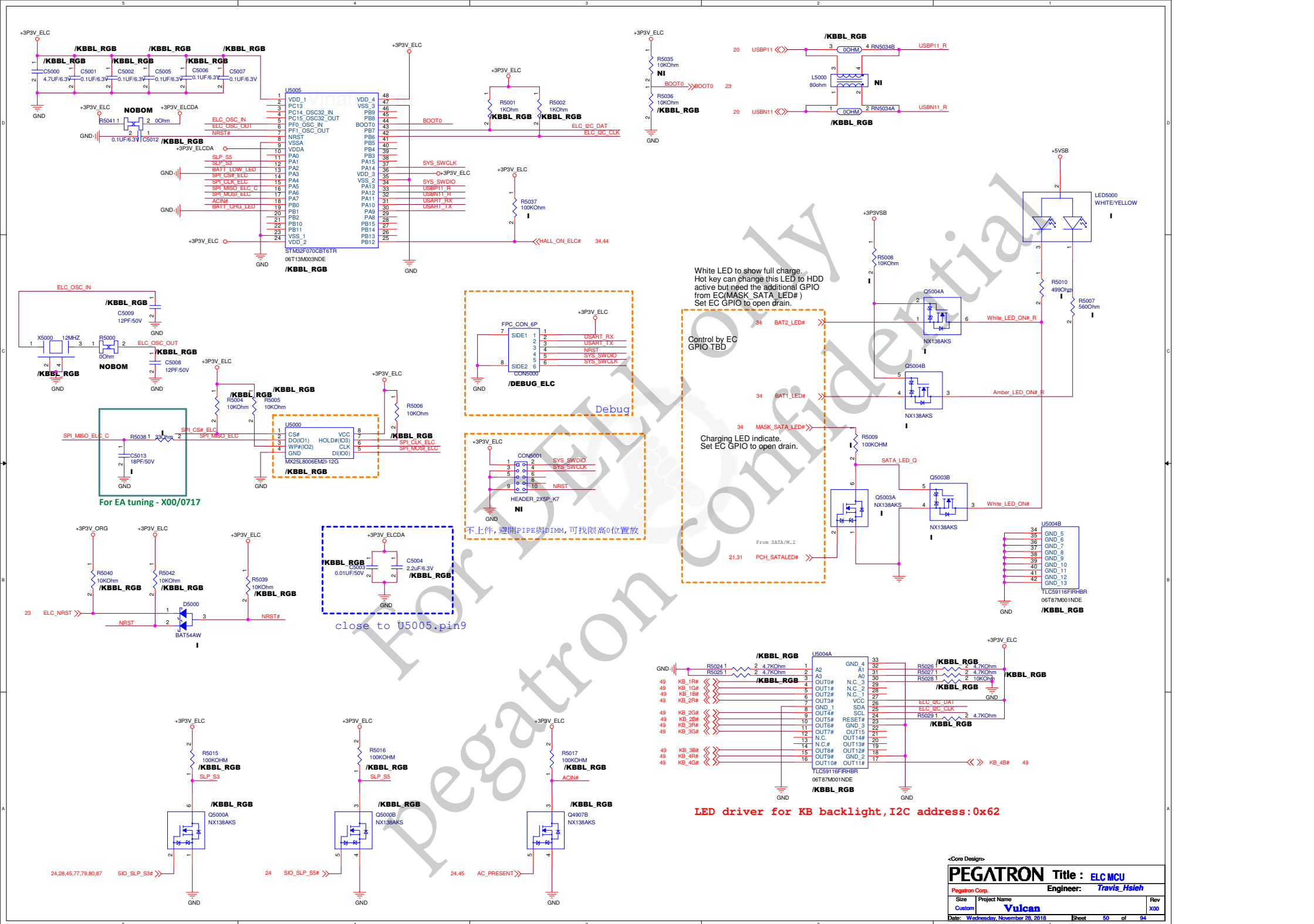
A2	<b>Vulcan</b>	X00
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Date: Wednesday, November 28, 2018 Sheet 48 of 94

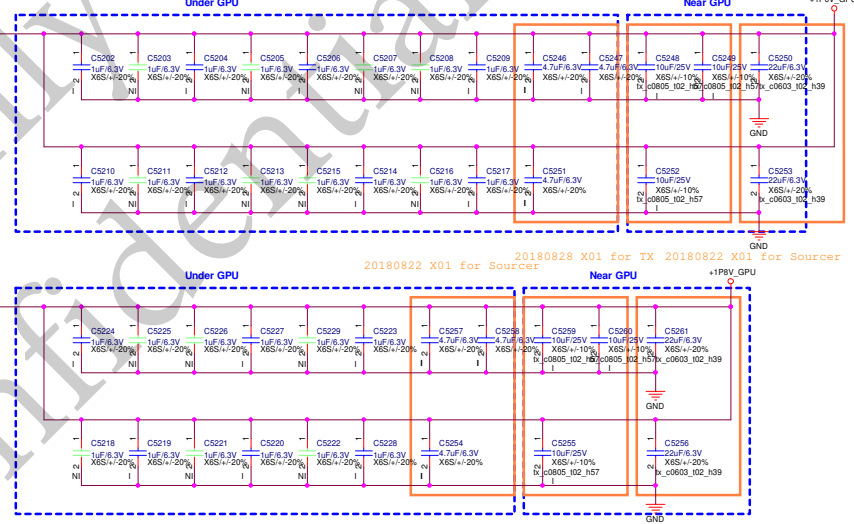


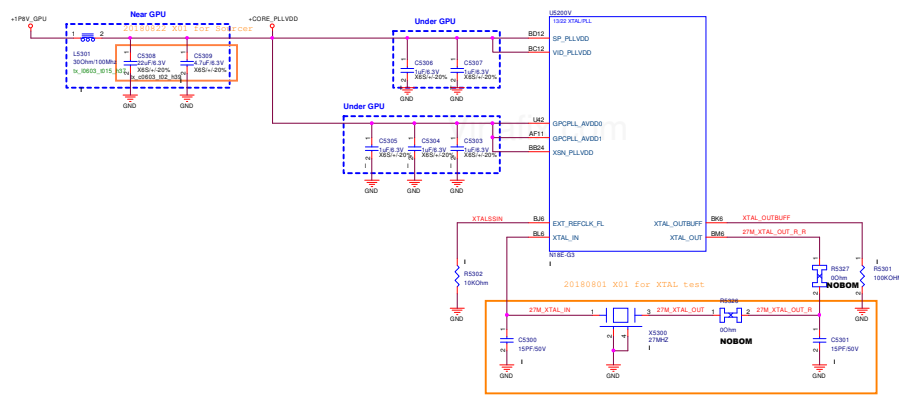
KB_BL_ID		
Config	KB_BL_RGB_EN#	KB_BL_DET
KB_BL_RGB	0	0
KB_SINGLE	1	1
KB_NON_BL	1	0
N/A	1	1











Strap Pins see Note			FS_OVERT* Function	
ROM_SO	ROM_SI	ROM_SCLK	FS_OVERT* function ENABLED	
L	L	L	FS_OVERT* function DISABLED (Reserved; do not configure)	
L	L	H	(Invalid; do not configure)	
all other configurations				

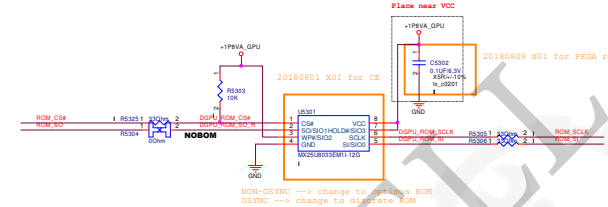
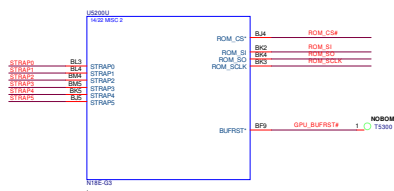
Strap Pins see Note			RAMCFG Setting Number	
STRAP2	STRAP1	STRAP0	(see Memory RVL for memory configs corresponding to these numbers)	
L	L	L	0 (0x0000)	
L	L	H	1 (0x0001)	
L	H	L	2 (0x0002)	

STRAP5	STRAP4	STRAP3	SMB_ALT_ADDR	DEVID_SEL	PCIE_CFG	VGA_DEVICE
M	H	H	1	1	1	1
M	H	L	1	1	1	0
M	L	H	1	1	0	1
M	L	L	1	1	0	0
L	H	M	1	0	1	1
L	M	H	1	0	1	0
L	M	L	1	0	0	1
L	L	M	1	0	0	0
H	H	H	0	1	1	1
H	H	L	0	1	1	0
H	L	H	0	1	0	1
H	L	L	0	1	0	0
L	H	H	0	0	1	1
L	H	L	0	0	1	0
L	L	H	0	0	0	1
L	L	L	0	0	0	0

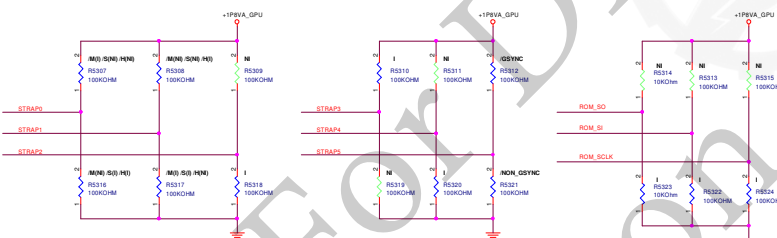
1:SMB\_ALT\_ADDR ENABLE  
0:SMB\_ALT\_ADDR DISABLE  
1:DEVID\_SEL REBRAND  
0:DEVID\_SEL ORIGINAL  
1:PCIE\_CFG LOW POWER  
0:PCIE\_CFG HIGH POWER  
1:VGA\_DEVICE ENABLE  
0:VGA\_DEVICE DISABLE

Default

Straps 需確認strap及ROM(Memory 還未確定)



Need NV check



Strap2,1,0, please check memory RVL  
/M(1): Micron STUFF /M(N1): Micron NO STUFF  
/S(1): Samsung STUFF /S(N1): Samsung NO STUFF  
/H(1): Hynix STUFF /H(N1): Hynix NO STUFF

Memory Density	Allowed Memory Configuration	FBVDD/Q	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed Grade	Date Code Alert	Qual Plan	Status
8 Gb	256Mx2Chx16	1.35V	Micron	MT61K256M32JE-14:A	A-die	0x1	14 Gbps	N/A	Full	Production candidate
			Samsung	K4Z80325BC-HC14	C-die	0x0	14 Gbps	N/A	Full	Production candidate

Notes:  
1. For N18E-G3, the maximum allowable memory case temperature is 95 °C.

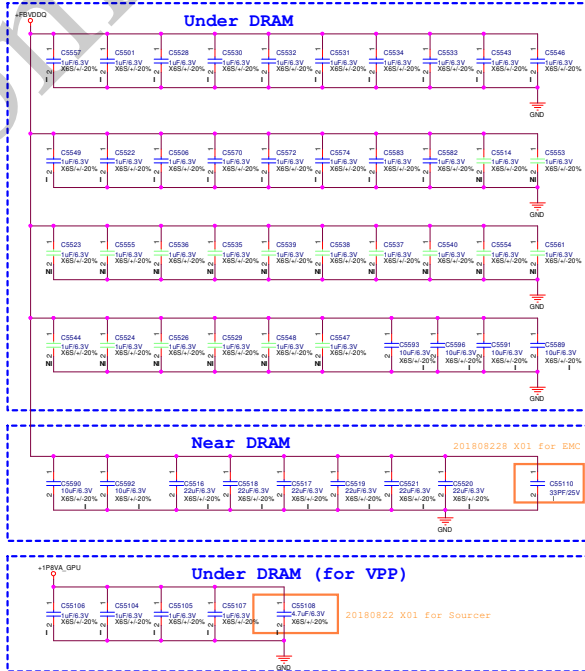
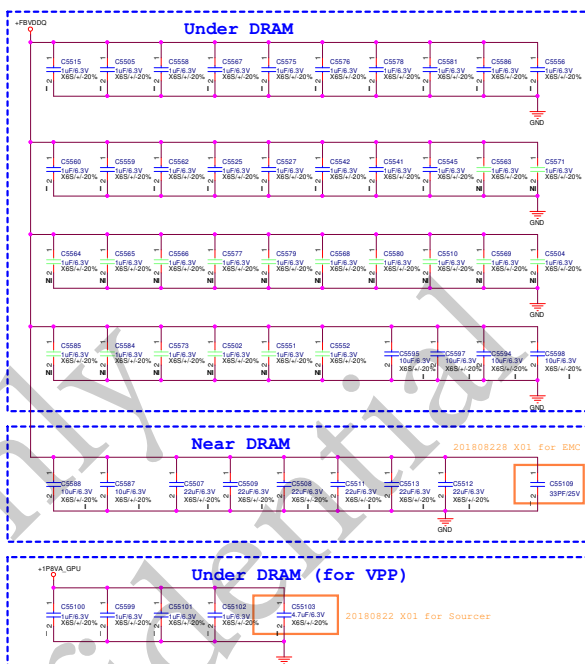
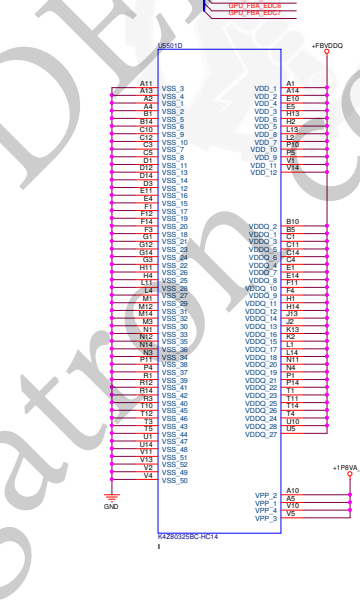
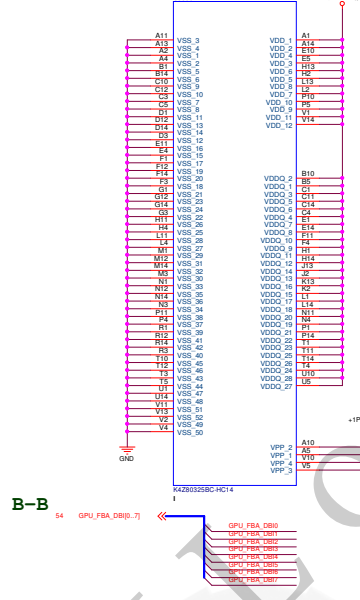
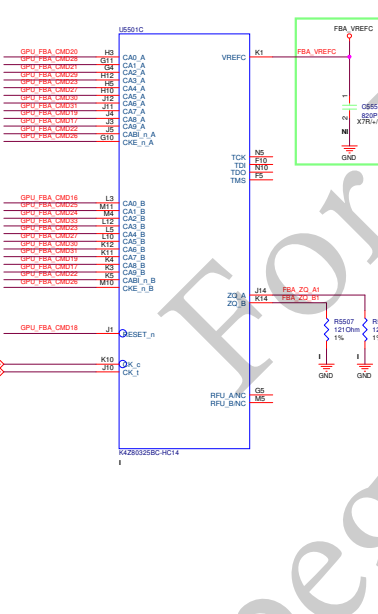
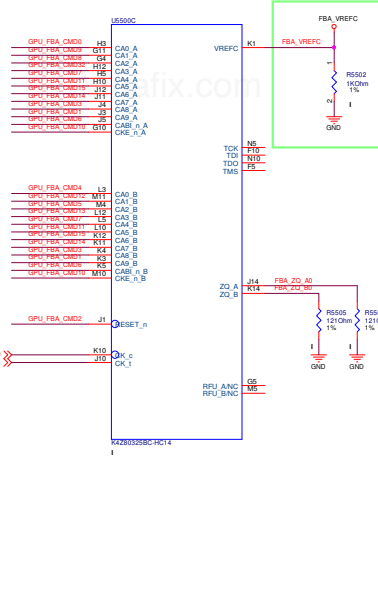
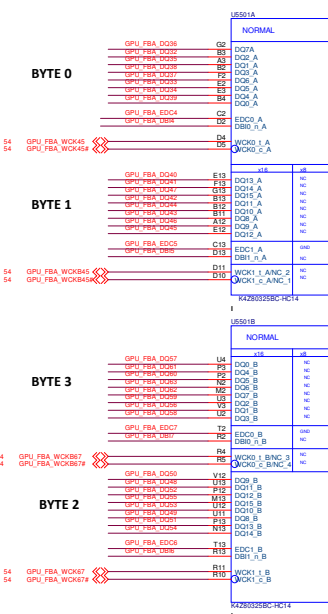
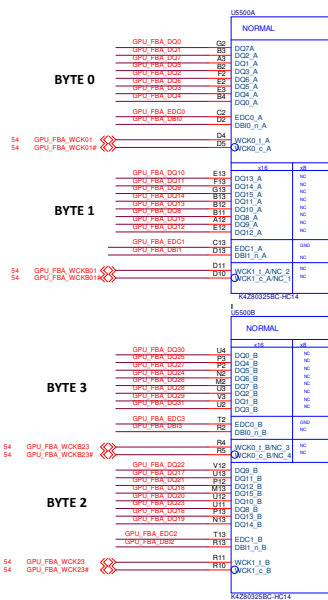
Memory Density	Allowed Memory Configuration	FBVDD/Q	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed Grade	Date Code Alert	Qual Plan	Status
8 Gb	2Chx256Mx16	1.25V and 1.35V <sup>2</sup>	Micron	MT61K256M32JE-14:A	A-die	0x1	14 Gbps	N/A	Full	Production candidate
			Samsung	K4Z80325BC-HC14	C-die	0x0	14 Gbps	N/A	Full	Production candidate
			Hynix	H56C8H24MJR-S2C	M-die	0x2	14 Gbps	N/A	Full	Production candidate

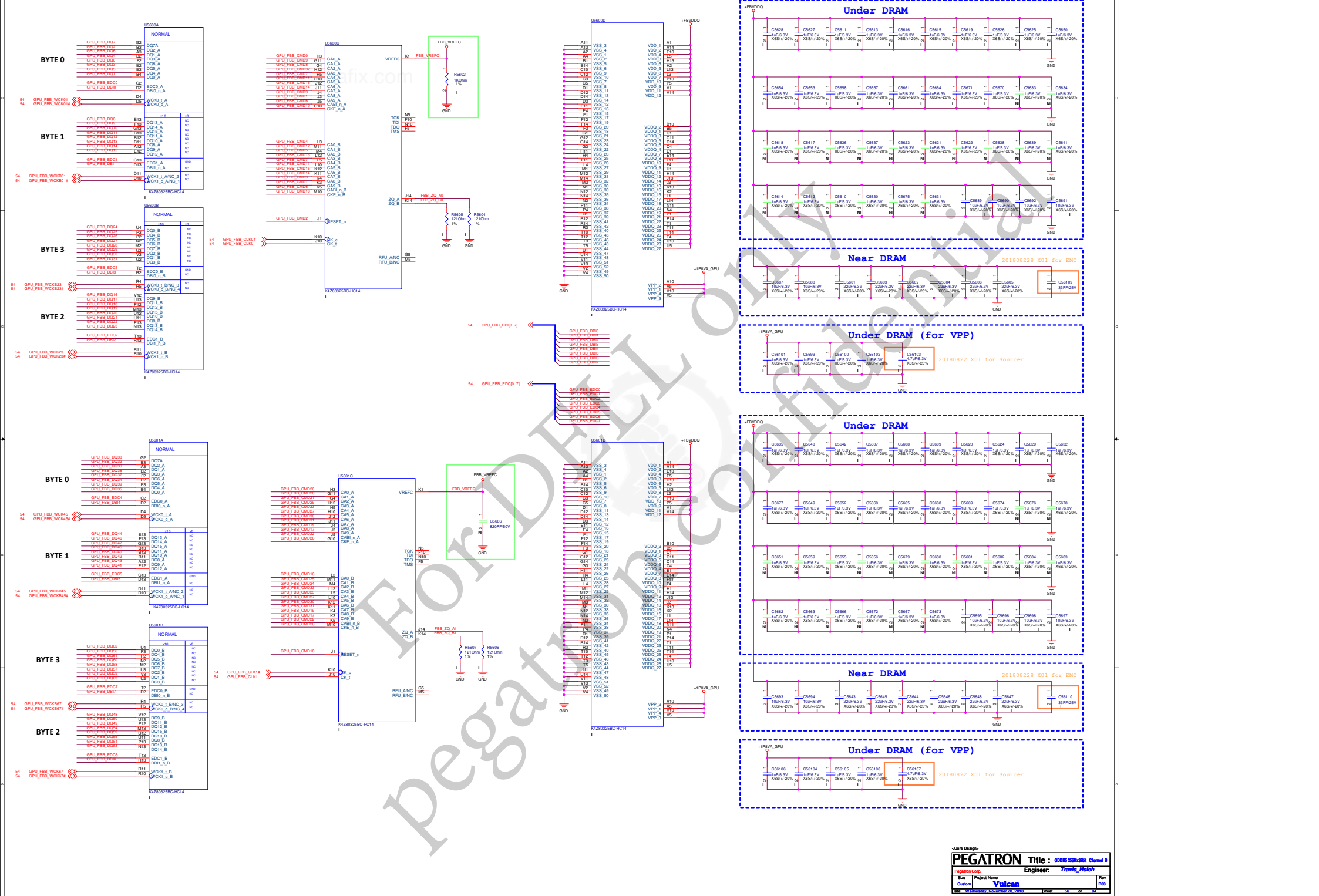
Notes:  
1. For N18E-G2, the maximum allowable memory case temperature is 95 °C.  
2. DVS is required. WCK: TBD

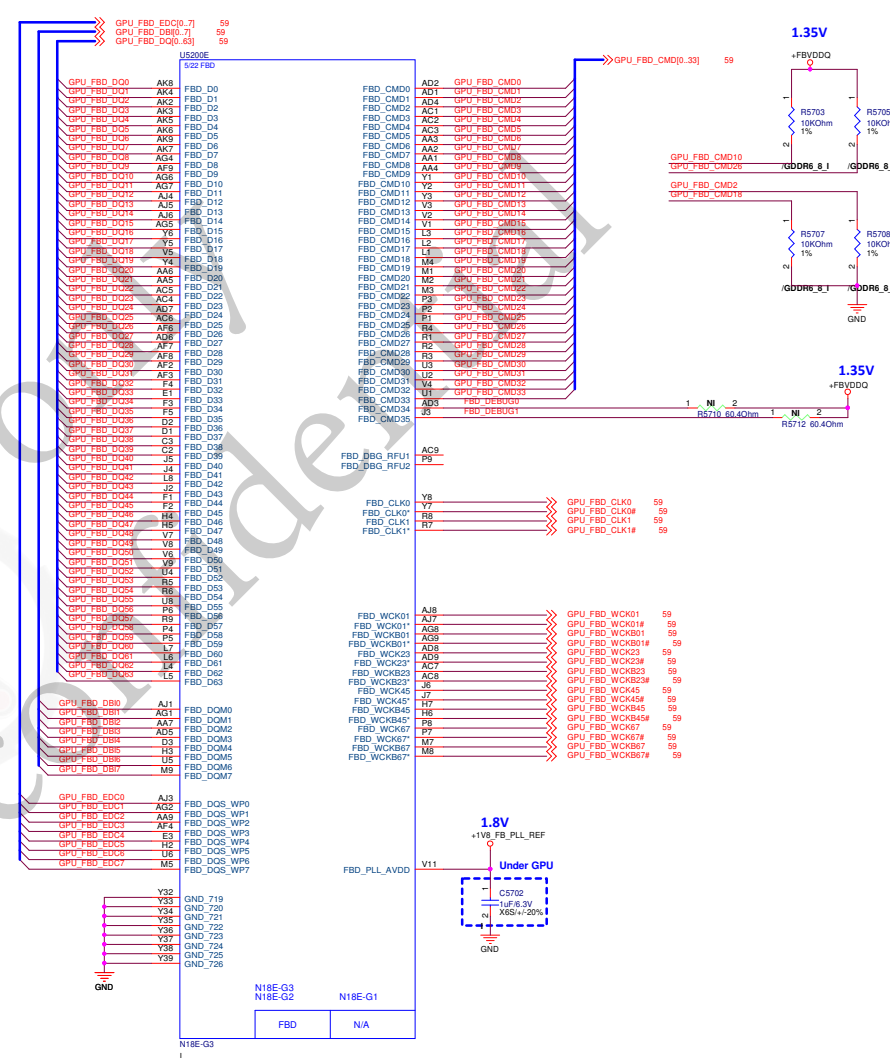


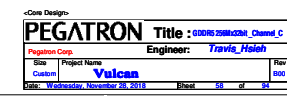


CELL1 TOP X32 MODE



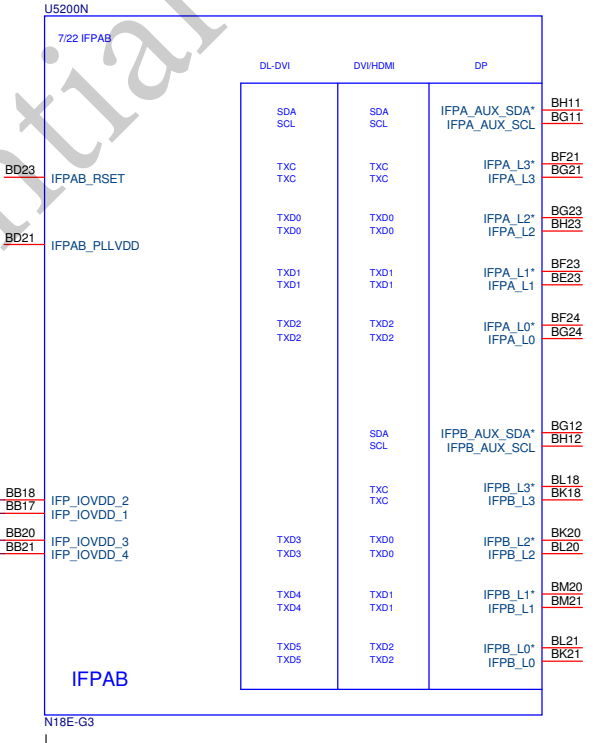
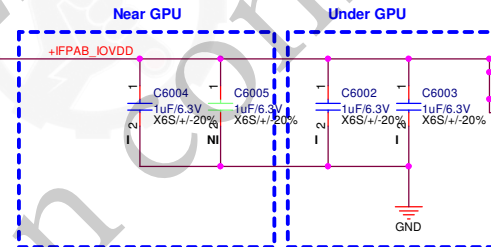
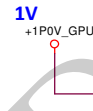
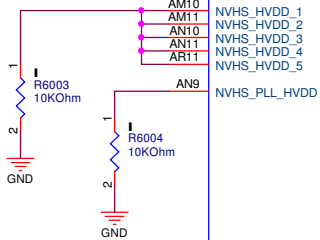












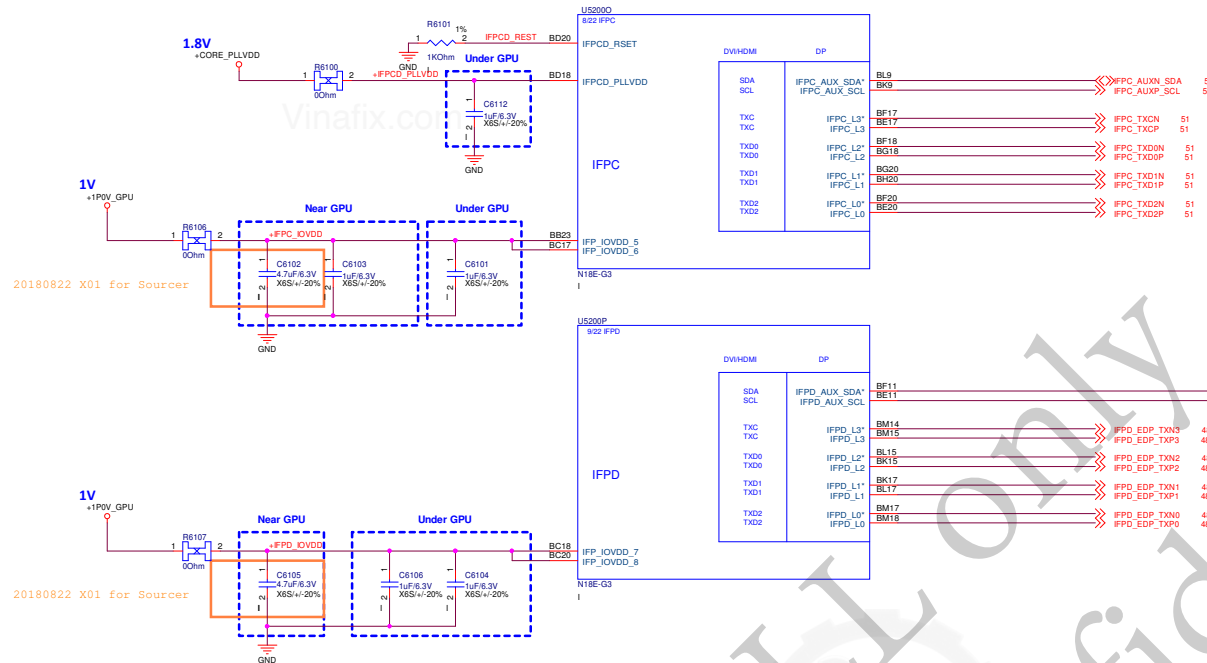


Table 9.6 HDMI Power Rails

Power Rails	Voltage	Maximum Current Draw
IFP_IOVDD	1.0 V ± 5%	~87 mA
IFPAB_PLLVDD	1.8 V ± 10%	~98 mA
IFPCD_PLLVDD	1.8 V ± 10%	~98 mA
IFPEF_PLLVDD	1.8 V ± 10%	~98 mA

TO HDMI

TO eDP

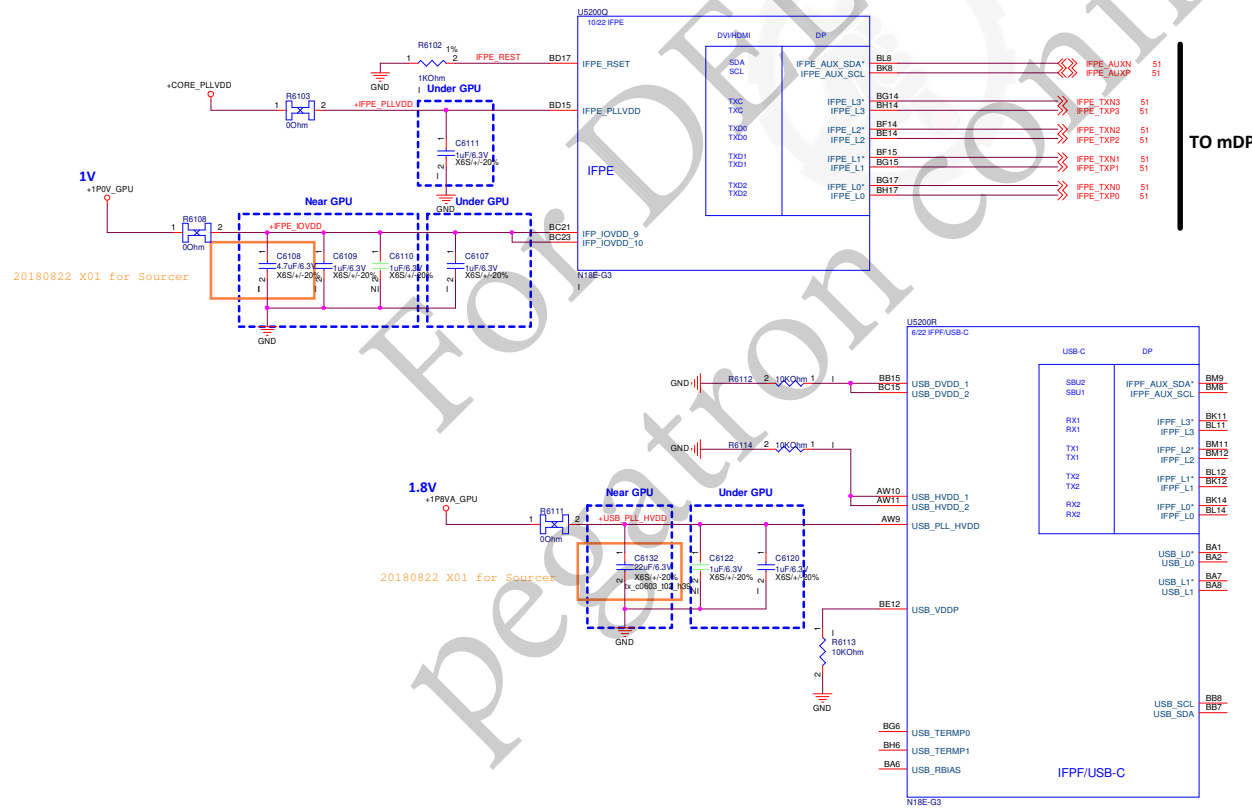


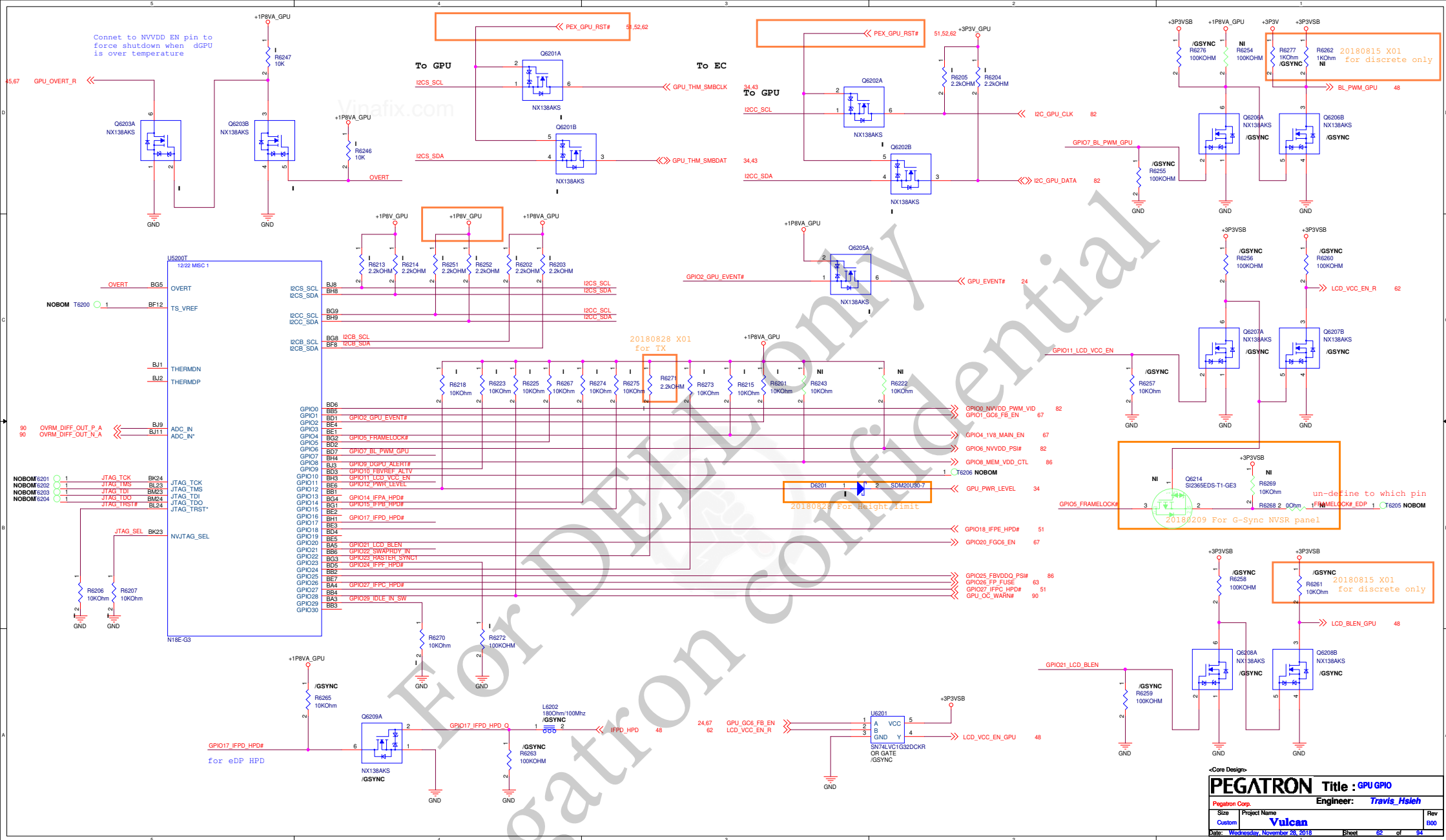
Table 9.11 DP Power Rails

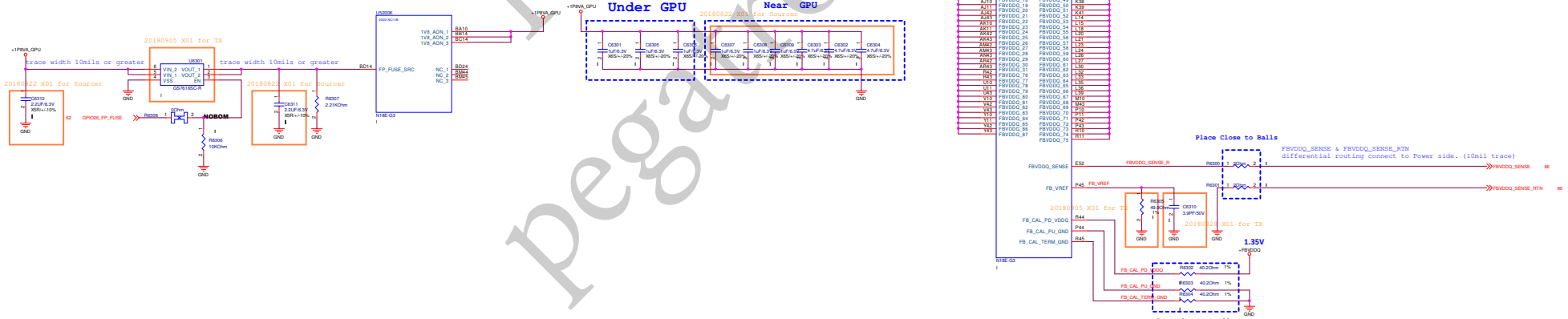
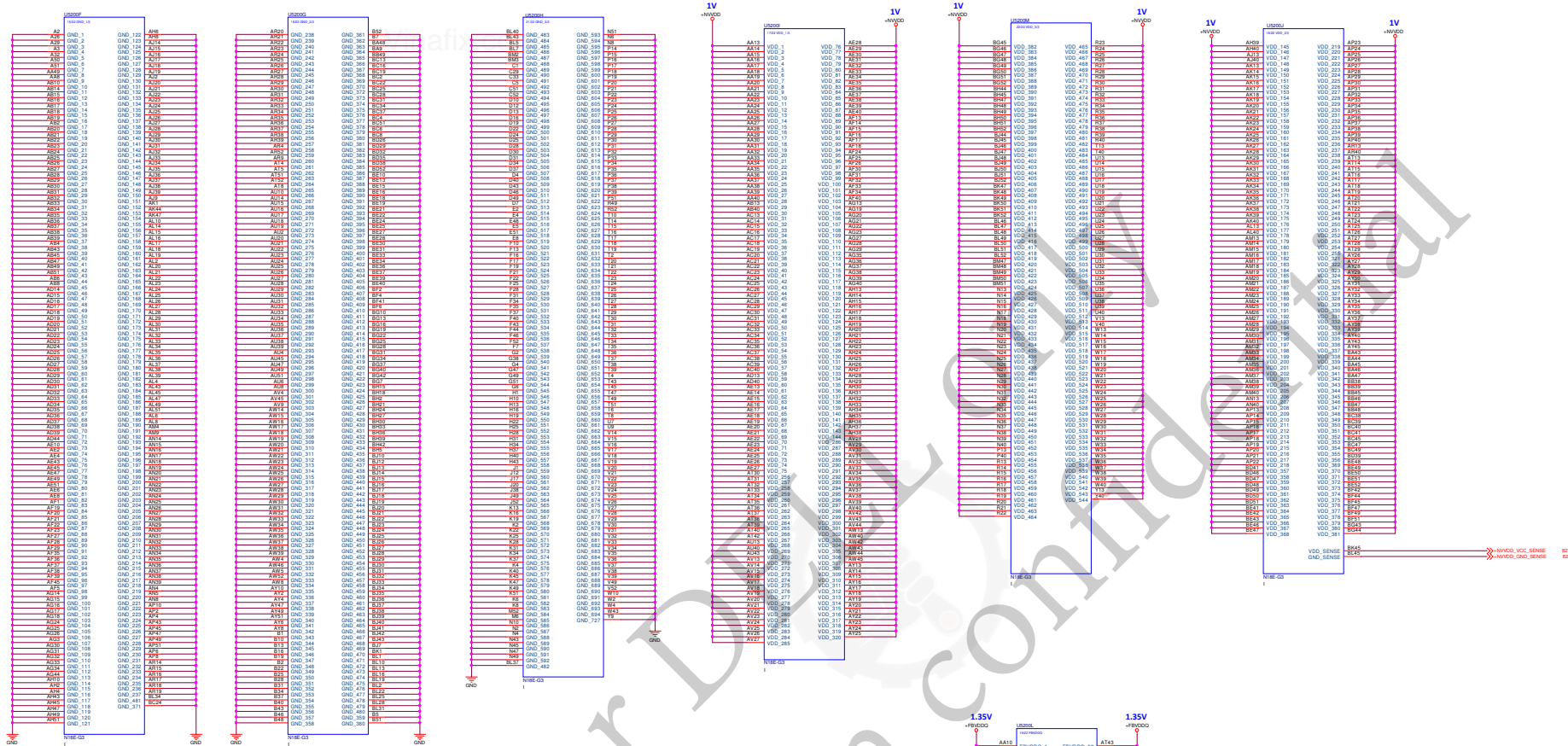
Power Rails	Voltage	Maximum Current Draw
IFP_IOVDD	1.0 V ± 5%	~118 mA
IFPAB_PLLVDD	1V8 V ± 10%	~102 mA
IFPCD_PLLVDD	1V8 V ± 10%	~102 mA
IFPEF_PLLVDD	1V8 V ± 10%	~102 mA

TO mDP

Core Design





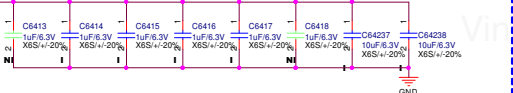


+FBVDDQ

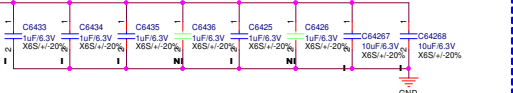
+NVVDD

Under GPU

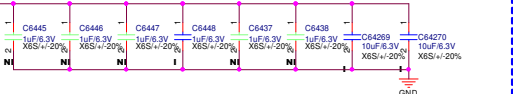
Partition A



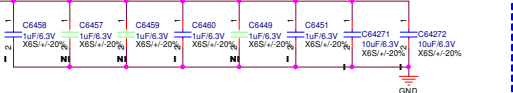
Partition B



Partition C



Partition D



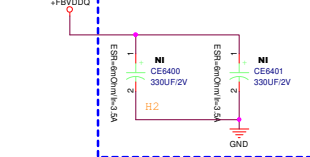
Partition E



Near GPU

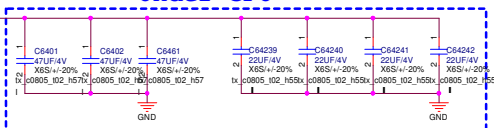
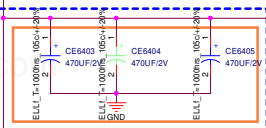


Close to GDDR

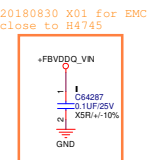
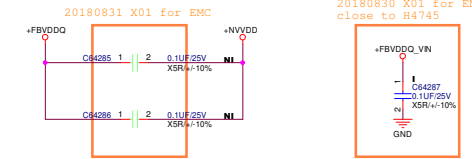
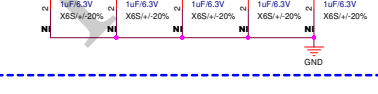
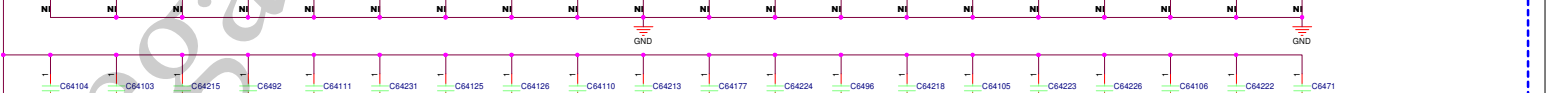
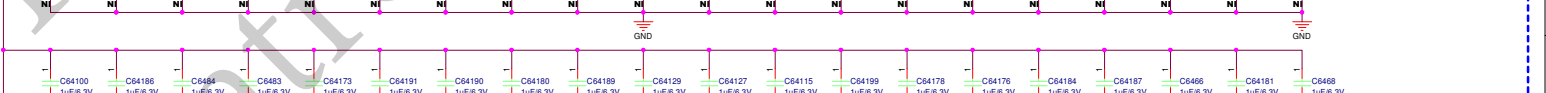
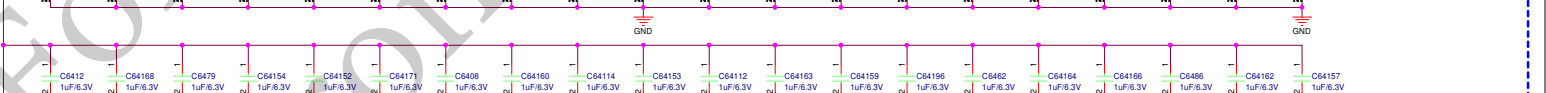
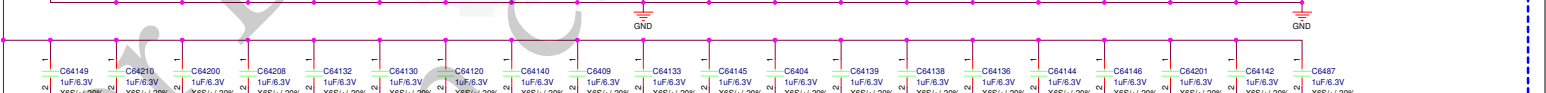
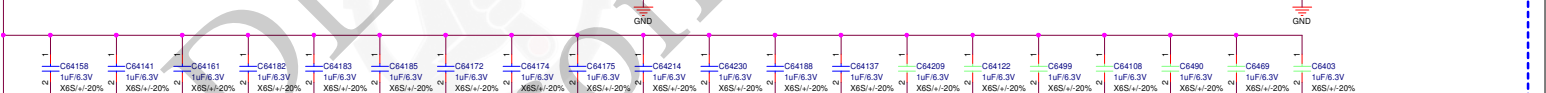
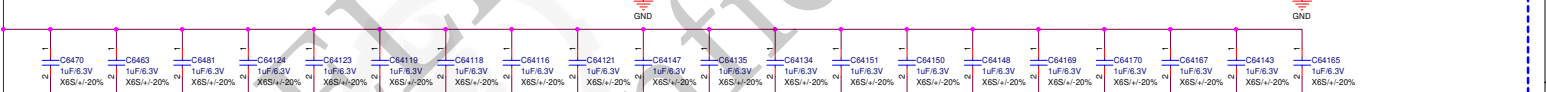
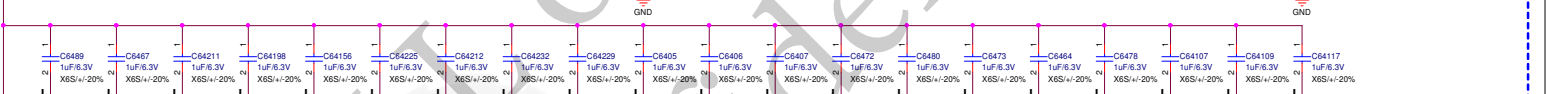
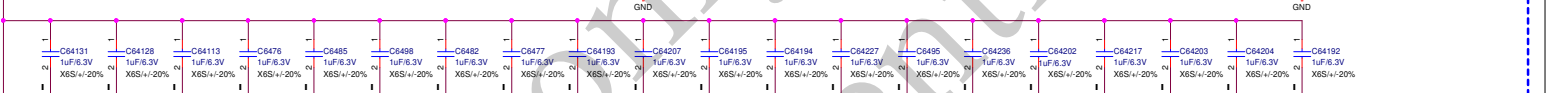
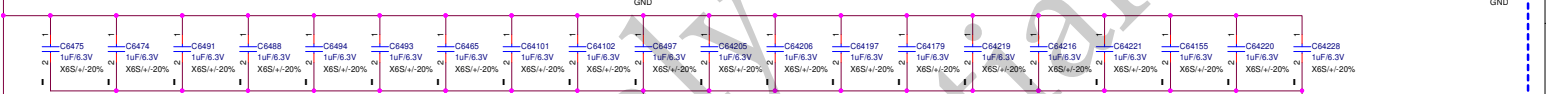
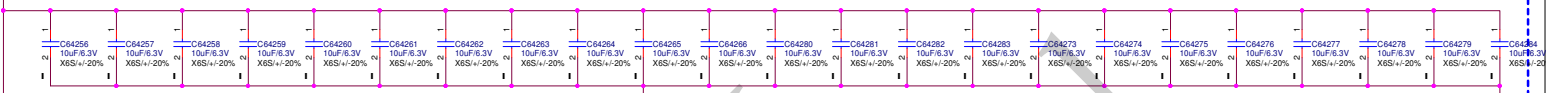


Under GPU

Near GPU



Under GPU



Vinafix.com

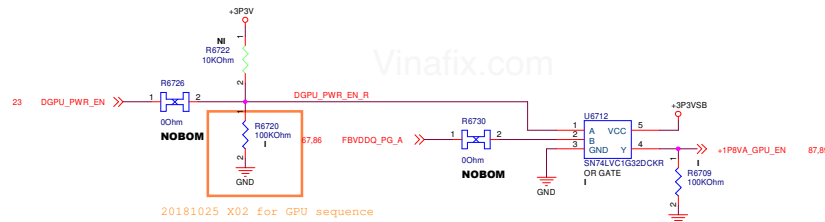
For DELL only  
pegatron confidential

<b>PEGATRON</b>		Title : TYPE-C_PD	
Pegatron Corp.		Engineer: <u>Travis_Hsieh</u>	
Size C	Project Name <b>Vulcan</b>	Rev 800	
Date: Wednesday, November 28, 2018		Sheet	65 of 84

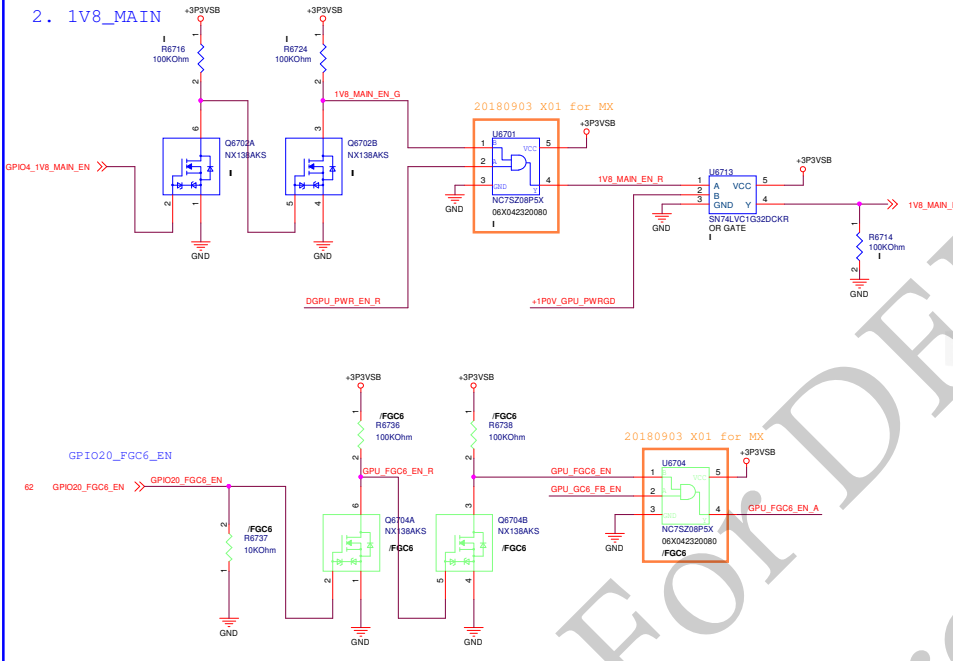
Vinafix.com

For DELL only  
pegatron confidential

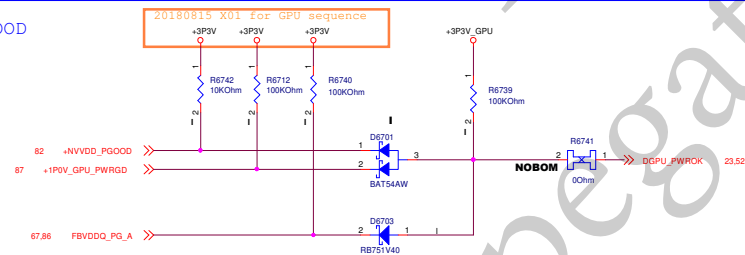
## 1.1V8\_AON



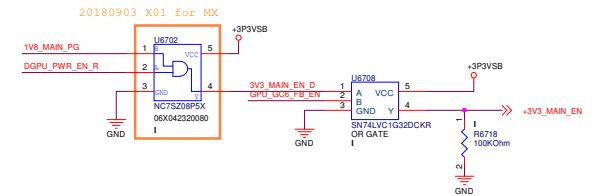
## 2.1V8\_MAIN



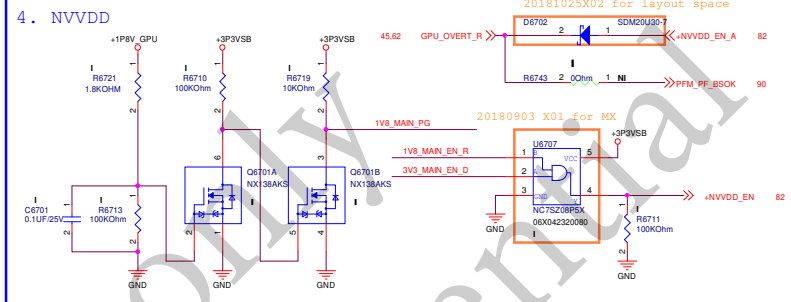
## POWER GOOD



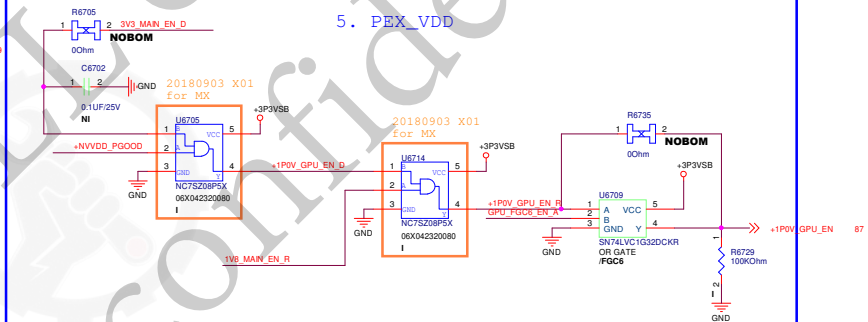
## 3.3V3\_MAIN



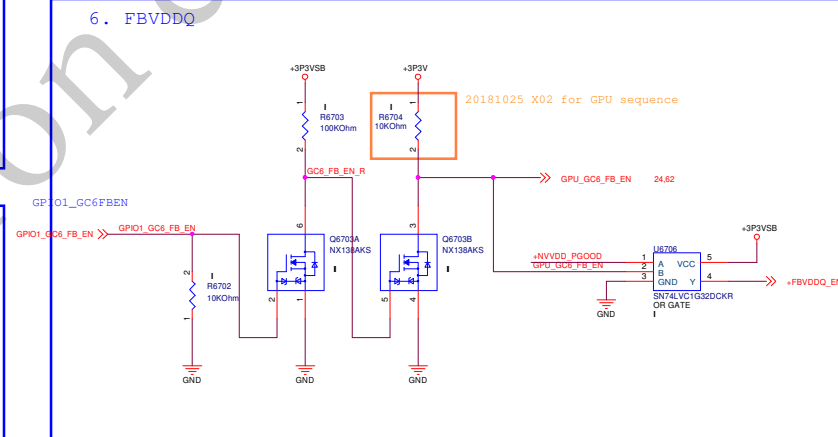
## 4.NVDD



## 5. PEX\_VDD



## 6. FBVDDQ

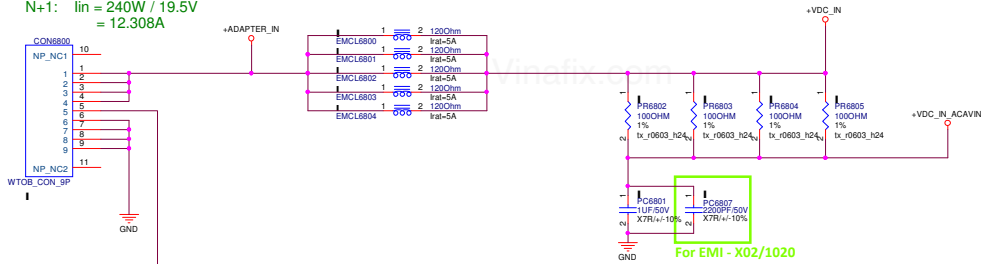


Core Design

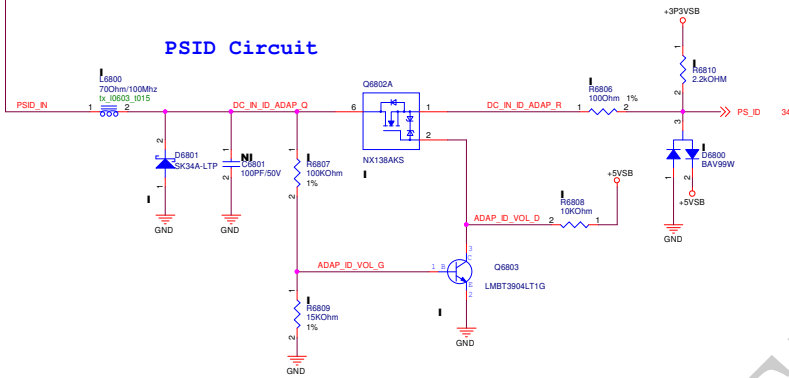
## DC-IN connector

N :  $I_{in} = 180W / 19.5V$   
 $= 9.231A$

N+1:  $I_{in} = 240W / 19.5V$   
 $= 12.308A$

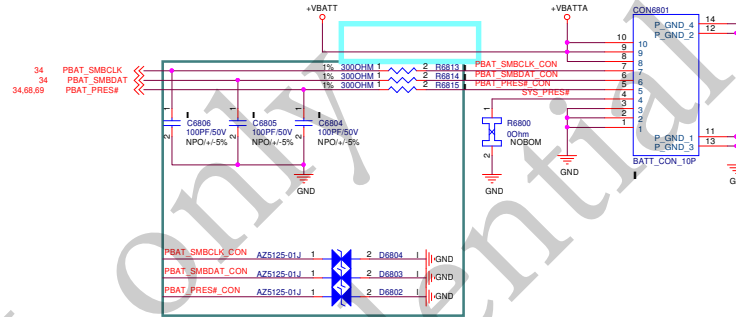


## PSID Circuit



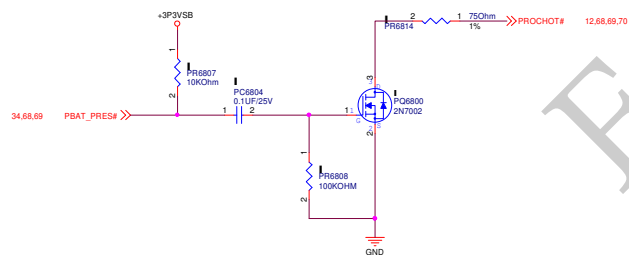
Remove JP6800 and JP6801

## Battery Pack connector

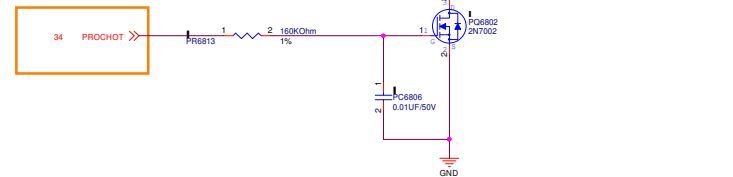
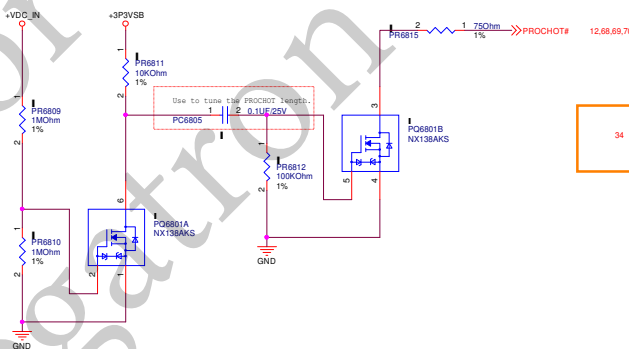


For Battery damage EC issue - X01/0824

## Adapter Protection Circuit

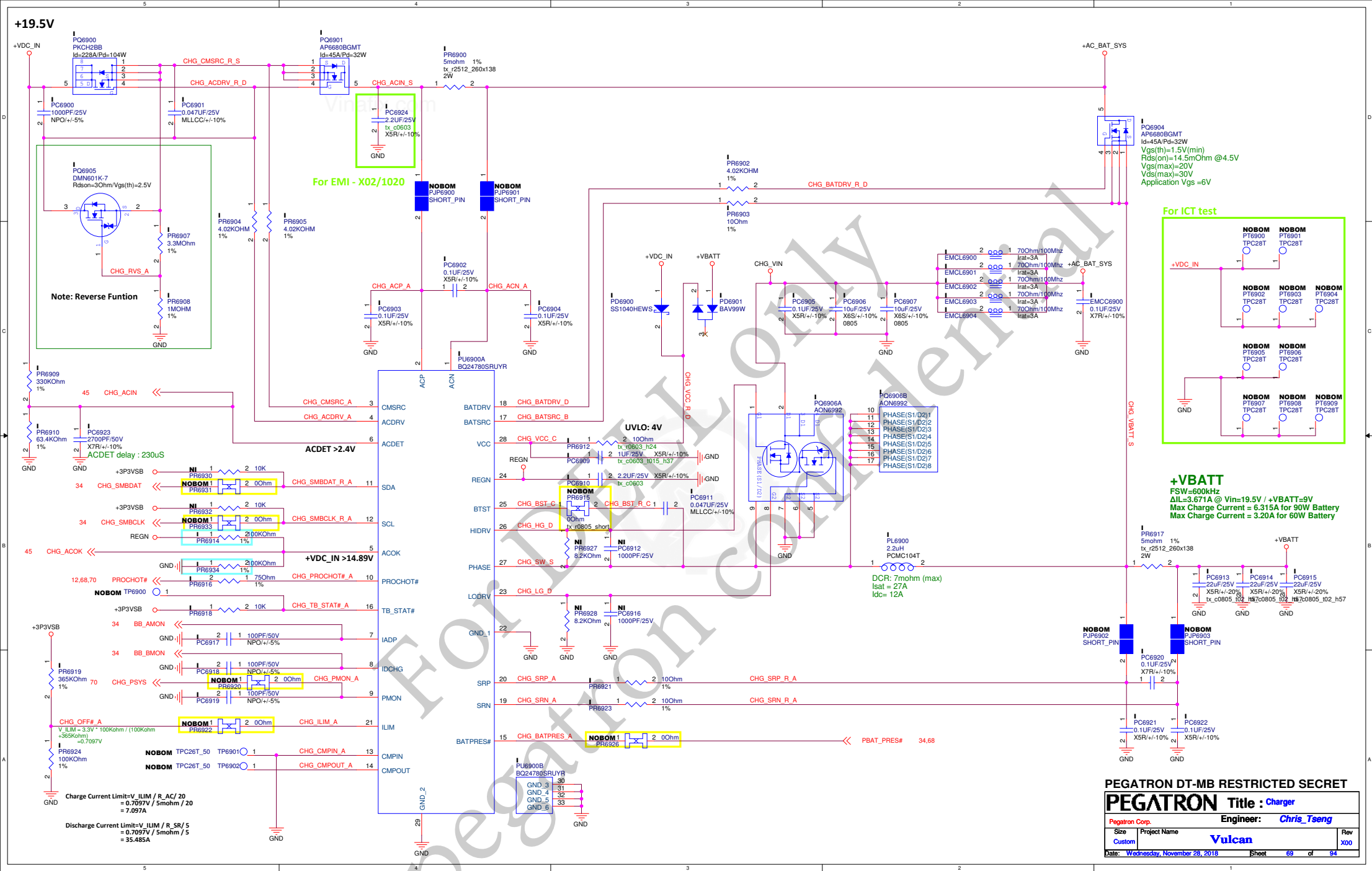


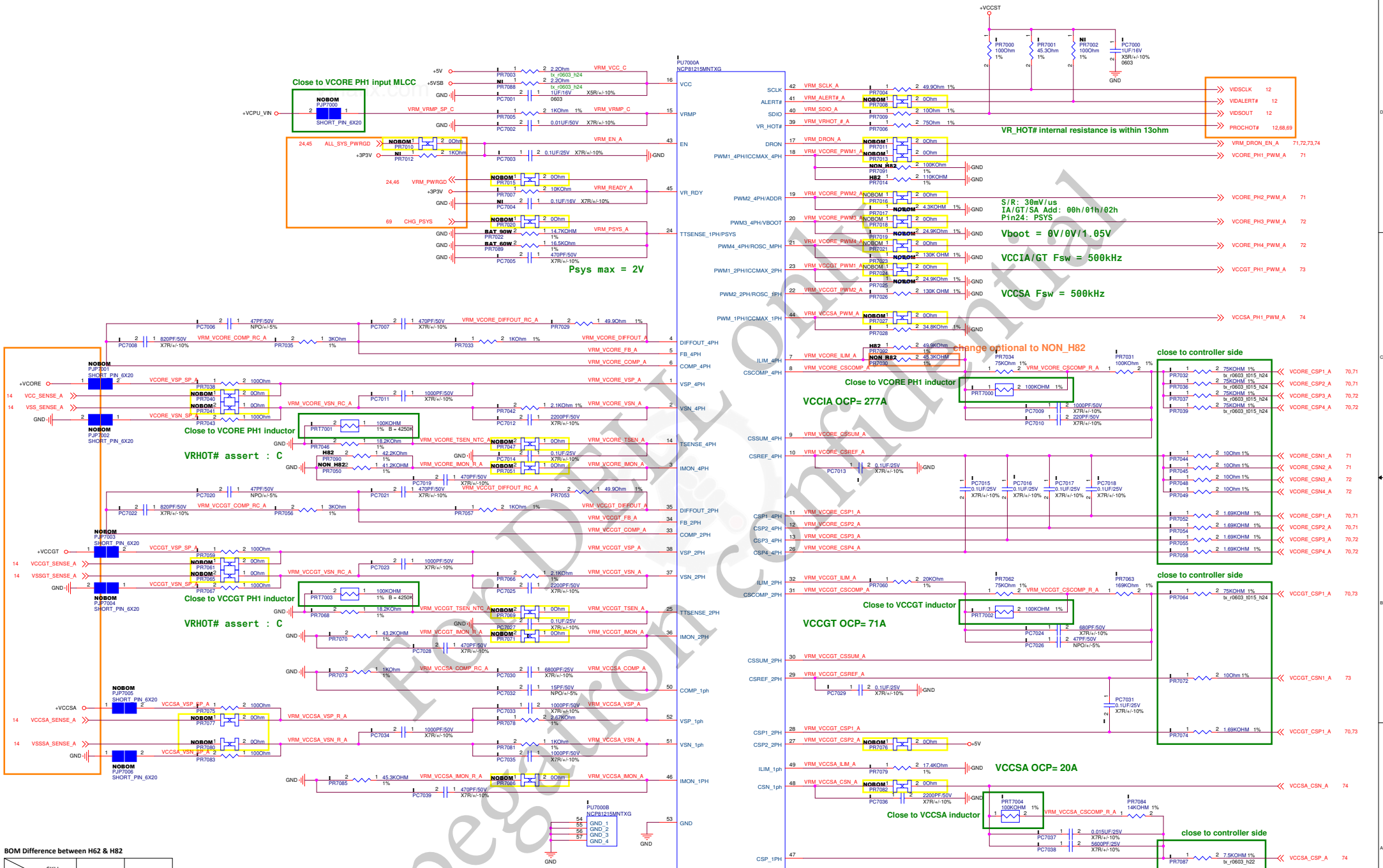
## Battery Protection Circuit





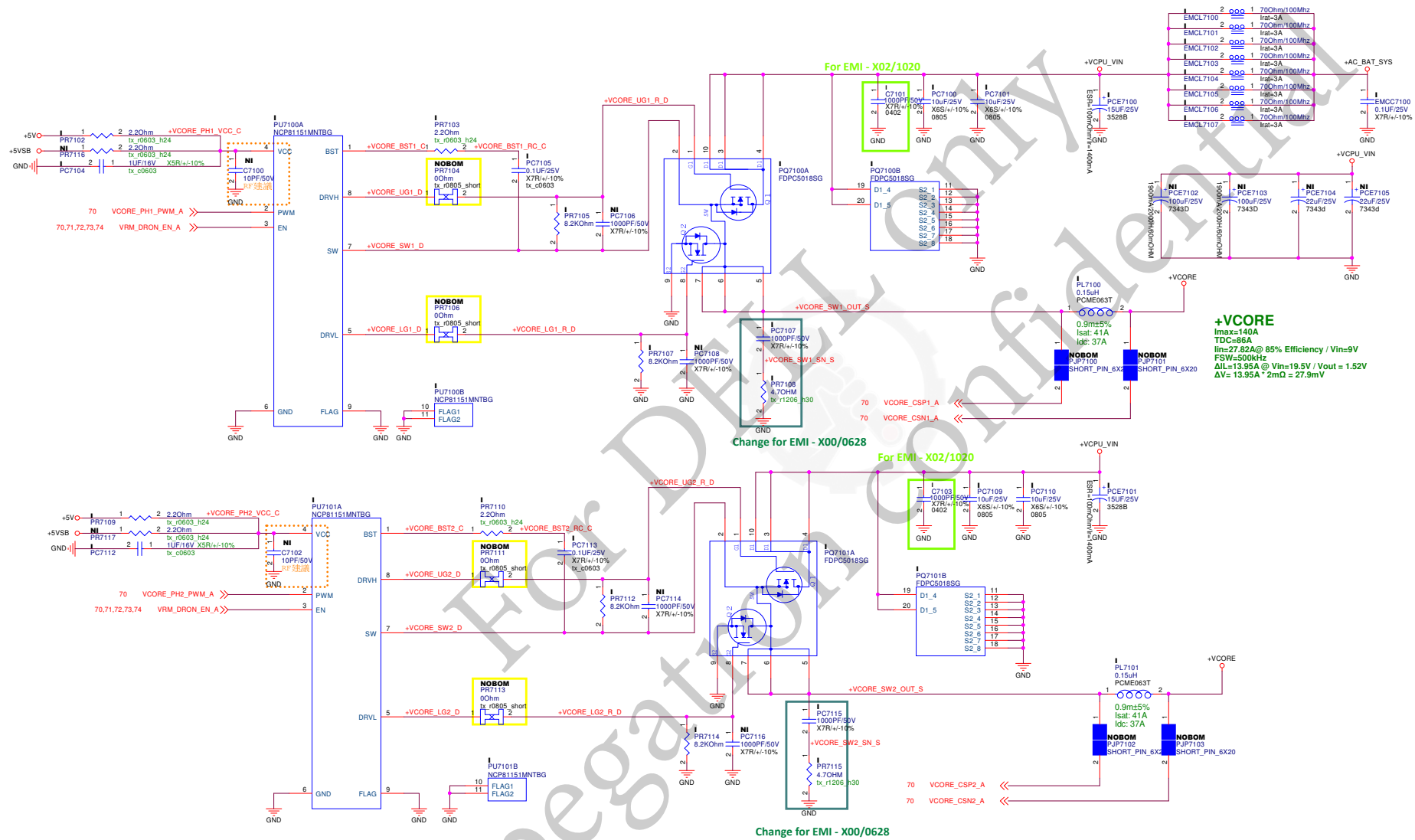
+VDC\_IN





BOM Difference between H62 & H82

SKU	H62	H82
Part Reference		
PR7050 / PR7090	41.2KΩ	42.2KΩ
PR7014 / PR7091	110KΩ	100KΩ
PR7030 / PR7092	45.3KΩ (OCP = 252A)	49.9KΩ (OCP = 277A)



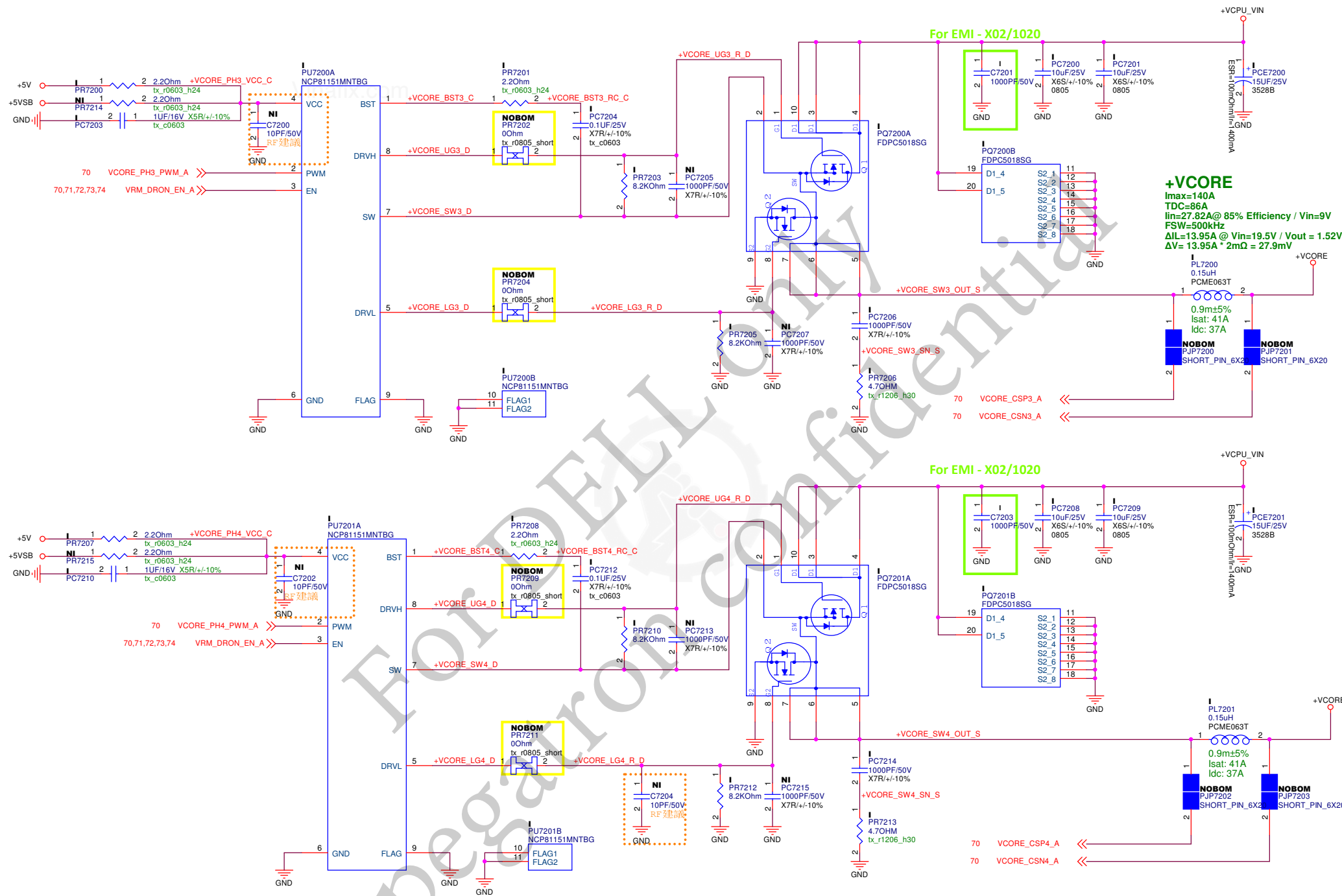
PEGATRON DT-MB RESTRICTED SECRET

**PEGATRON** Title : Vcore Driver-1

Pegatron Corp. Engineer: Chris Tseng

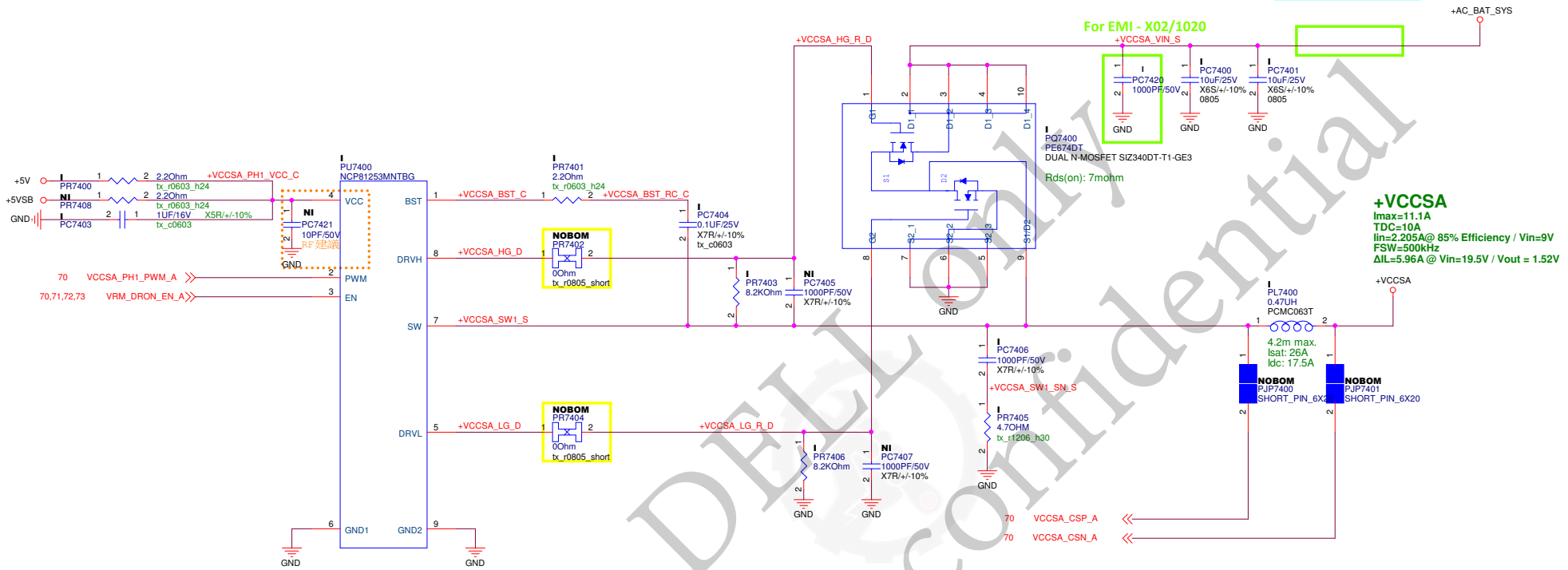
Size Project Name Custom Vulcan

Date: Wednesday, November 28, 2018 Sheet 71 of 84



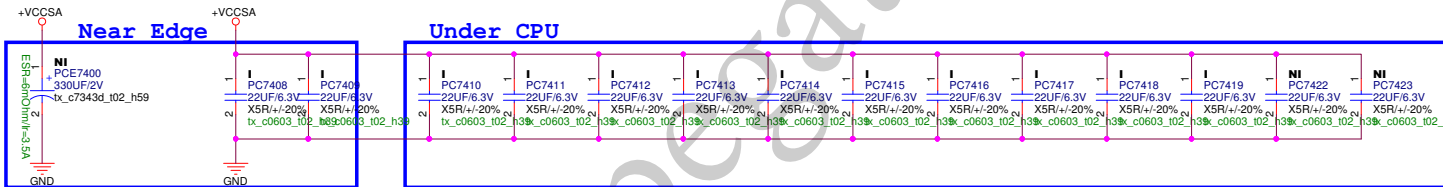


Remove PJP7402 and PJP7403



OWNER	+VCCSA OC Point	Low Limit	High Limit
Atticus	18.96A @ DCR=4.2mΩ (Worst) 19.91A @ DCR=4mΩ (Typ.)	12.95A	L= 0.3uH @ 27A
Terry	18.96A @ DCR=4.2mΩ (Worst) 19.91A @ DCR=4mΩ (Typ.)	12.95A	L= 0.3uH @ 27A

$$I_{Low\ Limit} = I_{DVID} + I_{o\_Cont} = 5A + (30mV/\mu S) * 265\mu F = 12.95A$$



**VCCSA Output CAP**  
 330uF/2V/H=2mm \* 1(NI)  
 22uF/6.3V \* 12 (I)  
 22uF/6.3V \* 2 (NI)

PEGATRON DT-MB RESTRICTED SECRET

**PEGATRON** Title : VccSA Driver

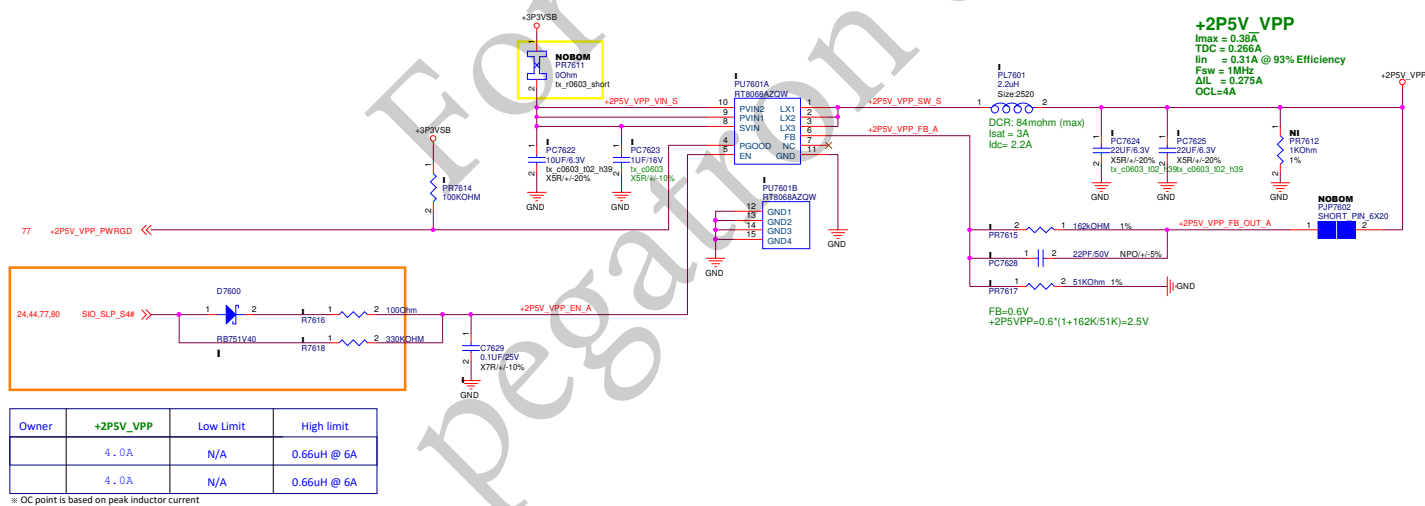
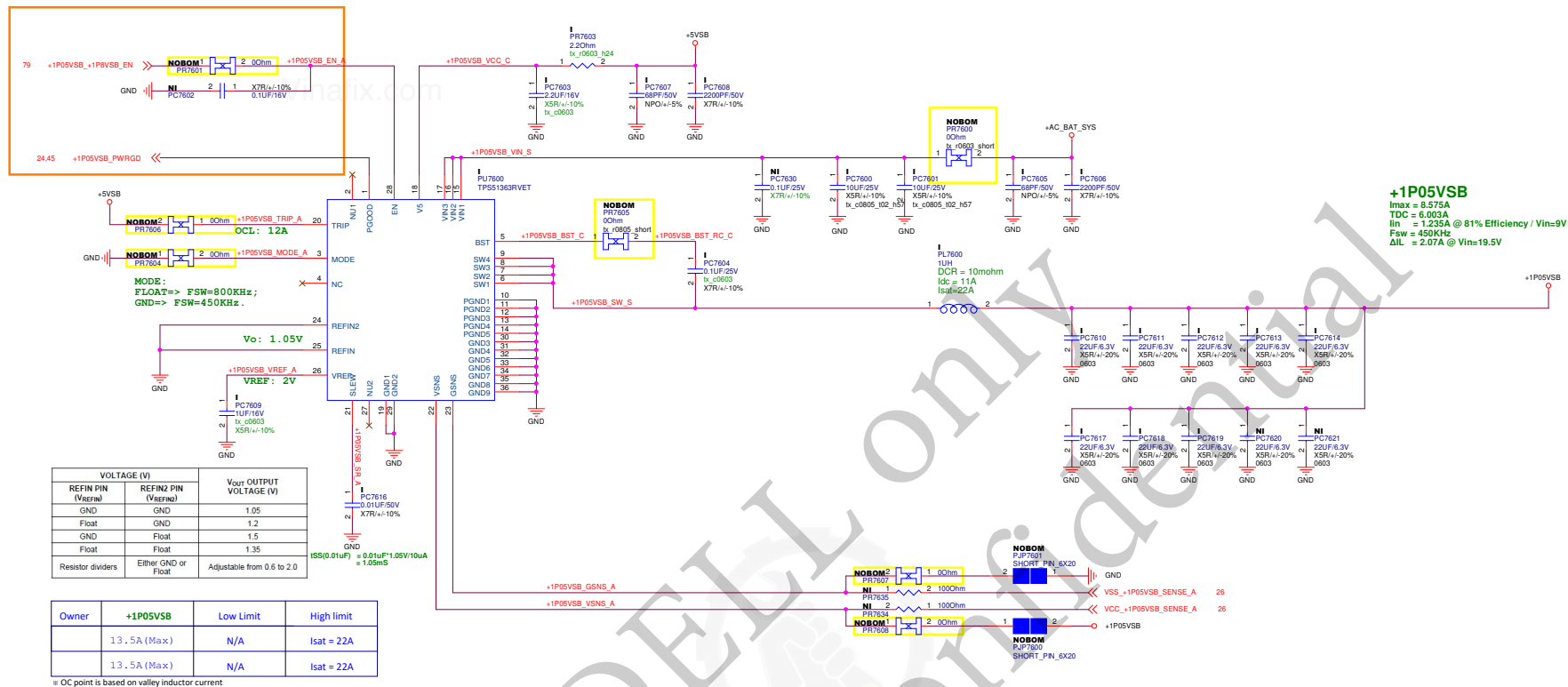
Pegatron Corp. Engineer: Chris\_Tseng

Size Project Name Custom Vulcan Rev X00

Date: Wednesday, November 28, 2018 Sheet 74 of 94







Remove PJP7704 and PJP7705

**+1P2V\_DUAL**  
 Imax=8.44A  
 TDC=5.906A  
 Iin=1.324A @ 85% Efficiency / Vin=9V  
 FSW=300kHz  
 AIL=2.503A @ Vin=19.5V  
 ΔV=22.53mV  
 H/S=0.638W  
 L/S=0.196W

**+VTT\_DDR**  
 Imax: 0.6A  
 TDC: 0.42A

Change for power sequence - X00/0713

OC Point = Rrip\*10uA @LS\_Rds(on) +

0.5V

Mode (Tracking Discharge):

100Kohm~300KHz

200Kohm~400KHz

ExtReference Vref2

DAC

VREF2:

5V/2.43K(7.68K+2.43K)=1.202V

RDS(ON)=2.5mΩ(25℃) - ADN6992  
 RDS(ON)=3.5mΩ(105℃) - ADN6992

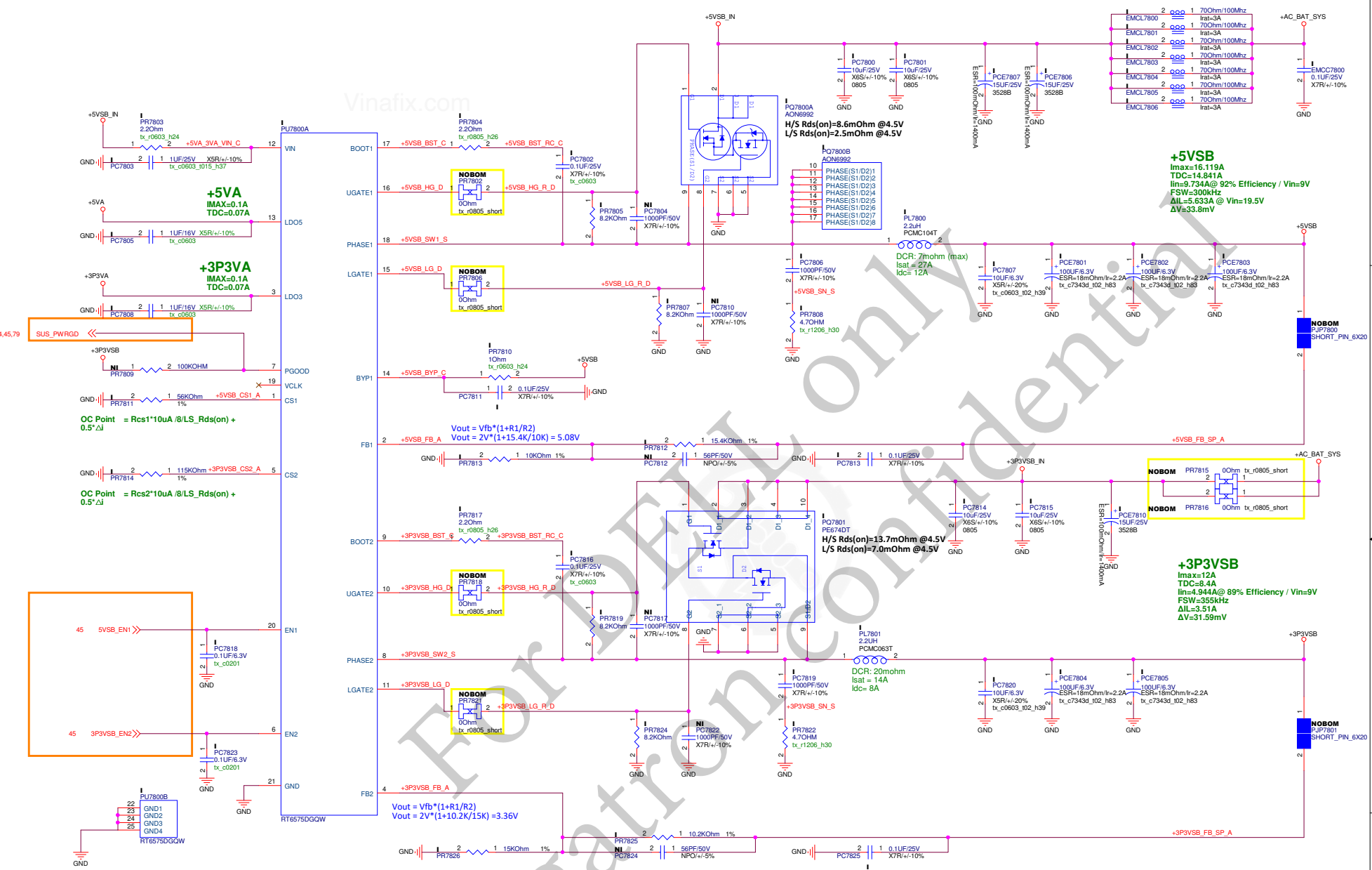
Owner	+5VSB OC point	Low Limit	High limit
Atticus	21.35A @25℃	N/A	0.7uH @ 26A
Terry	21.35A @25℃	N/A	0.7uH @ 26A

RDS(ON)=2.2mΩ(25℃) - SIZ9800T  
 RDS(ON)=3.0mΩ(105℃) - SIZ9800T

Owner	+5VSB OC point	Low Limit	High limit
Atticus	24.09A @25℃	N/A	0.7uH @ 26A
Terry	24.09A @25℃	N/A	0.7uH @ 26A

&lt;Core Design&gt;

PEGATRON Title : +1P2V_DUAL & +VTTDDR		Engineer: Chris Tseng	
Size	Project Name	Rev	
Custom	Vulcan	X00	
Date: Wednesday, November 28, 2018	Sheet	77	of 94



RDS(ON)=2.5mΩ(25℃) -A0N6992  
RDS(ON)=3.5mΩ(105℃) -A0N6992

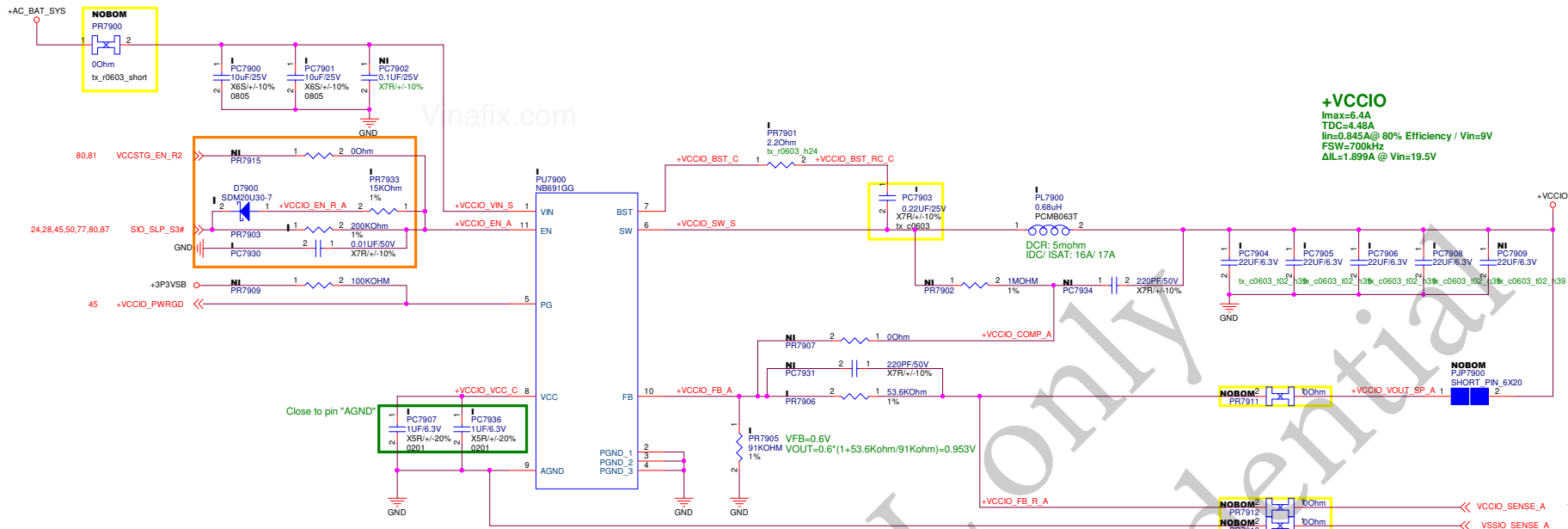
RDS(ON)=7.0mΩ(25℃) -S1Z340DT-T1-GE3  
RDS(ON)=9.8mΩ(105℃) -S1Z340DT-T1-GE3

RDS(ON)=2.2mΩ(25℃) -S1Z980DT  
RDS(ON)=3.08mΩ(105℃) -S1Z980DT

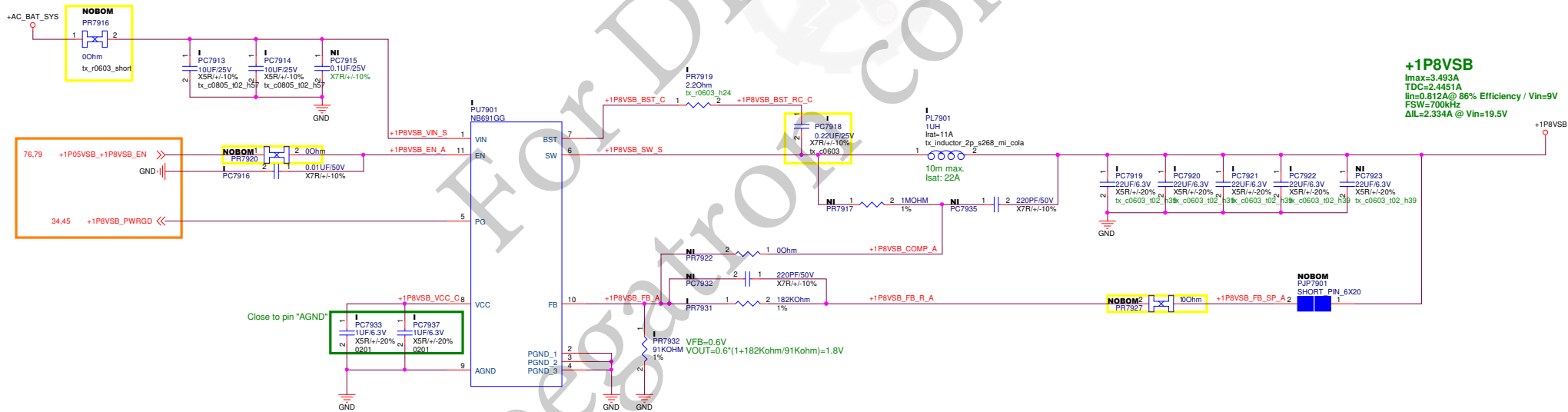
Owner	+5VSB OC point	Low Limit	High limit
	30.82A @25℃	N/A	1.6uH @ 36A
	22.82A @105℃	N/A	1.6uH @ 36A
	32.3165A @25℃	N/A	1.6uH @ 36A
	23.89A @105℃	N/A	1.6uH @ 36A

Owner	+3P3VSB OC point	Low Limit	High limit
	22.29A @25℃	N/A	1.5uH @ 23A
	16.463A @105℃	N/A	1.5uH @ 23A
	22.29A @25℃	N/A	1.5uH @ 23A
	16.463A @105℃	N/A	1.5uH @ 23A

Owner	+5VSB OC point	Low Limit	High limit
	34.63A @25℃	N/A	1.6uH @ 36A
	25.54A @105℃	N/A	1.6uH @ 36A
	34.63A @25℃	N/A	1.6uH @ 36A
	25.54A @105℃	N/A	1.6uH @ 36A



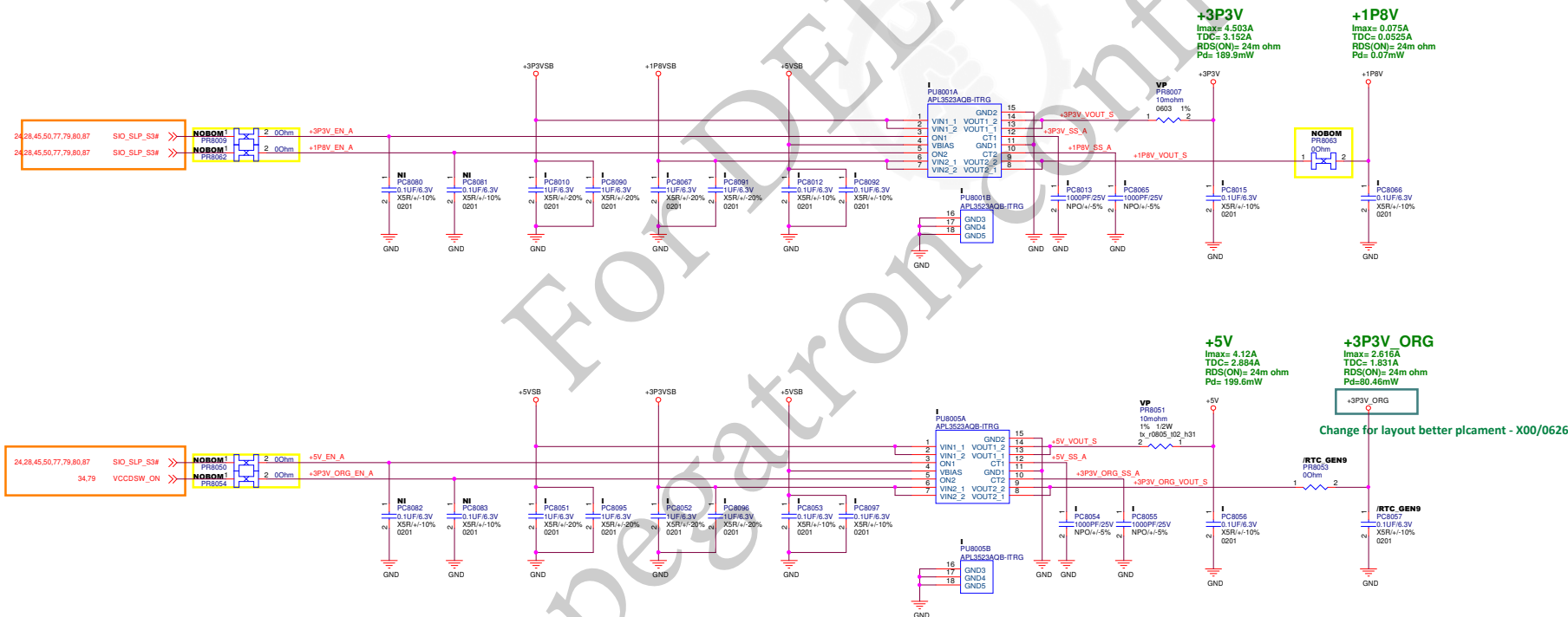
Owner	+VCCIO OC point (Valley point)	Low Limit	High limit
Atticus	7A (min.) 8A (max.)	N/A	$L_{Isat} = 17A$
Terry	7A (min.) 8A (max.)	N/A	$L_{Isat} = 17A$



Owner	+VCCIO OC point (Valley point)	Low Limit	High limit
Atticus	7A (min.) 8A (max.)	N/A	$L_{Isat} = 22A$
Terry	7A (min.) 8A (max.)	N/A	$L_{Isat} = 22A$

<Core Design>

PEGATRON Title : 79.+VCCIO/+1P8V			
Pegatron Corp.	Engineer: Chris Tseng		
Size	Project Name	Rev	
Custom	Vulcan	X00	
Date: Wednesday, November 28, 2018	Sheet	79	of 94

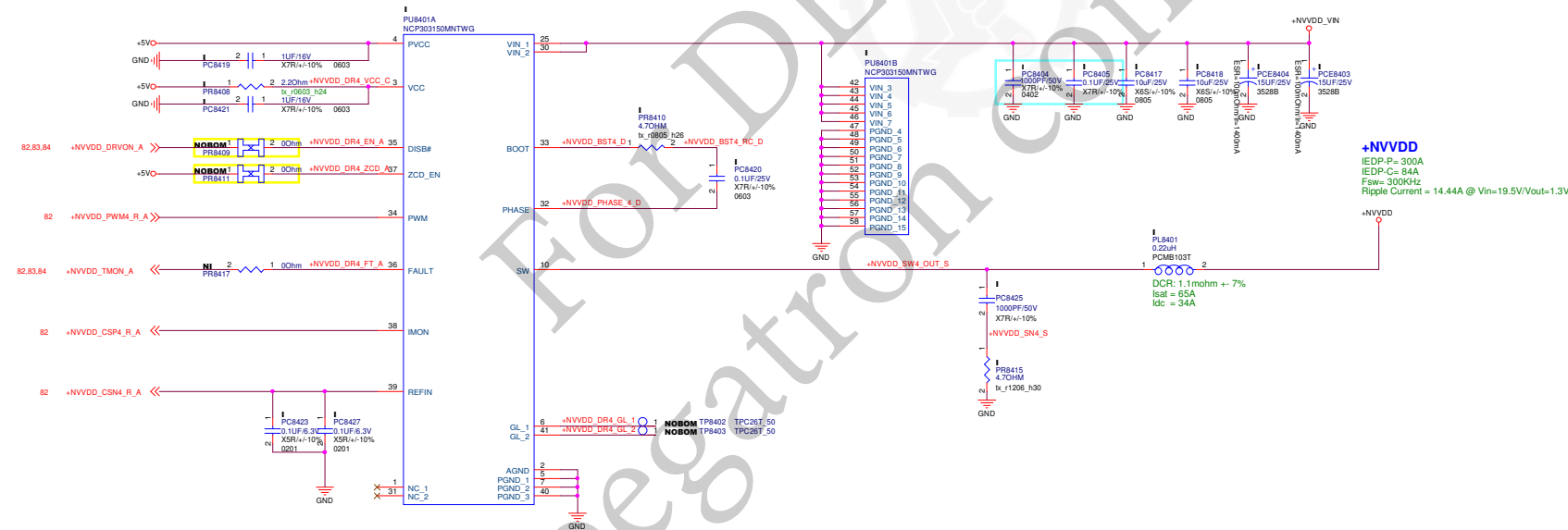
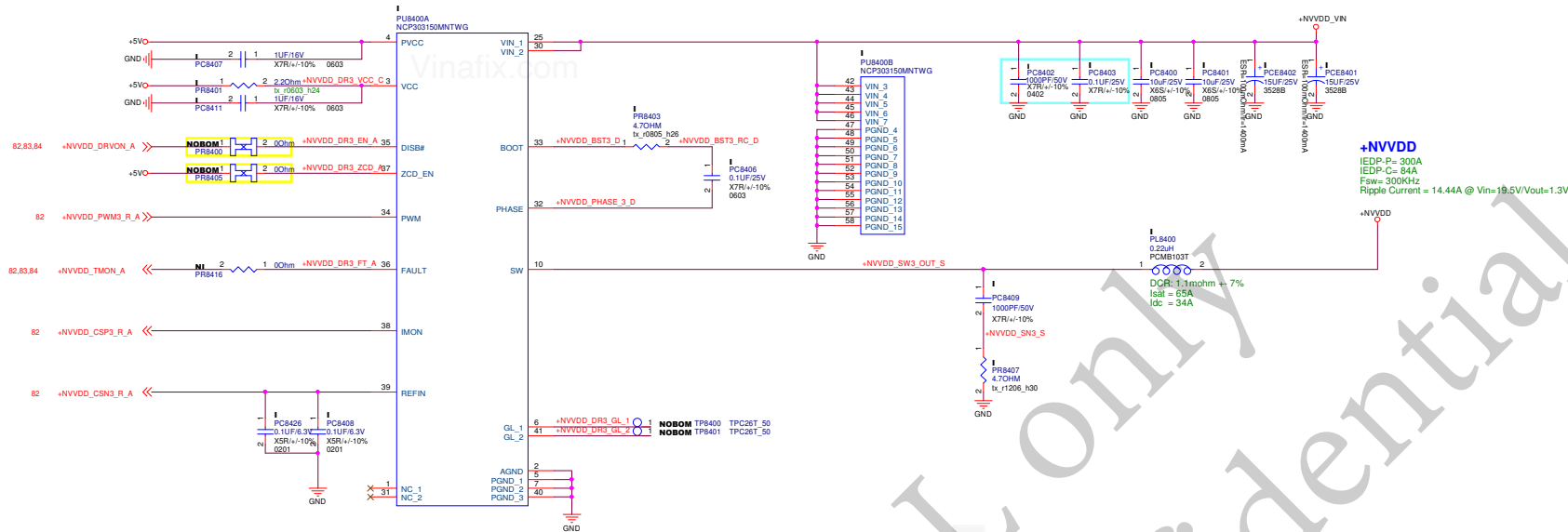












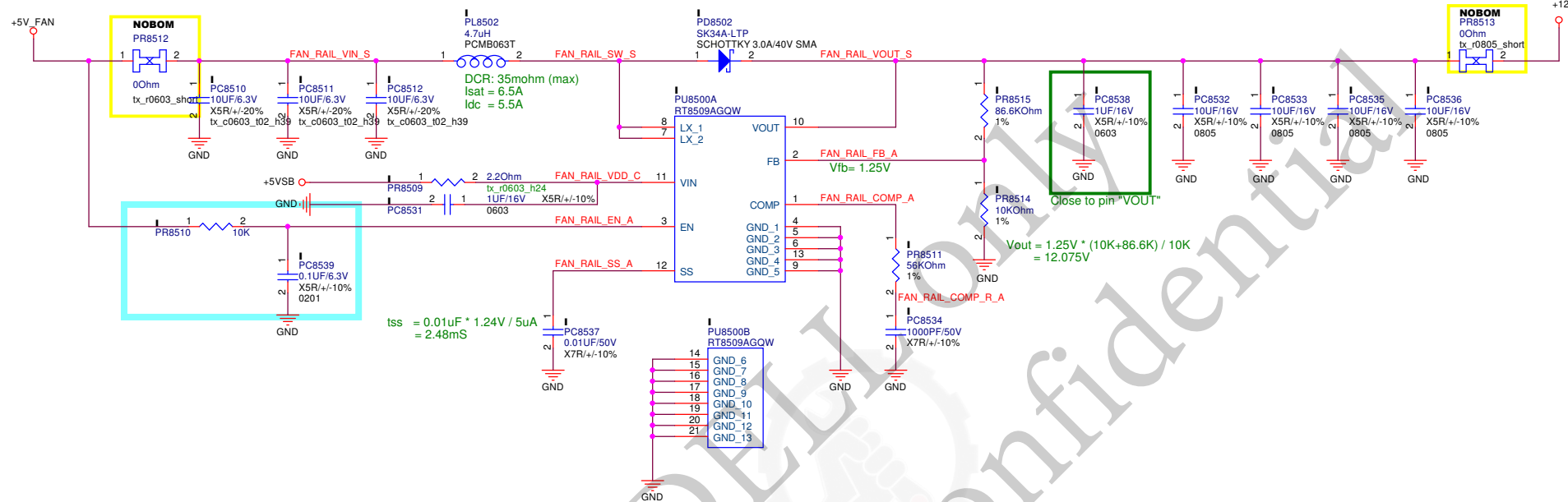
<Core Design>

**PEGATRON** Title : +NVVDD Driver-2

Pegatron Corp. Engineer: Chris Tseng

Size	Project Name	Rev
Custom	Vulcan	X00
Date: Wednesday, November 28, 2018		Sheet 84 of 94

**+12V**  
 $I_{max} = 0.8A$   
 $TDC = 0.8A$   
 $I_{in} = 2.259A @ 85\% \text{ Efficiency}$   
 $F_{sw} = 1.2MHz$   
 $\Delta I_L = 0.517A$



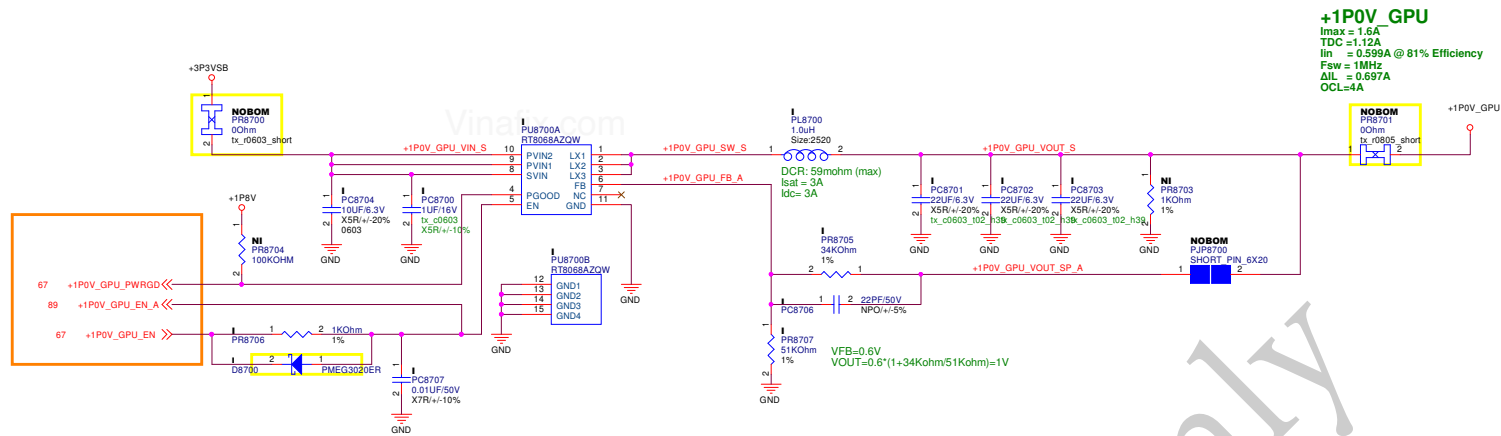
Owner	+12V OC point	Low Limit	High limit
	4.5A (Min) / 5.0A (Typ.)	N/A	3.25uH @ 8A
	4.5A (Min) / 5.0A (Typ.)	N/A	3.25uH @ 8A

※ OC point is based on peak inductor current

PEGATRON DT-MB RESTRICTED SECRET

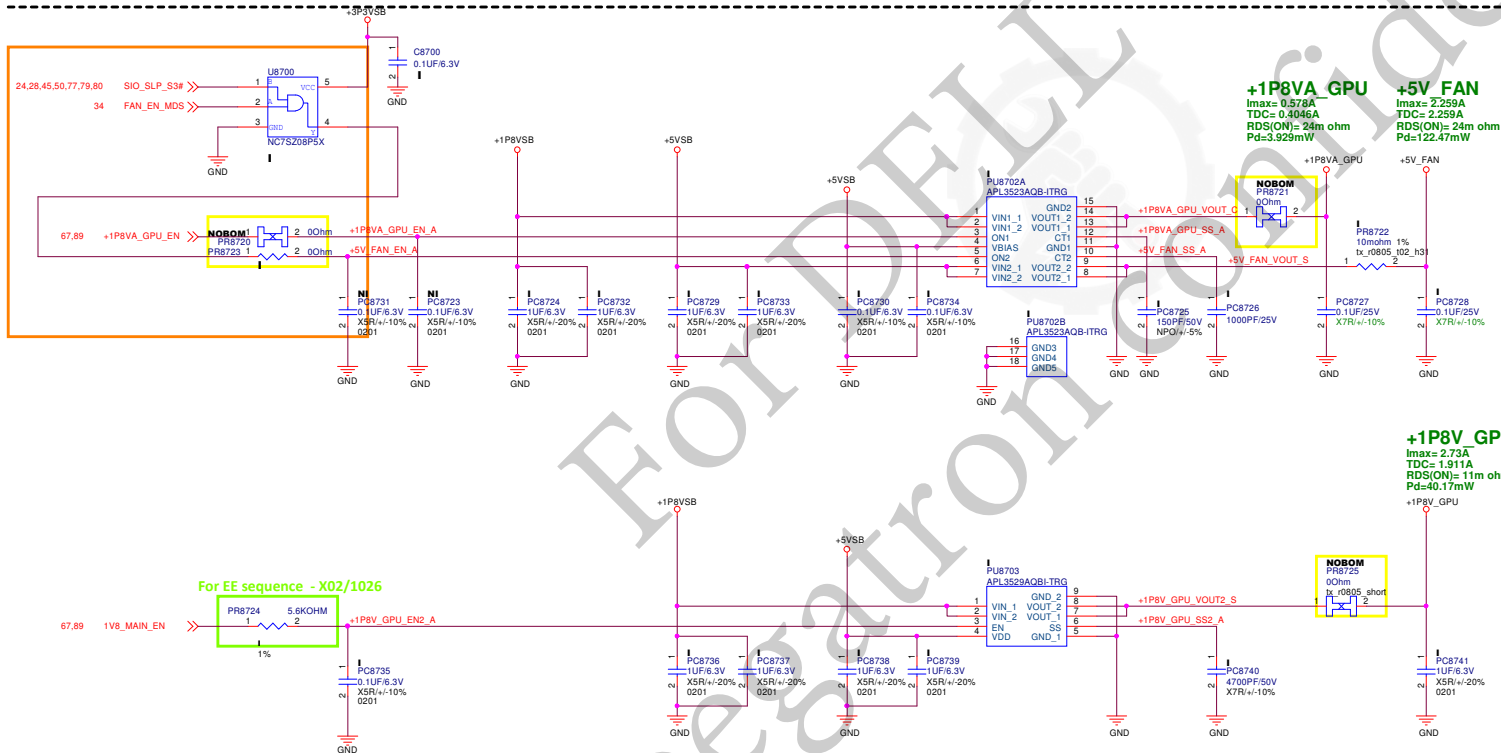
PEGATRON		Title : +12V
Pegatron Corp.		Engineer: Chris Tseng
Size	Project Name	Rev
Custom	Vulcan	X00
Date: Wednesday, November 28, 2018	Sheet 85 of 94	

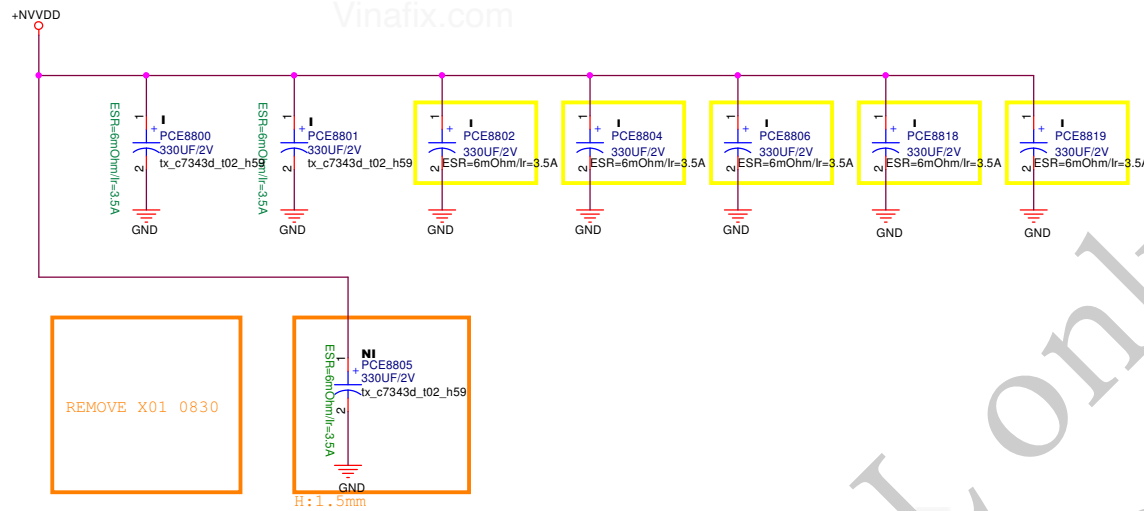




Owner	+1P0V_GPU	Low Limit	High limit
Atticus	4.0A	N/A	0.44uH @ 6A
Terry	4.0A	N/A	0.44uH @ 6A

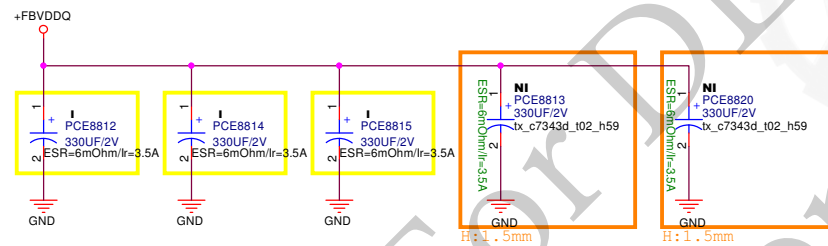
\* OC point is based on peak inductor current





### +NVVDD Output CAP(w/ +NVVDDS)

330uF/2V/H=2mm \* 7 (I)  
330uF/2V/H=1.5mm \* 2(NI)



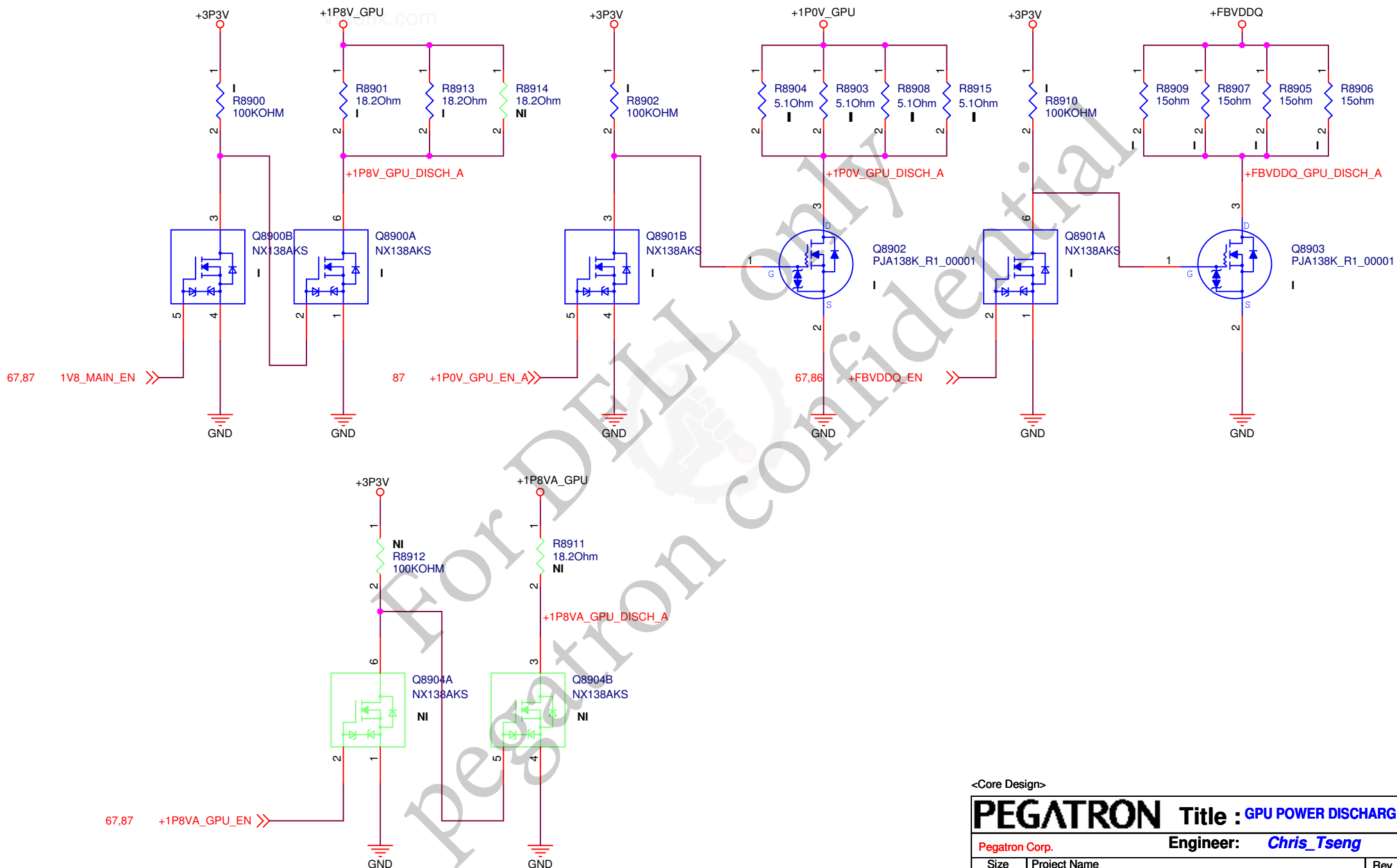
### +FBVDDQ Output CAP

330uF/2V/H=2mm \* 3 (I)  
330uF/2V/H=1.5mm \* 2(NI)

<Core Design>

PEGATRON		Title : GPU_POWER_CAP	
Pegatron Corp.		Engineer: Chris_Tseng	
Size	Project Name	Rev	
A3	Vulcan	X00	
Date: Wednesday, November 28, 2018	Sheet 88 of 94		

# GPU POWER DISCHARGE



<Core Design>

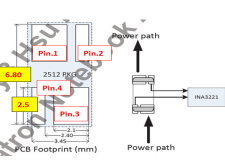
**PEGATRON** Title : GPU POWER DISCHARGE

Pegatron Corp. Engineer: Chris Tseng

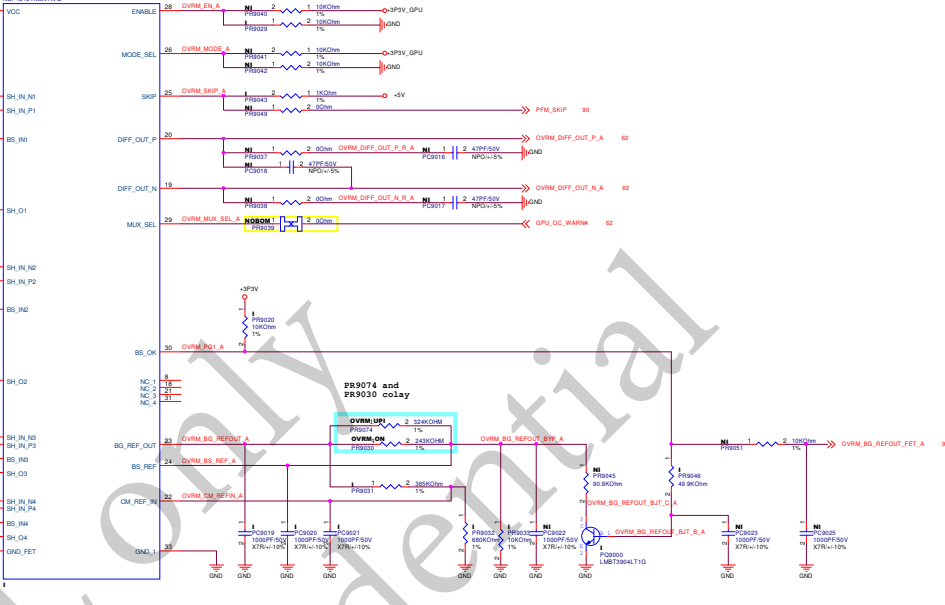
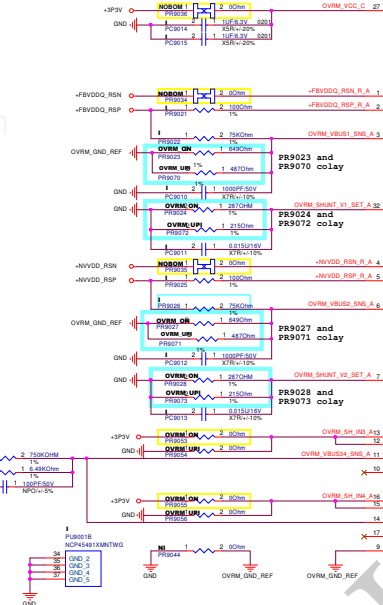
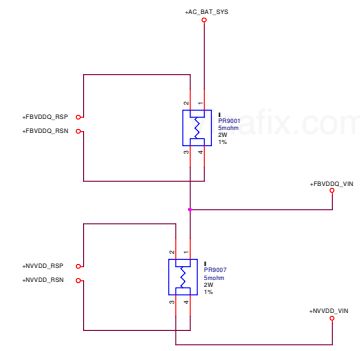
Size A4	Project Name <b>Vulcan</b>	Rev B00
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Date: Wednesday, November 28, 2018 Sheet 89 of 94





+AC\_BAT\_SYS (GPU power only)  
Input Current: 15A @19V (1ms moving average)  
Input Current: 15A @19V (5ms moving average)  
Input Current: 4.21A @19V (1s moving average)  
Input Current: 35.88A @9V (1ms moving average)  
Input Current: 21.31A @9V (5ms moving average)  
Input Current: 8.88A @9V (1s moving average)

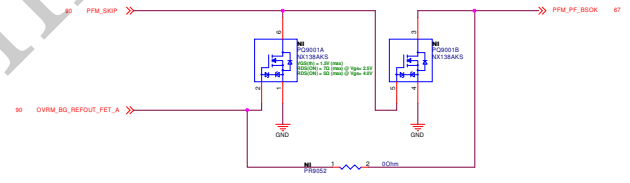


Only change part number to On-semi (06T99V004N00)

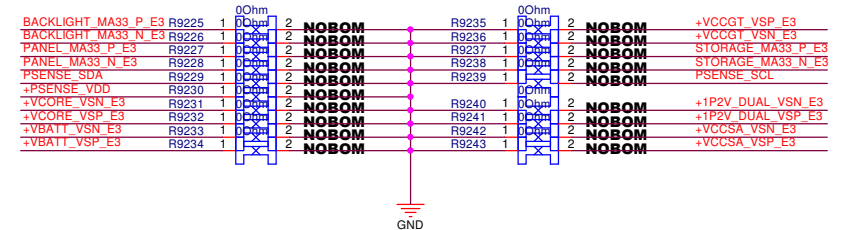
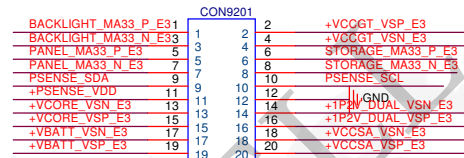
OnSemi	R954	R924	R977	R923	R950	R953	R952	C841	C836
	PR9023	PR9027	PR9024	PR9028	PR9030	PR9022	PR9026	PC9010	PC9012
N18E-G3 MAX-Q	80W	649Ω	649Ω	287Ω	287Ω	243kΩ	75kΩ	1.0mF	1.0nF
N18E-G2 MAX-Q	80W	649Ω	649Ω	287Ω	287Ω	243kΩ	75kΩ	1.0mF	1.0nF
N18E-G1 MAX-P	80W	649Ω	649Ω	287Ω	287Ω	243kΩ	75kΩ	1.0mF	1.0nF
N18E-G0 MAX-P	80W	649Ω	649Ω	287Ω	287Ω	243kΩ	75kΩ	1.0mF	1.0nF

uPI	R954	R924	R977	R923	R950	R953	R952	C841	C836
	PR9070	PR9071	PR9072	PR9073	PR9074	PR9022	PR9026	PC9010	PC9012
N18E-G3 MAX-Q	80W	487Ω	487Ω	215Ω	215Ω	324kΩ	75kΩ	1.0mF	1.0nF
N18E-G2 MAX-Q	80W	487Ω	487Ω	215Ω	215Ω	324kΩ	75kΩ	1.0mF	1.0nF
N18E-G1 MAX-P	80W	487Ω	487Ω	215Ω	215Ω	324kΩ	75kΩ	1.0mF	1.0nF
N18E-G0 MAX-P	80W	487Ω	487Ω	215Ω	215Ω	324kΩ	75kΩ	1.0mF	1.0nF



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	Chip Channel	Connector pin	Item	Location	Sense Resistor	Note
Sensor 1 [10h]	1	P1+/-	CPU_VCCGT	PR7307 (10m ohm) PR7308 (10m ohm)	5m ohm (0x05)	VCCGT
	2	P2+/-	STORAGE	R3109 (10m ohm)	10m ohm (0x0A)	SSD
				R3216 (10m ohm)		HDD(SATA)
	3	P3+/-	DISPLAY_CTLR	R4852 (10m ohm)	10m ohm (0x0A)	Panel Logic
	4	P4+/-	DISPLAY_BACKLIGHT	R4800 (10m ohm)	10m ohm (0x0A)	Panel Backlight
Sensor 2 [1Eh]	1	P5+/-	STYSTEM	R6811 (5m ohm)	5m ohm (0x05)	Battery
	2	P6+/-	CPU_VCORE	PR7100 (10m ohm) PR7101 (10m ohm)	5m ohm (0x05)	VCORE
	3	P7+/-	CPU_VDDQ	PR7700 (10m ohm)	10m ohm (0x0A)	VDDQ
	4	P8+/-	CPU_VCCSA	PR7407 (10m ohm)	10m ohm (0x0A)	VCCSA

Date: Wednesday, November 20, 2019	Sheet	32	of	34
		1		

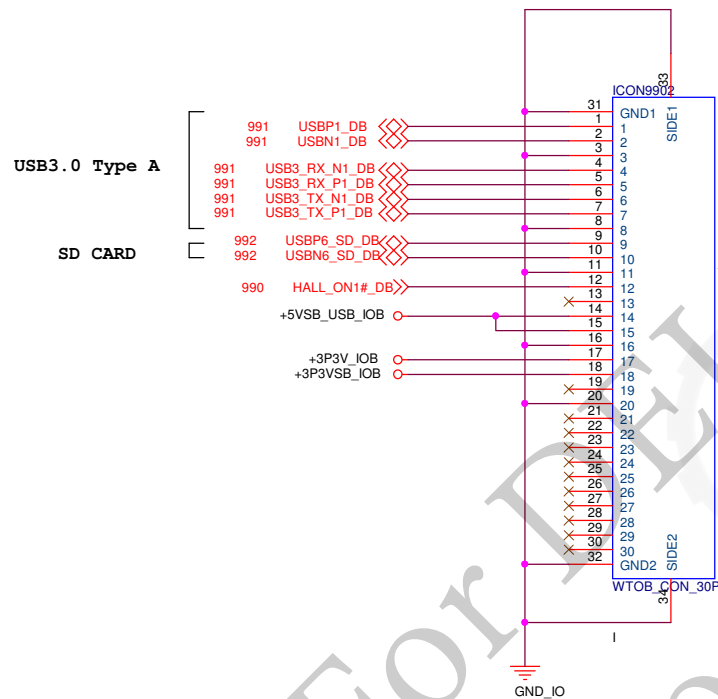
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<Core Design>

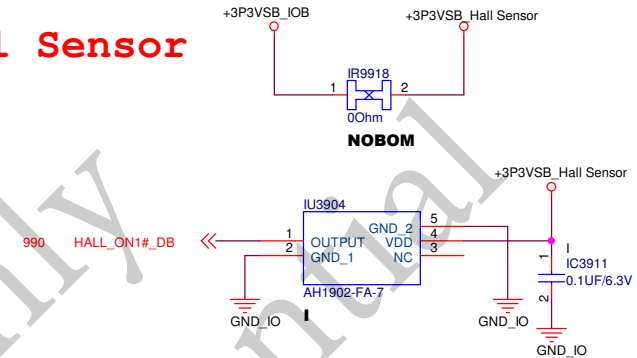
<b>PEGATRON</b>		Title : <b>RESERVE</b>	
Pegatron Corp.		Engineer: <b>Chris Tseng</b>	
Size <b>A3</b>	Project Name <b>Vulcan</b>	Rev <b>X00</b>	
Date: <b>Wednesday, November 28, 2018</b>		Sheet	<b>94</b> of <b>94</b>

# 990.IO port/Hall sensor

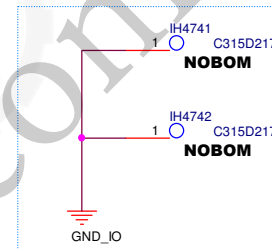
Vinafix.com



## Hall Sensor



## Screw Hole

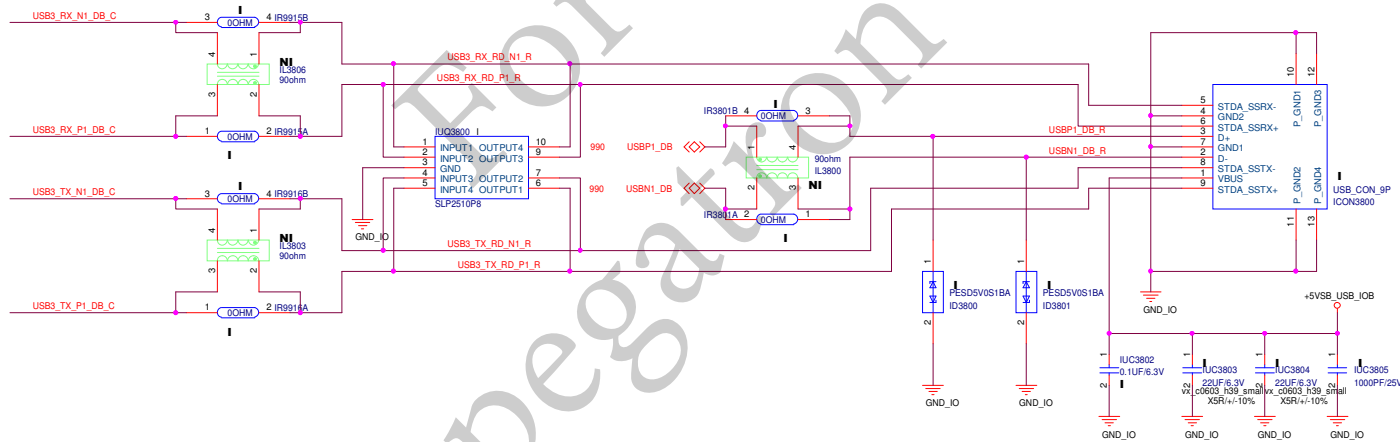
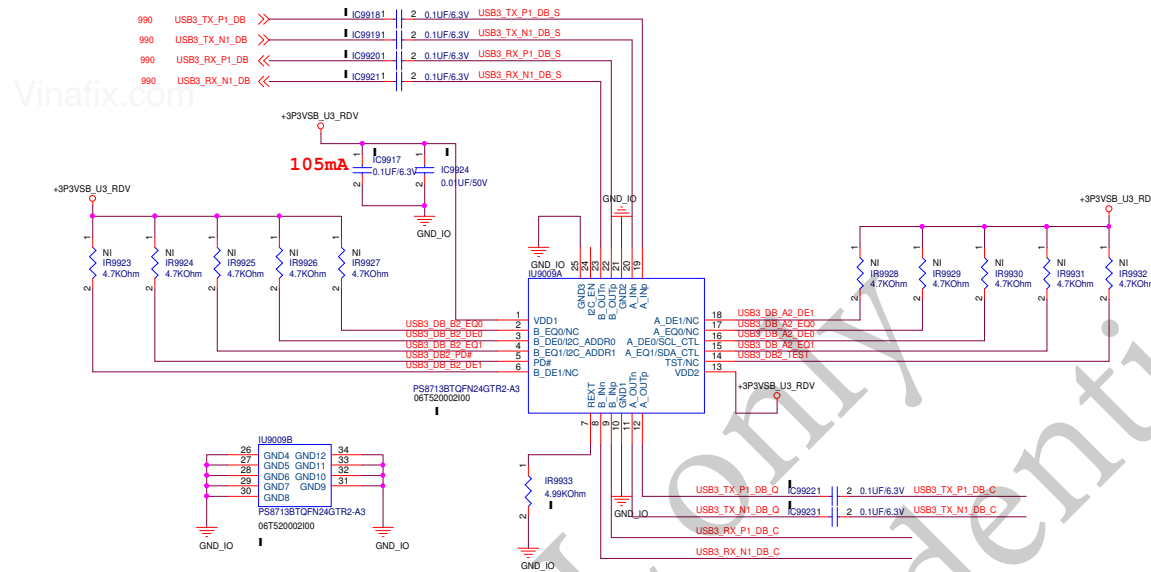
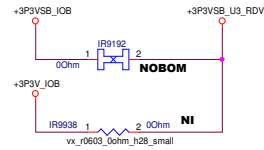


<Core Design>

PEGATRON		Title : IO port/Hall sensor	
Pegatron Corp.		Engineer: Alex_Tsai	
Size B	Project Name Vulcan		Rev X00
Date: Wednesday, November 28, 2018		Sheet	990 of 94

# 991.USB PORT

Imax: 105mA

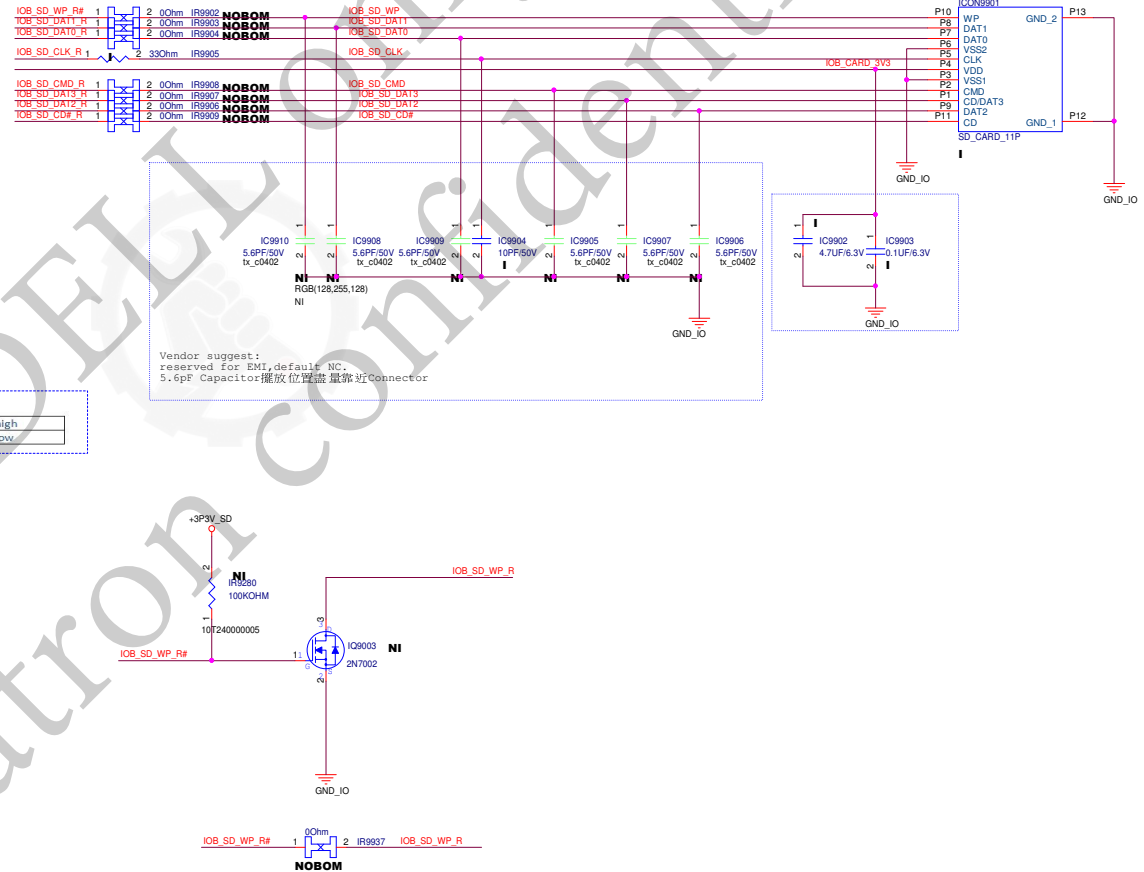
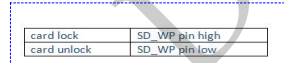
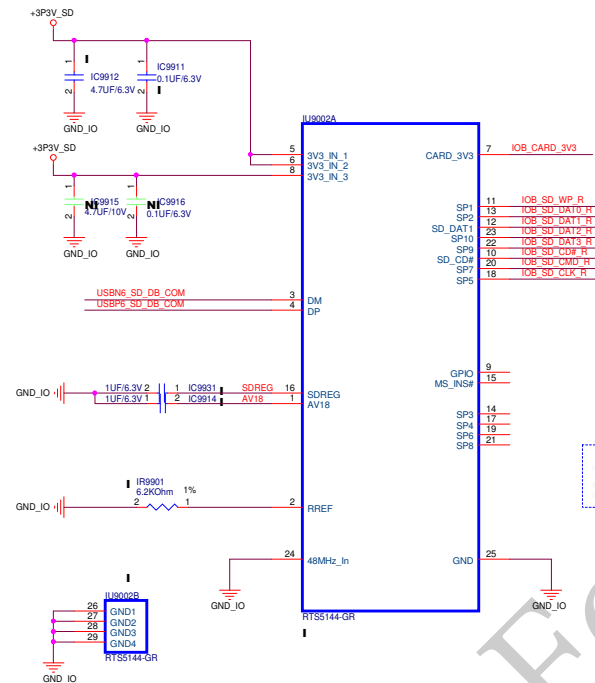
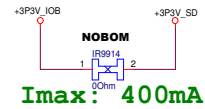


<Core Design>

PEGATRON		Title : USB DB PORT	
Pegatron Corp.		Engineer: Alex Tsai	
Size	Project Name	Vulcan	Rev
C			X00
Date: Wednesday, November 28, 2018		Sheet 991 of 94	

# 992.Card\_reader\_RTS5144-GR

## POWER



WITHOUT CARD		CARD INSERTED:LOCK		CARD INSERTED:UNLOCK	
W/P	GND	W/P	GND	W/P	GND
C/D	VSS1	C/D	VSS1	C/D	VSS1